

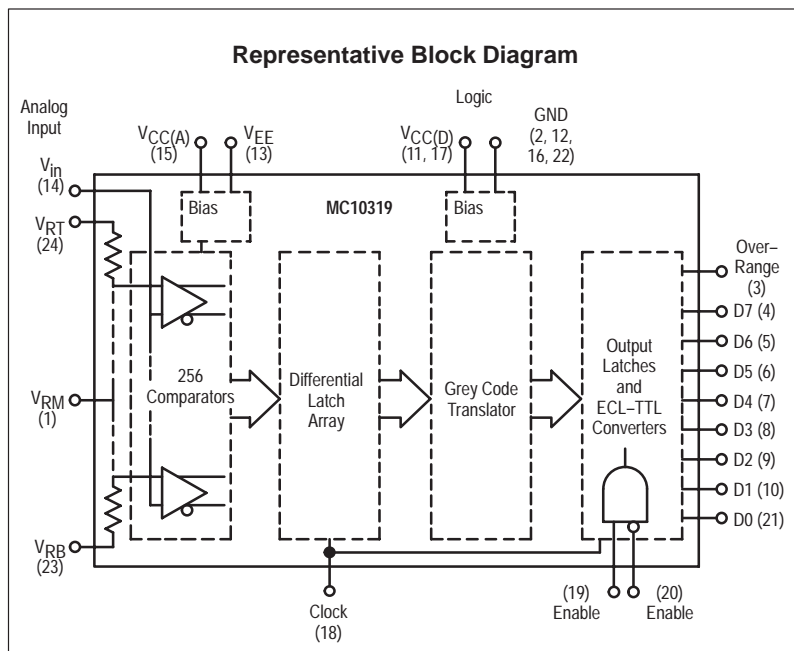
# High Speed 8-Bit Analog-to-Digital Converter

The MC10319 is an 8-bit high speed parallel flash A/D converter. The device employs an internal Grey Code structure to eliminate large output errors on fast slewing input signals. It is fully TTL compatible, requiring a + 5.0 V supply and a wide tolerance negative supply of - 3.0 to - 6.0 V. Three-state TTL outputs allow direct drive of a data bus or common I/O memory.

The MC10319 contains 256 parallel comparators across a precision input reference network. The comparator outputs are fed to latches and then to an encoder network, to produce an 8-bit data byte plus an overrange bit. The data is latched and converted to 3-state LS-TTL outputs. The overrange bit is always active to allow for either sensing of the overrange condition or ease of interconnecting a pair of devices to produce a 9-bit A/D converter.

Applications include video display and radar processing, high speed instrumentation and TV broadcast encoding.

- Internal Grey Code for Speed and Accuracy, Binary Outputs
- 8-Bit Resolution/9-Bit Typical Accuracy
- Easily Interconnected for 9-Bit Conversion
- 3-State LS-TTL Outputs with True/Complement Enable Inputs
- 25 MHz Sampling Rate
- Wide Input Range: 1.0 to 2.0  $V_{pp}$ , between  $\pm 2.0$  V
- Low Input Capacitance: 50 pF
- Low Power Dissipation: 618 mW
- No Sample/Hold Required for Video Bandwidth Signals
- Single Clock Cycle Conversion

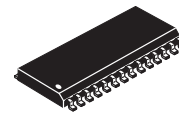
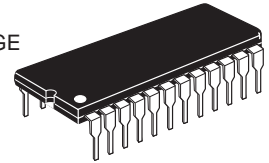


## MC10319

### HIGH SPEED 8-BIT ANALOG-TO-DIGITAL FLASH CONVERTER

#### SEMICONDUCTOR TECHNICAL DATA

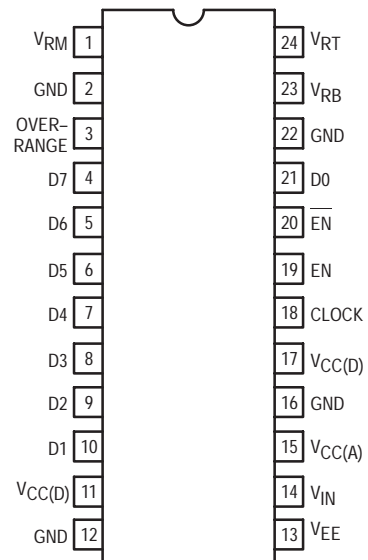
**P SUFFIX**  
PLASTIC PACKAGE  
CASE 709



**DW SUFFIX**  
PLASTIC PACKAGE  
CASE 751F  
(SO-28L)

#### PIN CONNECTIONS

(P only)



#### ORDERING INFORMATION

Device	Operating Temperature Range	Package
MC10319DW	$T_A = 0^\circ$ to $+70^\circ\text{C}$	SO-28L
MC10319P		Plastic

# MC10319

## ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Supply Voltage	$V_{CC(A),(D)}$ $V_{EE}$	+ 7.0 – 7.0	Vdc
Positive Supply Voltage Differential	$V_{CC(D)} - V_{CC(A)}$	– 0.3 to + 0.3	Vdc
Digital Input Voltage (Pins 18 to 20)	$V_{I(D)}$	– 0.5 to + 7.0	Vdc
Analog Input Voltage (Pins 1, 14, 23, 24)	$V_{I(A)}$	– 2.5 to + 2.5	Vdc
Reference Voltage Span (Pin 24 to Pin 23)	–	2.3	Vdc
Applied Output Voltage (Pins 4 to 10, 21 in 3–State)	–	– 0.3 to + 7.0	Vdc
Junction Temperature	$T_J$	+ 150	°C
Storage Temperature	$T_{stg}$	– 65 to + 150	°C

Devices should not be operated at these values. The “Recommended Operating Limits” table provides guidelines for actual device operation.

## RECOMMENDED OPERATING LIMITS

Characteristic	Symbol	Min	Typ	Max	Unit
Power Supply Voltage (Pin 15) (Pins 11, 17)	$V_{CC(A)}$ $V_{CC(D)}$	+ 4.5	+ 5.0	+ 5.5	Vdc
$V_{CC(D)} - V_{CC(A)}$	$\Delta V_{CC}$	– 0.1	0	+ 0.1	Vdc
Power Supply Voltage (Pin 13)	$V_{EE}$	– 6.0	– 5.0	– 3.0	Vdc
Digital Input Voltages (Pins 18 to 20)	$V_{I(D)}$	0	–	+ 5.0	Vdc
Analog Input (Pin 14)	$V_{I(A)}$	– 2.1	–	+ 2.1	Vdc
Voltage @ $V_{RT}$ (Pin 24)	$V_{RT}$	– 1.0	–	+ 2.1	Vdc
Voltage @ $V_{RB}$ (Pin 23)	$V_{RB}$	– 2.1	–	+ 1.0	Vdc
$V_{RT} - V_{RB}$	$\Delta V_R$	+ 1.0	–	+ 2.1	Vdc
$V_{RB} - V_{EE}$	–	1.3	–	–	Vdc
Applied Output Voltage (Pins 4 to 10, 21 in 3–State)	$V_o$	0	–	5.5	Vdc
Clock Pulse Width – High Low	$t_{CKH}$ $t_{CKL}$	5.0 15	20 20	– –	ns
Clock Frequency	$f_{CLK}$	0	–	25	MHz
Operating Ambient Temperature	$T_A$	0	–	+ 70	°C

## ELECTRICAL CHARACTERISTICS ( $0^\circ < T_A < 70^\circ\text{C}$ , $V_{CC} = 5.0\text{ V}$ , $V_{EE} = -5.2\text{ V}$ , $V_{RT} = +1.0\text{ V}$ , $V_{RB} = -1.0\text{ V}$ , unless noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
<b>TRANSFER CHARACTERISTICS (<math>f_{CKL} = 25\text{ MHz}</math>)</b>					
Resolution	N	–	–	8.0	Bits
Monotonicity	MON	Guaranteed			Bits
Integral Nonlinearity	INL	–	$\pm 1/4$	$\pm 1.0$	LSB
Differential Nonlinearity	DNL	–	–	$\pm 1.0$	LSB
Differential Phase (See Figure 16)	DP	–	1	–	Deg.
Differential Gain (See Figure 16)	DG	–	1	–	%
Power Supply Rejection Ratio ( $4.5\text{ V} < V_{CC} < 5.5\text{ V}$ , $V_{EE} = -5.2\text{ V}$ ) ( $-6.0\text{ V} < V_{EE} < -3.0\text{ V}$ , $V_{CC} = +5.0\text{ V}$ )	PSRR	– –	0.1 0	– –	LSB/V

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## ELECTRICAL CHARACTERISTICS – continued

( $0^\circ < T_A < 70^\circ\text{C}$ ,  $V_{CC} = 5.0\text{ V}$ ,  $V_{EE} = -5.2\text{ V}$ ,  $V_{RT} = +1.0\text{ V}$ ,  $V_{RB} = -1.0\text{ V}$ , unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
<b>ANALOG INPUTS (Pin 14)</b>					
Input Current @ $V_{in} = V_{RB}$ (See Figure 5)	$I_{INL}$	-100	0	-	$\mu\text{A}$
Input Current @ $V_{in} = V_{RT}$ (See Figure 5)	$I_{INH}$	-	60	150	$\mu\text{A}$
Input Capacitance ( $V_{RT} - V_{RB} = 2.0\text{ V}$ , See Figure 4)	$C_{in}$	-	36	-	pF
Input Capacitance ( $V_{RT} - V_{RB} = 1.0\text{ V}$ , See Figure 4)	$C_{in}$	-	55	-	pF
Bipolar Offset Error	$V_{OS}$	-	0.1	-	LSB

## REFERENCE

Ladder Resistance ( $V_{RT}$ to $V_{RB}$ , $T_A = 25^\circ\text{C}$ )	$R_{ref}$	104	130	156	$\Omega$
Temperature Coefficient	$T_C$	-	+0.29	-	$\%/^\circ\text{C}$
Ladder Capacitance (Pin 1 open)	$C_{ref}$	-	25	-	pF

## ENABLE INPUTS ( $V_{CC} = 5.5\text{ V}$ ) (See Figure 6)

Input Voltage – High (Pins 19 to 20)	$V_{IHE}$	2.0	-	-	V
Input Voltage – Low (Pins 19 to 20)	$V_{ILE}$	-	-	0.8	V
Input Current @ 2.7 V	$I_{IHE}$	-	0	20	$\mu\text{A}$
Input Current @ 0.4 V @ EN ( $0 < EN < 5.0\text{ V}$ )	$I_{IL1}$	-400	-100	-	$\mu\text{A}$
Input Current @ 0.4 V @ EN ( $EN = 0\text{ V}$ )	$I_{IL2}$	-400	-100	-	$\mu\text{A}$
Input Current @ 0.4 V @ EN ( $EN = 2.0\text{ V}$ )	$I_{IL3}$	-20	-2.0	-	$\mu\text{A}$
Input Clamp Voltage ( $I_{IK} = -18\text{ mA}$ )	$V_{IKE}$	-1.5	-1.3	-	V

## CLOCK INPUTS ( $V_{CC} = 5.5\text{ V}$ )

Input Voltage High	$V_{IHC}$	2.0	-	-	Vdc
Input Voltage Low	$V_{ILC}$	-	-	0.8	Vdc
Input Current @ 0.4 V (See Figure 7)	$I_{ILC}$	-400	-80	-	$\mu\text{A}$
Input Current @ 2.7 V (See Figure 7)	$I_{IHC}$	-100	-20	-	$\mu\text{A}$
Input Clamp Voltage ( $I_{IK} = -18\text{ mA}$ )	$V_{IKC}$	-1.5	-1.3	-	Vdc

## DIGITAL OUTPUTS

High Output Voltage ( $I_{OH} = -400\text{ }\mu\text{A}$ , $V_{CC} = 4.5\text{ V}$ , See Figure 8)	$V_{OH}$	2.4	3.0	-	V
Low Output Voltage ( $I_{OL} = 4.0\text{ mA}$ , See Figure 9)	$V_{OL}$	-	0.35	0.4	V
Output Short Circuit Current* ( $V_{CC} = 5.5\text{ V}$ )	$I_{SC}$	-	35	-	mA
Output Leakage Current ( $0.4 < V_O < 2.4\text{ V}$ , See Figure 3, $V_{CC} = 5.5\text{ V}$ , D0 to D7 in 3-State Mode)	$I_{LK}$	-50	-	+50	$\mu\text{A}$
Output Capacitance (D0 to D7 in 3-State Mode)	$C_{out}$	-	9.0	-	pF

\*Only one output is to be shorted at a time, not to exceed 1 second.

## POWER SUPPLIES

$V_{CC(A)}$ Current ( $4.5\text{ V} < V_{CC(A)} < 5.5\text{ V}$ ) (Outputs unloaded)	$I_{CC(A)}$	10	17	25	mA
$V_{CC(D)}$ Current ( $4.5\text{ V} < V_{CC(D)} < 5.5\text{ V}$ ) (Outputs unloaded)	$I_{CC(D)}$	50	90	133	mA
$V_{EE}$ Current ( $-6.0 < V_{EE} < -3.0\text{ V}$ )	$I_{EE}$	-14	-10	-6.0	mA
Power Dissipation ( $V_{RT} - V_{RB} = 2.0\text{ V}$ ) (Outputs unloaded)	$P_D$	-	618	995	mW

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**TIMING CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$ ,  $V_{CC} = +5.0\text{ V}$ ,  $V_{EE} = -5.2\text{ V}$ ,  $V_{RT} = +1.0\text{ V}$ ,  $V_{RB} = -1.0\text{ V}$ , see System Timing Diagram, Figure 1.)

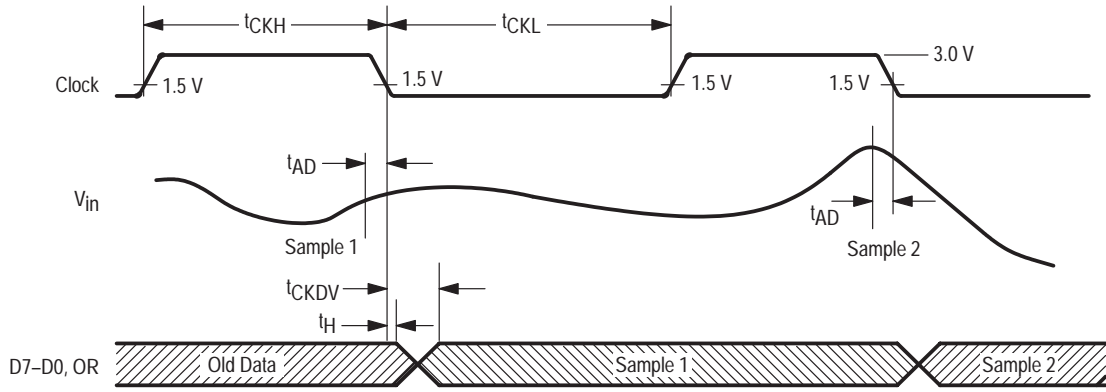
Characteristic	Symbol	Min	Typ	Max	Unit
<b>INPUTS</b>					
Min Clock Pulse Width – High	$t_{CKH}$	–	5.0	–	ns
Min Clock Pulse Width – Low	$t_{CKL}$	–	15	–	ns
Max Clock Rise, Fall Time	$t_{R,F}$	–	100	–	ns
Clock Frequency	$f_{CLK}$	0	30	25	MHz
<b>OUTPUTS</b>					
New Data Valid from Clock Low	$t_{CKDV}$	–	19	–	ns
Aperture Delay	$t_{AD}$	–	4.0	–	ns
Hold Time	$t_H$	–	6.0	–	ns
Data High to 3–State from Enable Low*	$t_{EHZ}$	–	27	–	ns
Data Low to 3–State from Enable Low*	$t_{ELZ}$	–	18	–	ns
Data High to 3–State from Enable High*	$t_{EHZ}$	–	32	–	ns
Data Low to 3–State from Enable High*	$t_{ELZ}$	–	18	–	ns
Valid Data from Enable High (Pin 20 = 0 V)*	$t_{EDV}$	–	15	–	ns
Valid Data from Enable Low (Pin 19 = 5.0 V)*	$t_{EDV}$	–	16	–	ns
Output Transition Time* (10% to 90%)	$t_{tr}$	–	8.0	–	ns

\*See Figure 2 for output loading.

## PIN FUNCTION DESCRIPTION

Function	Pin		Description
	P Suffix	DW Suffix	
$V_{RM}$	1	1	The midpoint of the reference resistor ladder. Bypassing can be done at this point to improve performance at high frequencies.
GND	2, 12 16, 22	2, 13, 17 18, 25, 26	Digital ground. The pins should be connected directly together, and through a low impedance path to the power supply.
OVR	3	3	Overrange output. Indicates $V_{in}$ is more positive than $V_{RT}$ 1/2 LSB. This output does not have 3–state capability.
D7–D0	4 to 10, 21	4 to 10, 24	Digital Outputs. D7 (Pin 4) is the MSB. D0 (Pin 21 or 24) is the LSB. LS–TTL compatible with 3–state capability.
$V_{CC(D)}$	11, 17	11, 12 19, 20	Power supply for the digital section. +5.0 V, $\pm 10\%$ required. Reference to digital ground.
$V_{EE}$	13	14	Negative power supply. Nominally $-5.2\text{ V}$ , it can range from $-3.0$ to $-6.0\text{ V}$ , and must be more negative than $V_{RB}$ by $> 1.3\text{ V}$ . Reference to analog ground.
$V_{in}$	14	15	Signal voltage input. This voltage is compared to the reference to generate a digital equivalent. Input impedance is nominally 16 to 33K in parallel with 36 pF.
$V_{CC(A)}$	15	16	Power supply for the analog section. +5.0 V, $\pm 10\%$ required. Reference to analog ground.
CLK	18	21	Clock input. TTL compatible.
EN	19	22	Enable input. TTL compatible, a logic 1 (and EN at a logic 0) enables the data outputs. A logic 0 puts the outputs in a 3–state mode.
EN	20	23	Enable input. TTL compatible, a logic 0 (and EN at a logic 1) enables the data outputs. A logic 1 puts the outputs in a 3–state mode.
$V_{RB}$	23	27	The bottom (most negative point) of the internal reference resistor ladder.
$V_{RT}$	24	28	The top (most positive point) of the internal reference resistor ladder.

Figure 1. System Timing Diagram



$t_{CKDV}$  and  $t_H$  measured at output levels of 0.8 and 2.4 V.

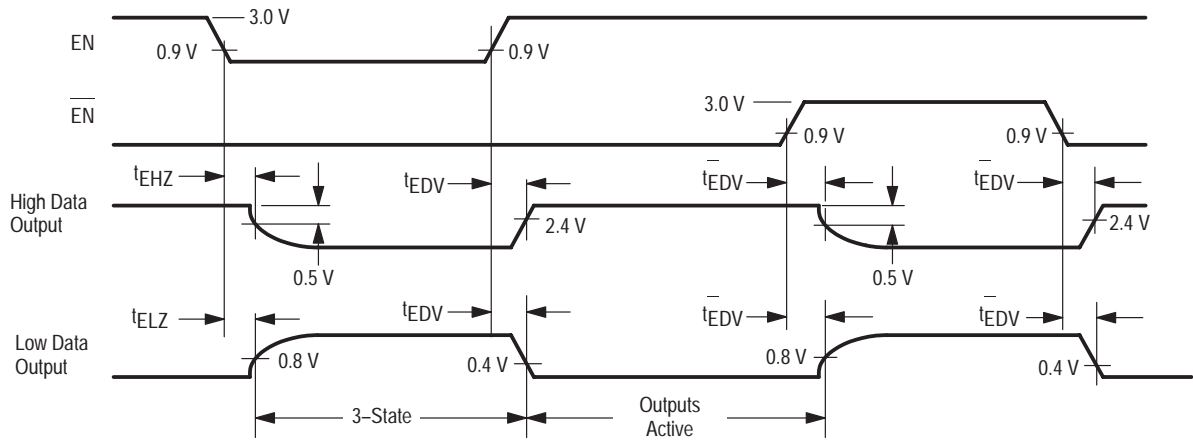


Figure 2. Data Output Test Circuit

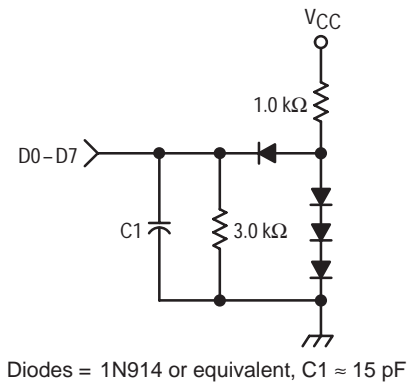


Figure 3. Output 3-State Leakage Current

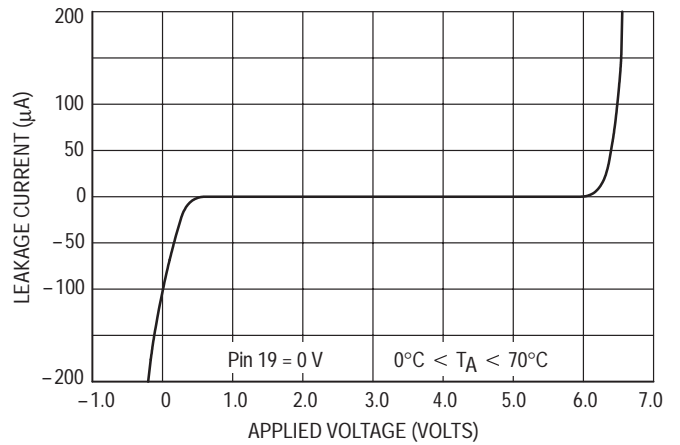


Figure 4. Input Capacitance @  $V_{in}$  (Pin 14)

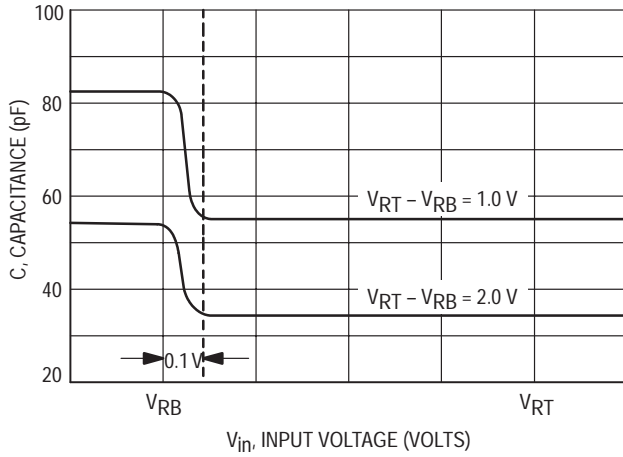


Figure 5. Input Current @  $V_{in}$  (Pin 14)

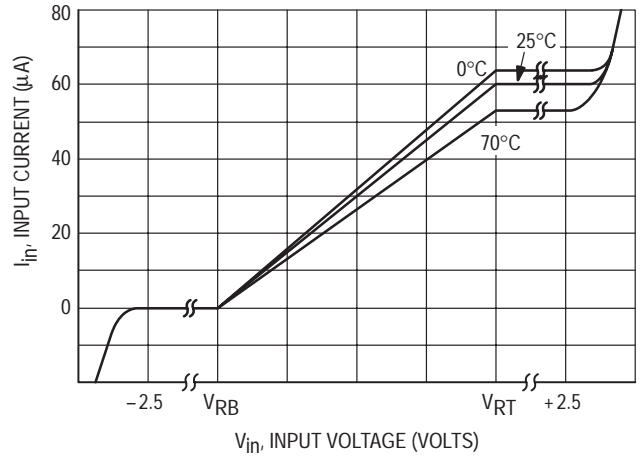


Figure 6. Input Current @ Enable, Enable

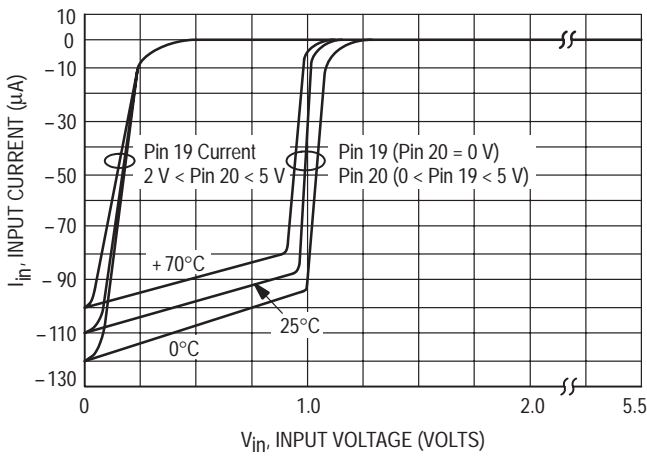


Figure 7. Clock Input Current

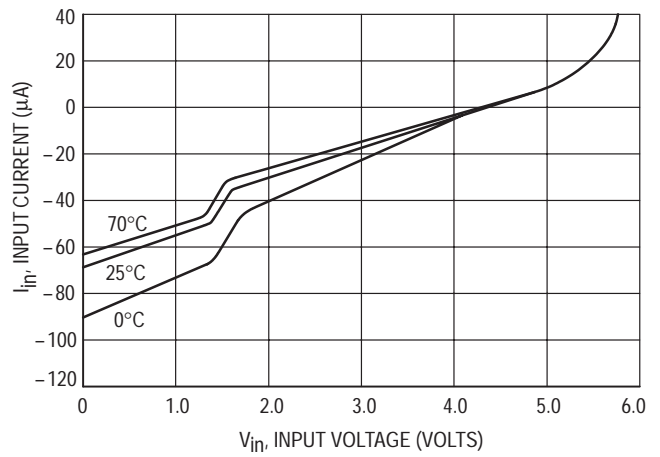


Figure 8. Output Voltage versus Output Current

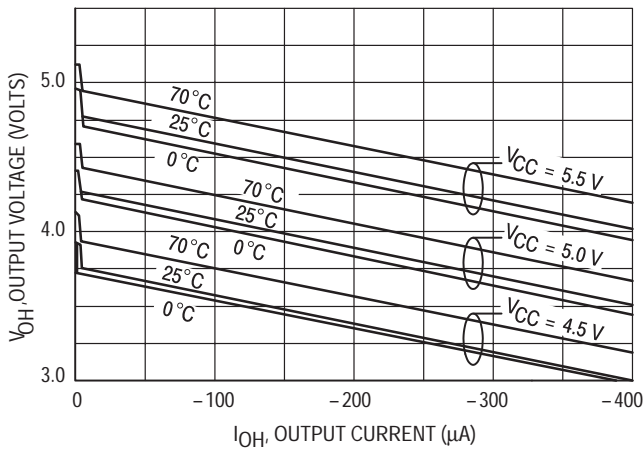


Figure 9. Output Voltage versus Output Current

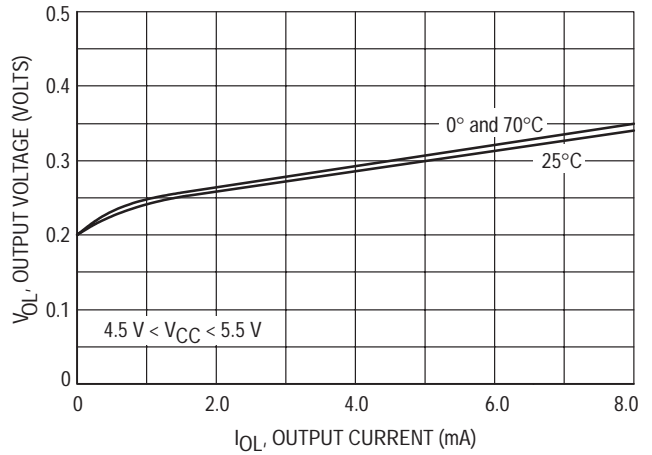


Figure 10. Supply Current versus Temperature

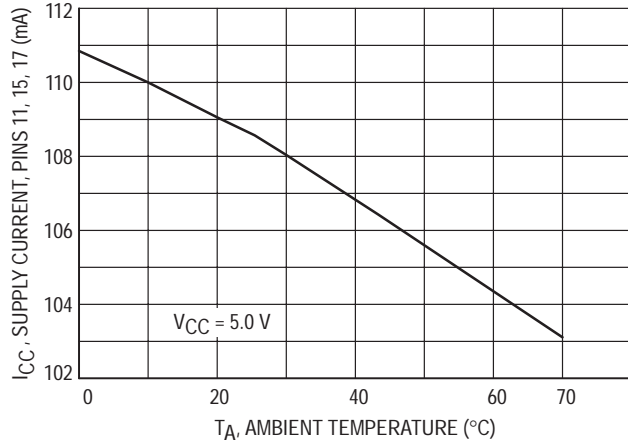


Figure 11. Supply Current versus Temperature

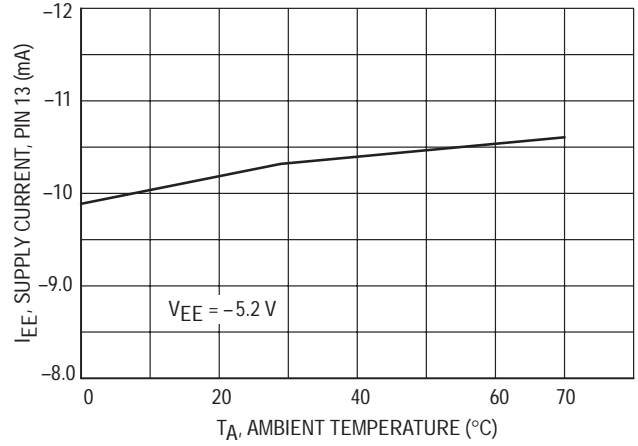


Figure 12. Differential Linearity Error

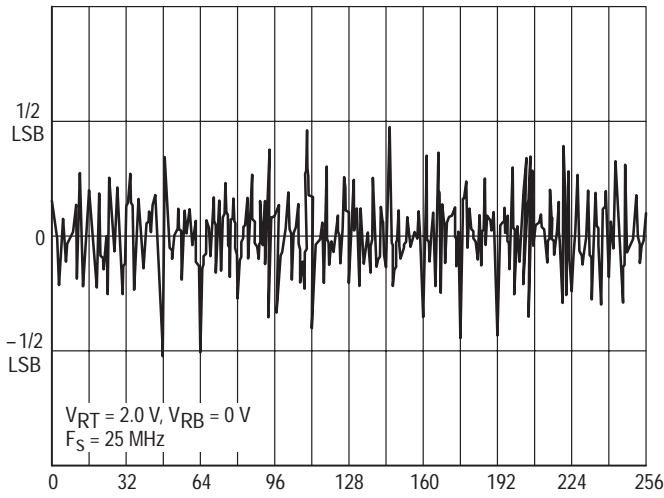


Figure 13. Integral Linearity Error

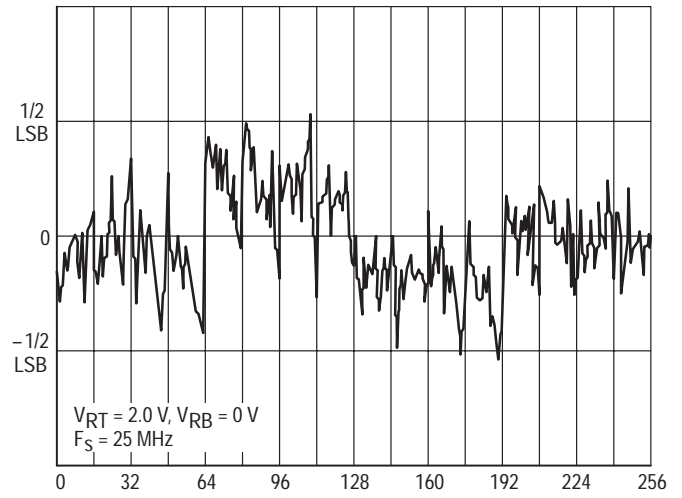


Figure 14. Differential Linearity Error

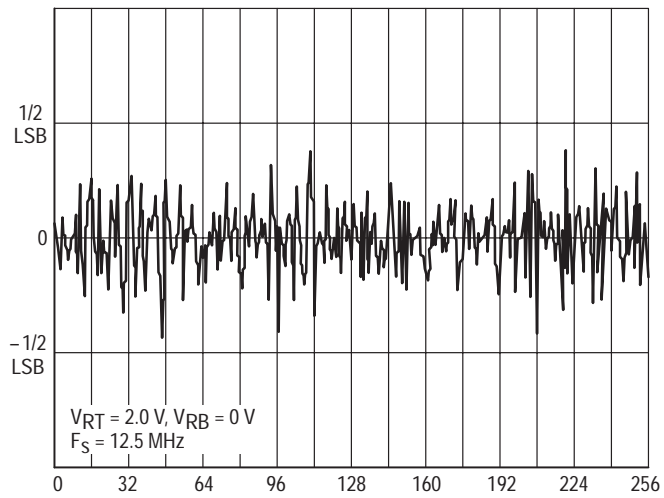
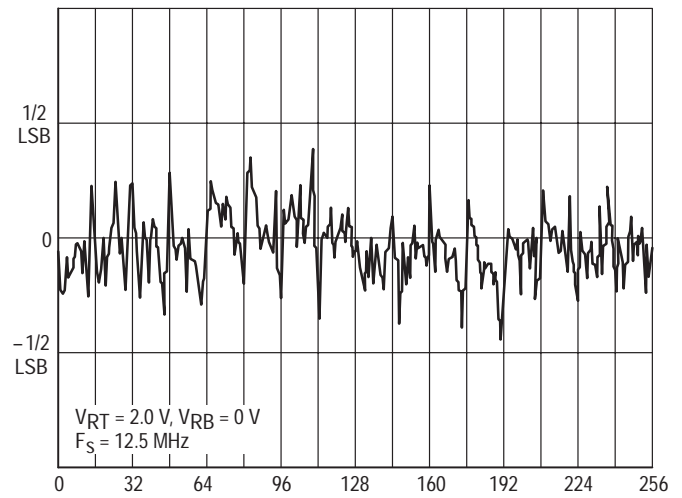


Figure 15. Integral Linearity Error



## DESIGN GUIDELINES

## Introduction

The MC10319 is a high speed, 8-bit, parallel (“flash”) type analog-to-digital converter containing 256 comparators at the front end. See Figure 17 for a block diagram. The comparators are arranged such that one input of each is referenced to evenly spaced voltages, derived from the reference resistor ladder. The other input of the comparators is connected to the input signal ( $V_{in}$ ). Some of the comparator’s differential outputs will be “true,” while other comparators will have “not true” outputs, depending on their relative position. Their outputs are then latched, and converted to an 8-bit Grey code by the Differential Latch Array. The Grey code ensures that any input errors due to cross talk, feed-thru, or timing disparities result in glitches at the output of only a few LSBs, rather than the more traditional 1/2 scale and 1/4 scale glitches.

The Grey code is then translated to an 8-bit binary code, and the differential levels are translated to TTL levels before being applied to the output latches. Enable inputs at this final stage permit the TTL outputs (except overrange) to be put into a high impedance (3-state) condition.

## ANALOG SECTION

## Signal Input

The signal voltage to be digitized ( $V_{in}$ ) is applied simultaneously to one input of each of the 256 comparators through Pin 14. The other inputs of the comparators are connected to 256 evenly spaced voltages derived from the reference ladder. The output code depends on the relative position of the input signal and the reference voltages. The comparators have a bandwidth of  $> 50$  MHz, which is more than sufficient for the allowable (Nyquist Theorem) input frequency of 12.5 MHz.

The current into Pin 14 varies linearly from 0 (when  $V_{in} = V_{RB}$ ) to  $\approx 60 \mu\text{A}$  (when  $V_{in} = V_{RT}$ ). If  $V_{in}$  is taken below  $V_{RB}$  or above  $V_{RT}$ , the input current will remain at the value corresponding to  $V_{RB}$  and  $V_{RT}$  respectively (see Figure 5). However,  $V_{in}$  must be maintained within the absolute range of  $\pm 2.5$  V (with respect to ground) – otherwise excessive currents will result at Pin 14, due to internal clamps.

The input capacitance at Pin 14 is typically 36 pF if  $[V_{RT} - V_{RB}]$  is 2.0 V, and increases to 55 pF if  $[V_{RT} - V_{RB}]$  is reduced to 1.0 V (see Figure 4). The capacitance is constant as  $V_{in}$  varies from  $V_{RT}$  down to  $\approx 0.1$  V above  $V_{RB}$ . Taking  $V_{in}$  to  $V_{RB}$  will show an increase in the capacitance of  $\approx 50\%$ . If  $V_{in}$  is taken above  $V_{RT}$ , or below  $V_{RB}$ , the capacitance will stay at the values corresponding to  $V_{RT}$  and  $V_{RB}$ , respectively.

The source impedance of the signal voltage should be maintained below  $100 \Omega$  (at the frequencies of interest) in order to avoid sampling errors.

## Reference

The reference resistor ladder is composed of a string of equal value resistors to provide 256 equally spaced voltages for the comparators (see Figure 17 for the actual configuration). The voltage difference between adjacent comparators corresponds to 1 LSB of the input range. The first comparator (closest to  $V_{RB}$ ) is referenced 1/2 LSB above  $V_{RB}$ , and 256th comparator (for the overrange) is referenced 1/2 LSB below  $V_{RT}$ . The total resistance of the ladder is nominally  $130 \Omega$ ,  $\pm 20\%$ , requiring  $15.4 \text{ mA @ } 2.0 \text{ V}$ , and  $7.7 \text{ mA @ } 1.0 \text{ V}$ . There is a nominal warm-up change of  $\approx +9.0\%$  in the ladder resistance due to the  $+0.29\%/^{\circ}\text{C}$  temperature coefficient.

The minimum recommended span  $[V_{RT} - V_{RB}]$  is 1.0 V. A lower span will allow offsets and nonlinearities to become significant. The maximum recommended span is 2.1 V due to power limitations of the resistor ladder. The span may be anywhere within the range of  $-2.1$  to  $+2.1$  V with respect to ground, and  $V_{RB}$  must be at least 1.3 V more positive than  $V_{EE}$ . The reference voltages must be stable and free of noise and spikes, since the accuracy of a conversion is directly related to the quality of the reference.

In most applications, the reference voltages will remain fixed. In applications involving a varying reference for modulation or signal scrambling, the modulating signal may be applied to  $V_{RT}$ , or  $V_{RB}$ , or both. The output will vary inversely with the reference signal, introducing a nonlinearity into the transfer function. The addition of the modulating signal and the dc level applied to the reference must be such that the absolute voltage at  $V_{RT}$  and  $V_{RB}$  is maintained within the values listed in the Recommended Operating Limits. The RMS value of the span must be maintained  $\leq 2.1$  V.

$V_{RM}$  (Pin 1) is the midpoint of the resistor ladder, excluding the Overrange comparator. The voltage at  $V_{RM}$  is:

$$\frac{V_{RT} + V_{RB}}{2.0} - 1/2 \text{ LSB}$$

In most applications, bypassing this pin to ground ( $0.1 \mu\text{F}$ ) is sufficient to maintain accuracy. In applications involving very high frequencies, and where linearity is critical, it may be necessary to trim the voltage at the midpoint. A means for accomplishing this is indicated in Figure 18.

## Power Supplies

$V_{CC(A)}$  is the positive power supply for the comparators, and  $V_{CC(D)}$  is the positive power supply for the digital portion. Both are to be  $+5.0 \text{ V}$ ,  $\pm 10\%$ , and the two are to be within 100 mV of each other. There is indirect internal coupling between  $V_{CC(D)}$  and  $V_{CC(A)}$ . If they are powered separately, and one supply fails, there will be current flow through the MC10319 to the failed supply.

$I_{CC(A)}$  is nominally 17 mA, and does not vary with clock frequency or with  $V_{in}$ . It does vary linearly with  $V_{CC(A)}$ .  $I_{CC(D)}$  is nominally 90 mA, and is independent of clock frequency. It does vary, however, by 6 to 7 mA as  $V_{in}$  is changed, with the lowest current occurring when  $V_{in} = V_{RT}$ . It varies linearly with  $V_{CC(D)}$ .

$V_{EE}$  is the negative power supply for the comparators, and is to be within the range  $-3.0$  to  $-6.0$  V. Additionally,  $V_{EE}$  must be at least 1.3 V more negative than  $V_{RB}$ .  $I_{EE}$  is a nominal  $-10$  mA, and is independent of clock frequency,  $V_{in}$ , and  $V_{EE}$ .

For proper operation, the supplies **must** be bypassed at the IC. A 10  $\mu$ F tantalum, in parallel with a 0.1  $\mu$ F ceramic is recommended for each supply to ground.

## DIGITAL SECTION

### Clock

The Clock input is TTL compatible with a typical frequency range of 0 to 30 MHz. There is no duty cycle limitations, but the minimum low and high times must be adhered to. See Figure 7 for the input current requirements.

The conversion sequence is shown in Figure 19, and is as follows:

- On the rising edge, the data output latches are latched with old data, and the comparator output latches are released to follow the input signal ( $V_{in}$ ).
- During the high time, the comparators track the input signal. The data output latches retain the old data.
- On the falling edge, the comparator outputs are latched with the data immediately prior to this edge. The conversion to digital occurs within the device, and the data output latches are released to indicate the new data within 20 ns.
- During the clock low time, the comparator outputs remain latched, and the data output latches remain transparent.

A summary of the sequence is that data present at  $V_{in}$  just prior to the Clock falling edge is digitized and available at the data outputs immediately after that same falling edge.

The comparator output latches provide the circuit with an effective sample-and-hold function, eliminating the need for an external sample-and-hold.

### Enable Inputs

The two Enable inputs are TTL compatible, and are used to change the data outputs (D7–D0) from active to 3–state. This capability allows cascading two MC10319s into a 9–bit configuration, flip–flopping two MC10319s into a 50 MHz configuration, connecting the outputs directly to a data bus, multiplexing multiple converters, etc. See the Applications Information section for more details. For the outputs to be active, Pin 19 must be a Logic “1”, and Pin 20 must be a Logic “0”. Changing either input will put the outputs into the high impedance mode. The Enable inputs affect **only** the state of the outputs – they do not inhibit a conversion. The input current into Pins 19 and 20 is shown in Figure 6, and the input/output timing is shown in Figure 1 and 20. Leaving either pin open is equivalent to a Logic “1”, although good design practice dictates that an input should never be left open.

The Overrange output (Pin 3) is not affected by the Enable inputs as it does not have 3–state capability.

### Outputs

The Data outputs are TTL level outputs with high impedance capability. Pin 4 is the MSB (D7), and Pin 21 is the LSB (D0). The eight outputs are active as long as the Enable inputs are true (Pin 19 = high, Pin 20 = low). The timing of the outputs relative to the Clock input and the Enable inputs is shown in Figures 1 and 20. Figures 8 and 9 indicate the output voltage versus load current, while Figure 3 indicates the leakage current when in the high impedance mode.

The output code is natural binary, depicted in the table below.

The Overrange output (Pin 3) goes high when the input,  $V_{in}$ , is more positive than  $V_{RT} - 1/2$  LSB. This output is always active – it does not have high impedance capability. Besides being used to indicate an input overrange, it is additionally used for cascading two MC10319s to form a 9–bit A/D converter (see Figure 27).

Table 1. Output Code

Input	$V_{RT}, V_{RB}$ (V)			Output Code	Overrange
	2.048 V, 0 V	+ 1.0 V, – 1.0 V	+ 1.0 V, 0 V		
$>V_{RT} - 1/2$ LSB	$>2.044$ V	$>0.9961$ V	$>0.9980$ V	FF <sub>H</sub>	1
$V_{RT} - 1/2$ LSB	2.044 V	0.9961 V	0.9980 V	FF <sub>H</sub>	0 ↔ 1
$V_{RT} - 1$ LSB	2.040 V	0.992 V	0.9961 V	FF <sub>H</sub>	0
$V_{RT} - 1-1/2$ LSB	2.036 V	0.988 V	0.9941 V	FE <sub>H</sub> ↔ FF <sub>H</sub>	0
Midpoint	1.024 V	0.000 V	0.5000 V	80 <sub>H</sub>	0
$V_{RB} + 1/2$ LSB	4.0 mV	– 0.9961 V	1.95 mV	00 <sub>H</sub> ↔ 01 <sub>H</sub>	0
$<V_{RB}$	$<0$ V	$<-1.0$ V	$<0$ V	00 <sub>H</sub>	0

## APPLICATIONS INFORMATION

**Power Supplies, Grounding**

The PC board layout, and the quality of the power supplies and the ground system **at the IC** are very important in order to obtain proper operation. Noise, from any source, coming into the device on  $V_{CC}$ ,  $V_{EE}$ , or ground can cause an incorrect output code due to interaction with the analog portion of the circuit. At the same time, noise generated within the MC10319 can cause incorrect operation if that noise does not have a clear path to ac ground.

Both the  $V_{CC}$  and  $V_{EE}$  power supplies must be decoupled to ground **at the IC** (within 1" max) with a 10  $\mu\text{F}$  tantalum and a 0.1  $\mu\text{F}$  ceramic. Tantalum capacitors are recommended since electrolytic capacitors simply have too much inductance at the frequencies of interest. The quality of the  $V_{CC}$  and  $V_{EE}$  supplies should then be checked at the IC with a high frequency scope. Noise spikes (always present when digital circuits are present) can easily exceed 400 mV peak, and if they get into the analog portion of the IC, the operation can be disrupted. Noise can be reduced by inserting resistors and/or inductors between the supplies and the IC.

If switching power supplies are used, there will usually be spikes of 0.5 V or greater at frequencies of 50 to 200 kHz. These spikes are generally more difficult to reduce because of their greater energy content. In extreme cases, 3-terminal regulators (MC78L05ACP, MC7905.2CT), with appropriate high frequency filtering, should be used and dedicated to the MC10319.

The ripple content of the supplies should not allow their magnitude to exceed the values in the Recommended Operating Limits table.

The PC board tracks supplying  $V_{CC}$  and  $V_{EE}$  to the MC10319 should preferably not be at the tail end of the bus distribution, after passing through a maze of digital circuitry. The MC10319 should be close to the power supply, or the connector where the supply voltages enter the board. If the  $V_{CC}$  and  $V_{EE}$  lines are supplying considerable current to other parts of the boards, then it is preferable to have dedicated lines from the supply or connector directly to the MC10319.

The four ground pins (2, 12, 16, and 22) must be connected directly together. Any long path between them can cause stability problems due to the inductance (at 25 MHz) of the PC tracks. The ground return for the signal source must be noise free.

**Reference Voltage Circuits**

Since the accuracy of the conversion is directly related to the quality of the references, it is imperative that accurate and stable voltages be provided to  $V_{RT}$  and  $V_{RB}$ . If the reference span is 2.0 V, then 1/2 LSB is only 3.9 mV, and it is desirable that  $V_{RT}$  and  $V_{RB}$  be accurate to within this amount, and furthermore, that they do not drift more than this amount once

set. Over the temperature range of 0° to 70°C, a maximum temperature coefficient of 28 ppm/°C is required.

The voltage supplies used for digital circuits should preferably **not** be used as a source for generating  $V_{RT}$  and  $V_{RB}$ , due to the noise spikes (50 to 400 mV) present on the supplies and on their ground lines. Generally  $\pm 15$  V, or  $\pm 12$  V, are available for analog circuits, and are usually clean compared to supplies used for digital circuits, although ripple may be present in varying amounts. Ripple is easier to filter out than spikes, however, and so these supplies are preferred.

Figure 21 depicts a circuit which can provide an extremely stable voltage to  $V_{RT}$  **at the current required** (the maximum reference current is 19.2 mA @ 2.0 V). The MC1403 series of reference sources has very low temperature coefficients, good noise rejection, and a high initial accuracy, allowing the circuit to be built without an adjustment pot if the  $V_{RT}$  voltage is to remain fixed at one value. Using 0.1% wirewound resistors for the divider provides sufficient accuracy and stability in many cases. Alternately, resistor networks provide high ratio accuracies, and close temperature tracking. If the application requires  $V_{RT}$  to be changed periodically, the two resistors can be replaced with a 20 turn, cermet potentiometer. Wirewound potentiometers should not be used for this type of application since the pot's slider jumps from winding to winding, and an exact setting can be difficult to obtain. Cermet pots allow for a smooth continuous adjustment.

In Figure 21, R1 reduces the power dissipation in the transistor, and can be carbon composition. The 0.1  $\mu\text{F}$  capacitor in the feedback path provides stability in the unity gain configuration. Recommended op amps are: LM358, MC34001 series, LM308A, LM324, and LM11C. Offset drift is the key parameter to consider in choosing an op amp, and the LM308A has the lowest drift of those mentioned. Bypass capacitors are not shown in Figure 21, but should always be provided at the input to the 2.5 V reference, and at the power supply pins of the op amp.

Figure 22 shows a simpler and more economical circuit, using the LM317LZ regulator, but with lower initial accuracy and temperature stability. The op amp/current booster is not needed since the LM317LZ can supply the current directly. In a well controlled environment, this circuit will suffice for many applications. Because of the lower initial accuracy, an adjustment pot is a necessity.

Figure 23 shows two circuits for providing the voltage to  $V_{RB}$ . The circuits are similar to those of Figures 21 and 22, and have similar accuracy and stability. The output transistor is a PNP in this case since the circuit must sink the reference current.

## VIDEO APPLICATIONS

The MC10319 is suitable for digitizing video signals directly without signal conditioning, although the standard  $1.0 V_{pp}$  video signal can be amplified to a  $2.0 V_{pp}$  signal for slightly better accuracy. Figure 24 shows the input (top trace) and reconstructed output of a standard NTSC test signal, sampled at 25 MSPS, consisting of a sync pulse, 3.58 MHz color burst, a 3.58 MHz signal in a  $\text{Sin}^2x$  envelope, a pulse, a white level signal, and a black level signal. Figure 25 shows a  $\text{Sin}^2x$  pulse that has been digitized and reconstructed at 25 MSPS. The width of the pulse is  $\approx 450$  ns at the base. Figure 26 shows an application circuit for digitizing video.

## 9-Bit A/D Converter

Figure 27 shows how two MC10319s can be connected to form a 9-bit converter. In this configuration, the outputs (D7 to D0) of the two 8-bit converters are paralleled. The outputs of one device are active, while the outputs of the other are in the 3-state mode. The selection is made by the Overrange output of the lower MC10319, which controls Enable inputs on the two devices. Additionally, this output provides the 9th bit.

The reference ladders are connected in series, providing the 512 steps required for 9 bits. The input voltage range is determined by  $V_{RT}$  of the upper MC10319, and  $V_{RB}$  of the lower device. A minimum of 1.0 volt is required across each converter. The  $500 \Omega$  pot (20 turn cermet) allows for adjustment of the midpoint since the reference resistors of the two MC10319s may not be identical in value. Without the adjustment, a non-equal voltage division would occur, resulting in a nonlinear conversion. If the references are to be

symmetrical about ground (e.g.,  $\pm 1.0$  V), the adjustment can be eliminated, and the midpoint connected to ground. The use of latches on the outputs is optional, depending on the application.

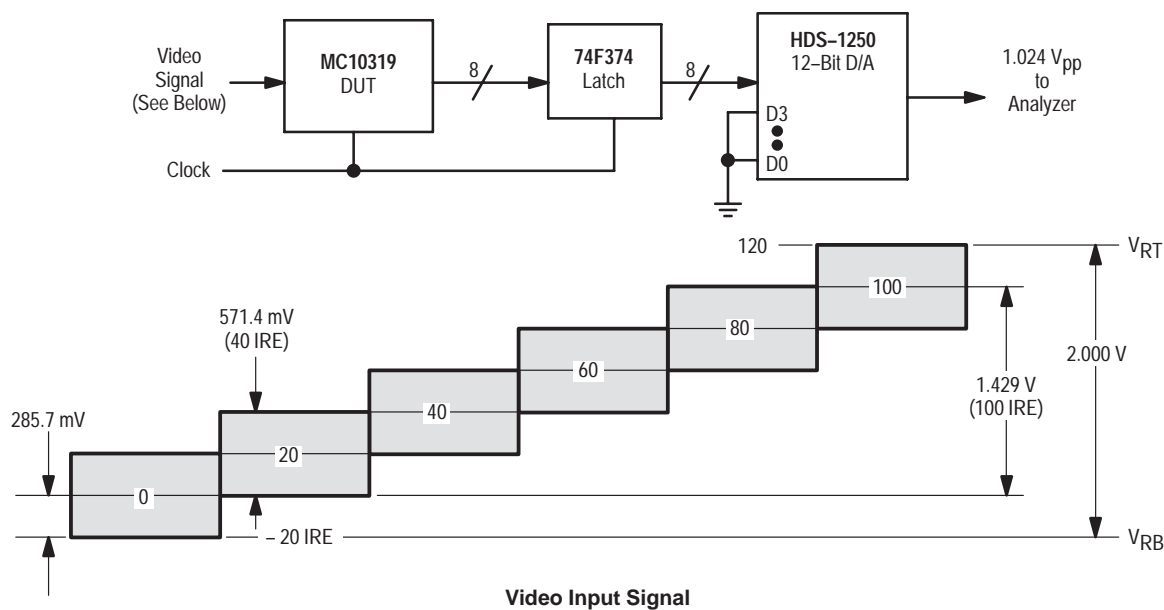
## 50 MHz, 8-Bit A/D Converter

Figure 28 shows how two MC10319s can be connected together in a flip-flop arrangement in order to have an effective conversion speed of 50 MHz. The 74F74 D-type flip-flop provides a 25 MHz clock to each converter, and at the same time, controls the Enables so as to alternately enable and disable the outputs. The Overranges do not have 3-state capability, and so cannot be paralleled. Instead they are OR'd together. The use of latches is optional, and depends on the application. Data should be latched, or written to RAM (in a DMA operation), on the high-to-low transition of the 50 MHz clock.

## Negative Voltage Regulator

In the cases where a negative power supply is not available (neither the  $-3.0$  to  $-6.0$  V, nor a higher negative voltage from which to derive it), the circuit of Figure 29 can be used to generate  $-5.0$  V from the  $+5.0$  V supply. The PC board space required is small ( $\approx 2.0$  in<sup>2</sup>), and it can be located physically close to the MC10319. The MC34063A is a switching regulator, and in Figure 29 is configured in an inverting mode of operation. The regulator operating specifications are also given.

Figure 16. Differential Phase and Gain Test



1. Input waveform: 571.4 mV<sub>pp</sub>, sine wave @ 3.579545 MHz, dc levels as shown above.
2. MC10319 clock at 14.31818 MHz (4x) asynchronous to input.
3. Differential gain: peak-to-peak output @ each IRE level compared to that at 0 IRE.
4. Differential phase: Phase @ each IRE level compared to that @ 0 IRE.

# MC10319

Figure 17. Representative Block Diagram

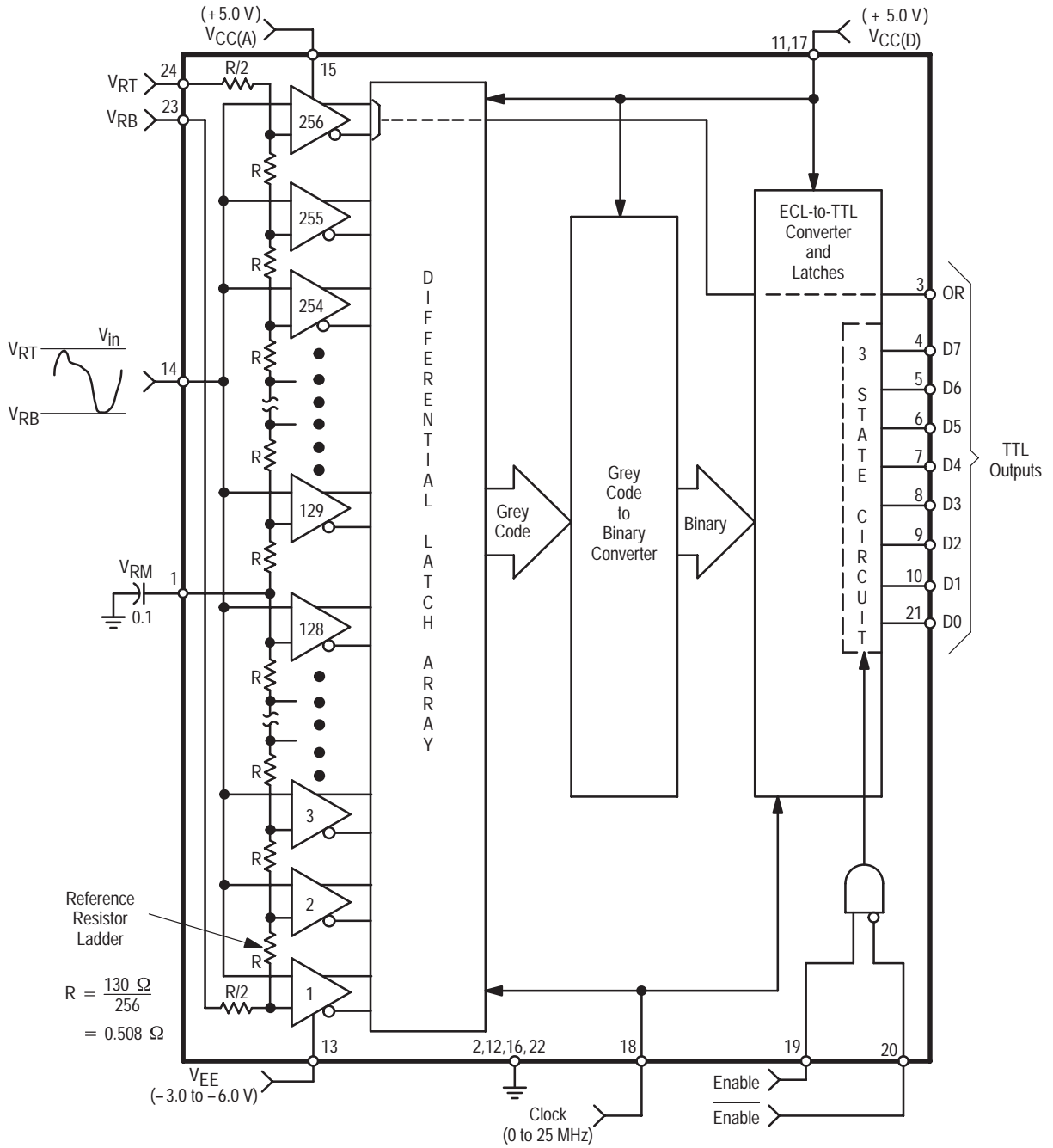


Figure 18. Adjusting  $V_{RM}$  for Improved Linearity

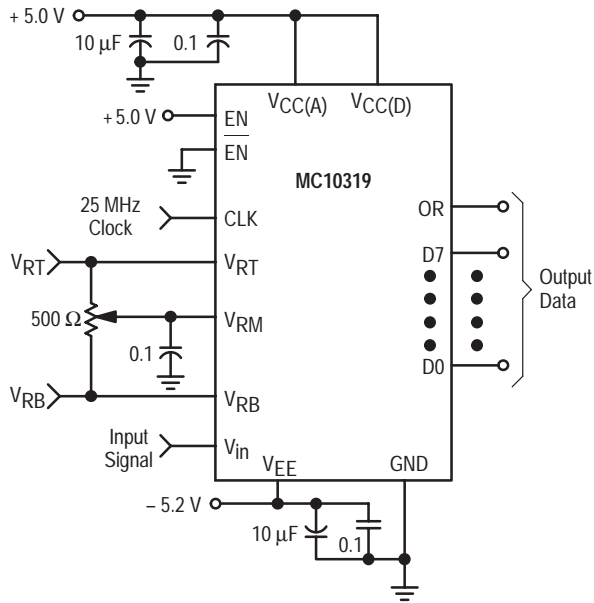


Figure 19. Conversion Sequence

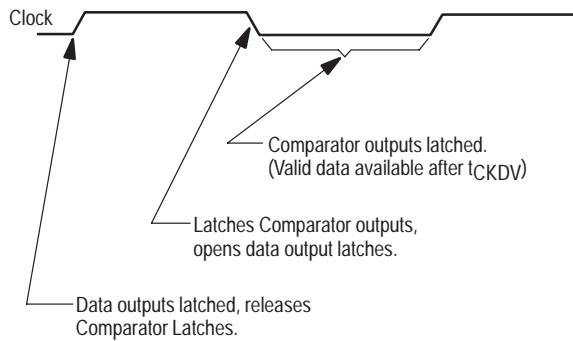
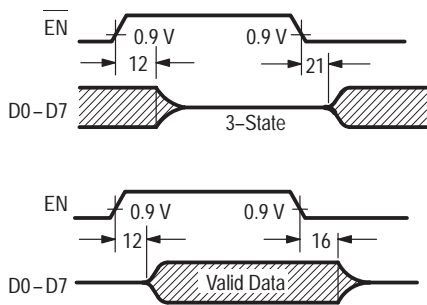
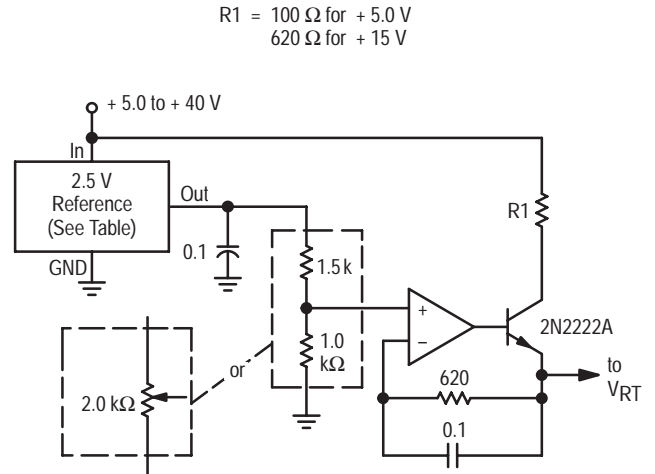


Figure 20. Enable to Output Critical Timing



Timing @ D7 to D0 measured where waveform starts to change. Indicated time values are typical @ 25°C, and are in ns.

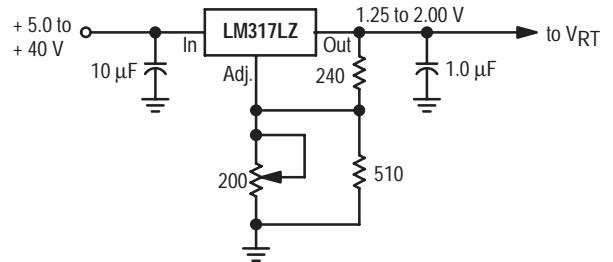
Figure 21. Precision  $V_{RT}$  Voltage Source



$R1 = 100 \Omega$  for + 5.0 V  
 $620 \Omega$  for + 15 V

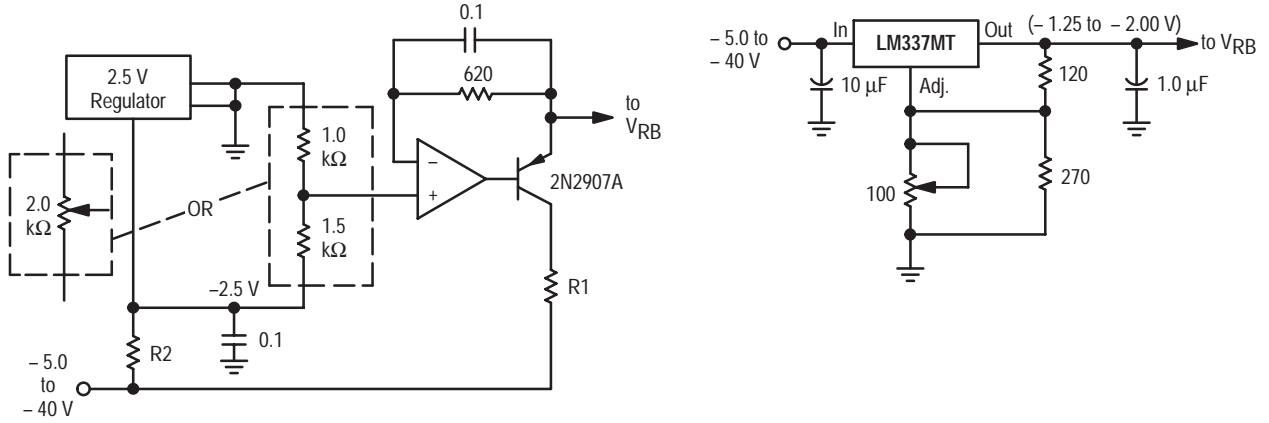
2.5 V References	MC1403	MC1403A
Line Regulation	0.5 mV	0.5 mV
$T_C$ (ppm/°C) max	40	25
$\Delta V_{out}$ for 0 to +70°C	7.0 mV	4.4 mV
Initial Accuracy	$\pm 1\%$	$\pm 1\%$

Figure 22. Voltage Source for  $V_{RT}$  Pin



LM317LZ	
Line Regulation	1.0 mV
$T_C$ (ppm/°C) max	60
$\Delta V_{out}$ for 0 to +70°C	8.4 mV
Initial Accuracy	$\pm 4\%$

Figure 23. Voltage Sources for  $V_{RB}$  Pin



$R1 = 100 \Omega$  for  $-5.0 \text{ V}$   
 $= 620 \Omega$  for  $-15 \text{ V}$

$R2 = 620 \Omega$  for  $-5.0 \text{ V}$   
 $= 3.0 \text{ k}\Omega$  for  $-15 \text{ V}$

2.5 V Reference	LM337MT
Line Regulation	1.0 mV
$T_C$ (ppm/ $^{\circ}\text{C}$ ) max	48
$\Delta V_{out}$ for 0 to $+70^{\circ}\text{C}$	6.7 mV
Initial Accuracy	$\pm 4\%$

Figure 24. Composite Video Waveform

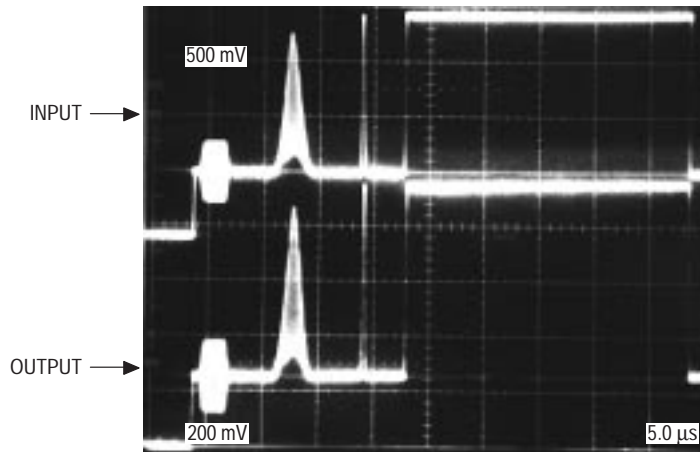
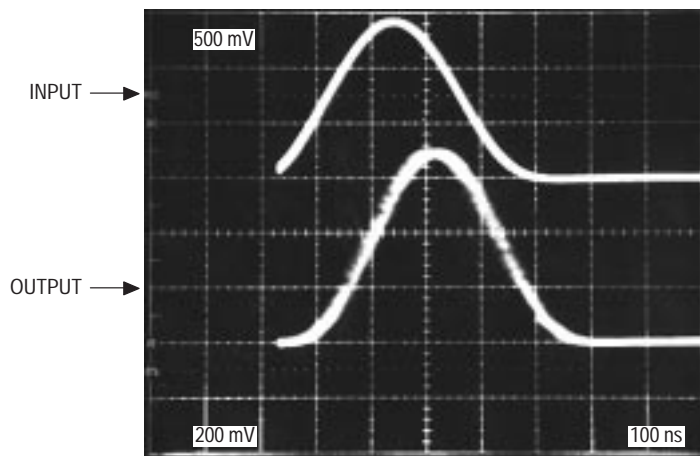
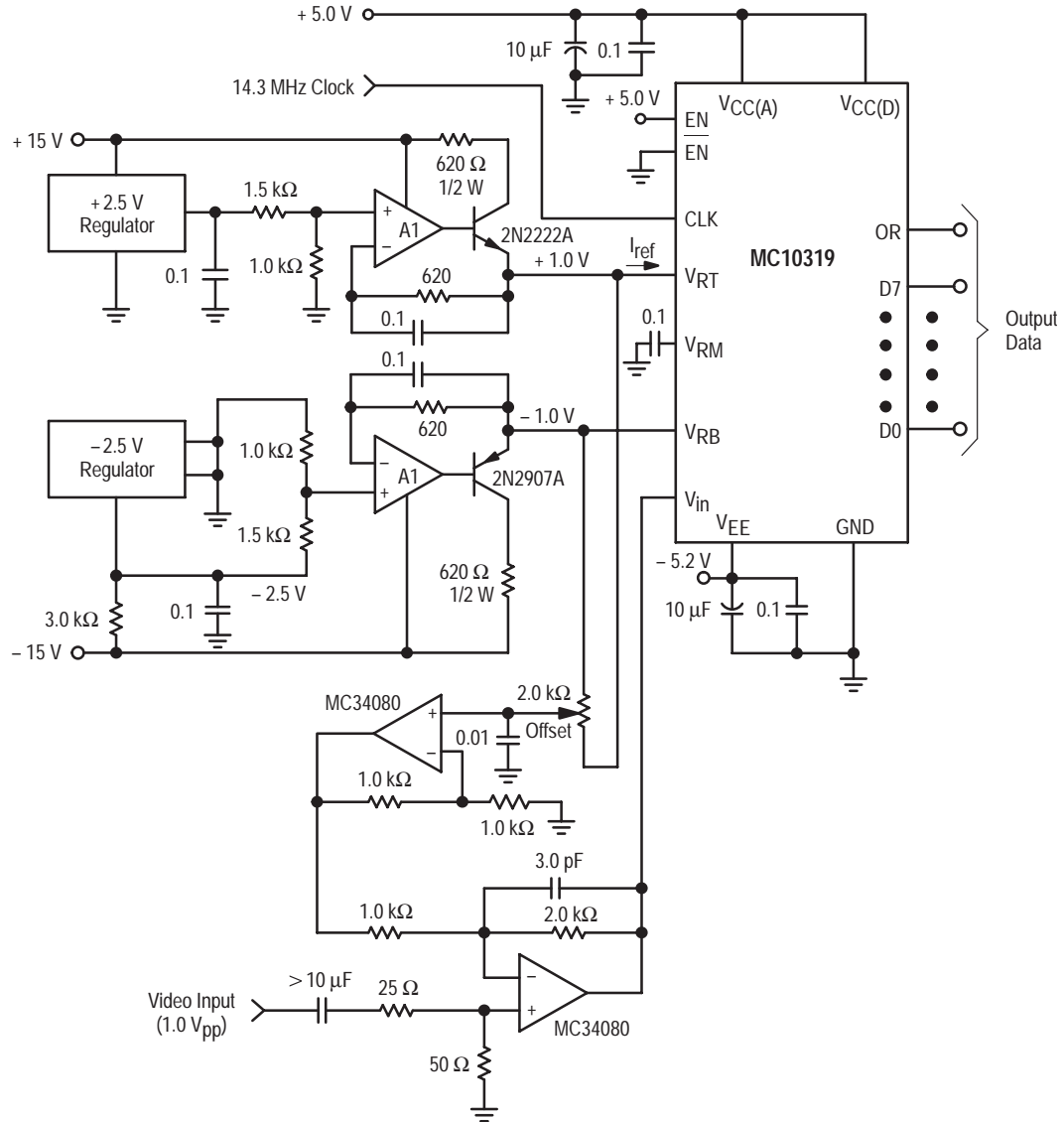


Figure 25.  $\text{SIN}^2 x$  Waveform



# MC10319

Figure 26. Application Circuit for Digitizing Video



- NOTES:**
- 1) MC34080's powered from  $\pm 15$  V supplies. MC34083 (Dual) may be used.
  - 2) Bypass capacitors required at power supply pins of **all** ICs.
  - 3) Ground plane required over all parts of circuit board.
  - 4) Care in layout around MC34080's necessary for good frequency response.
  - 5) A1 = MC34002.



# MC10319

Figure 28. 50 MHz 8-Bit A/D Converter

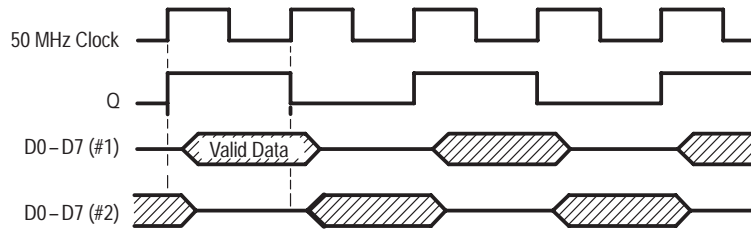
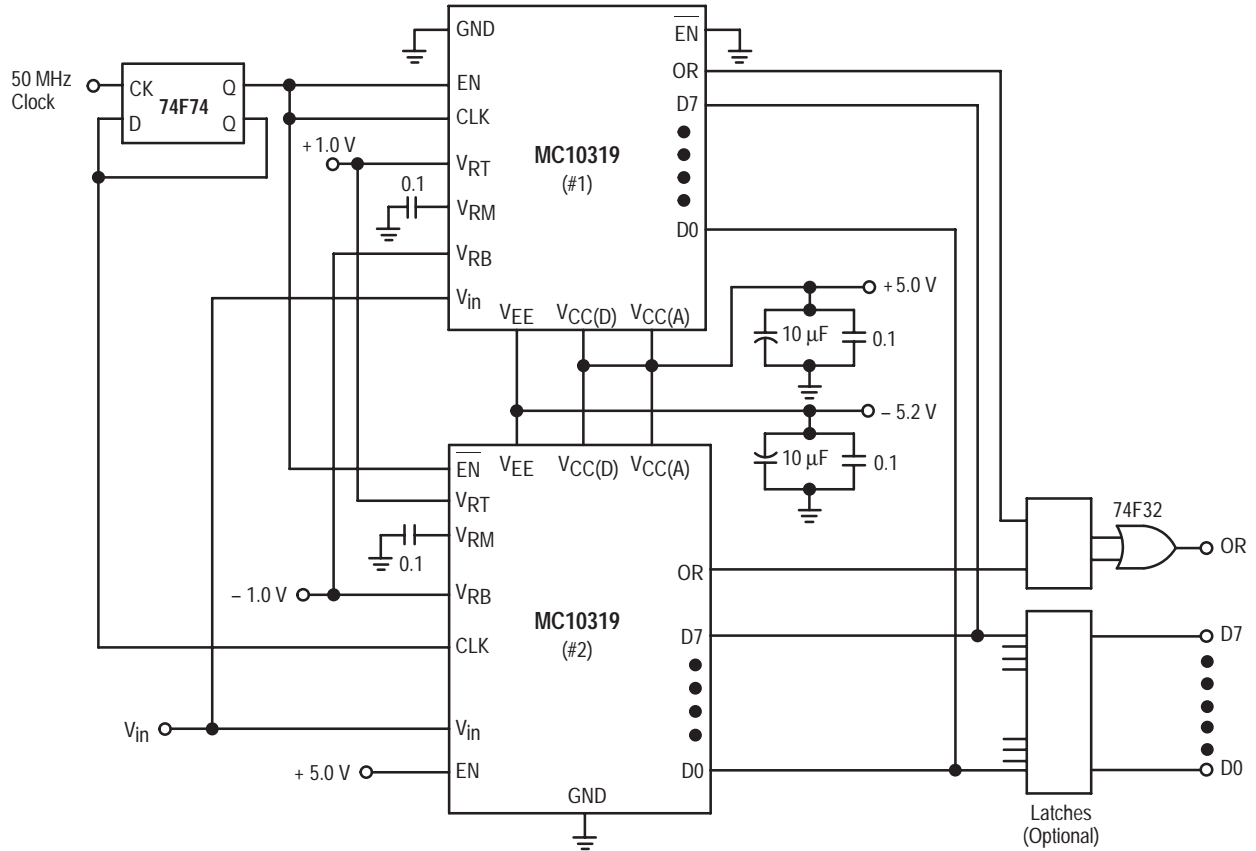
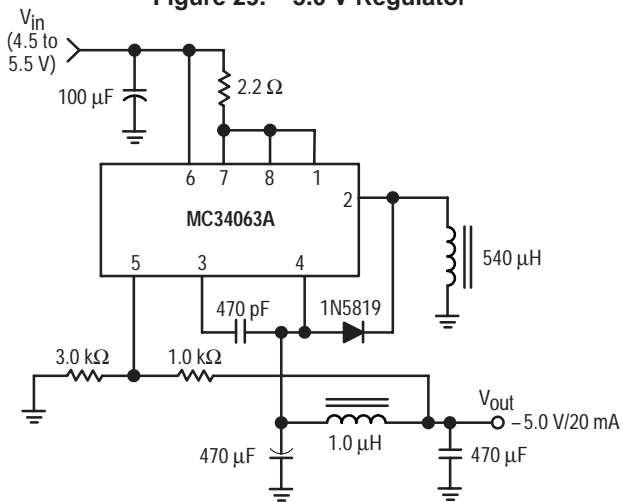


Figure 29. - 5.0 V Regulator



Test	Conditions	Results
Line Regulation	$4.5 \text{ V} < V_{in} < 5.5 \text{ V}$ , $I_{out} = 10 \text{ mA}$	0.16%
Load Regulation	$V_{in} = 5.0 \text{ V}$ , $8.0 \text{ mA} < I_{out} < 20 \text{ mA}$	0.4%
Output Ripple	$V_{in} = 5.0 \text{ V}$ , $I_{out} = 20 \text{ mA}$	2.0 mV <sub>pp</sub>
Short Circuit $I_{out}$	$V_{in} = 5.0 \text{ V}$ , $R_1 = 0.1 \Omega$	140 mA
Efficiency	$V_{in} = 5.0 \text{ V}$ , $I_{out} = 50 \text{ mA}$	52%

## GLOSSARY

**Aperture Delay** – The time difference between the sampling signal (typically a clock edge) and the actual analog signal converted. The actual signal converted may occur before or after the sampling signal, depending on the internal configuration of the converter.

**Bipolar Input** – A mode of operation whereby the analog input (of an A/D), or output (of a DAC), includes both negative and positive values. Examples are  $-1.0$  to  $+1.0$  V,  $-5.0$  to  $+5.0$  V,  $-2.0$  to  $+8.0$  V, etc.

**Bipolar Offset Error** – The difference between the actual and ideal locations of the 00<sub>H</sub> to 01<sub>H</sub> transition, where the ideal location is 1/2 LSB above the most negative reference voltage.

**Bipolar Zero Error** – The error (usually expressed in LSBs) of the input voltage location (of an A/D) of the 80<sub>H</sub> to 81<sub>H</sub> transition. The ideal location is 1/2 LSB above zero volts in the case of an A/D setup for a symmetrical bipolar input (e.g.,  $-1.0$  to  $+1.0$  V).

**Differential Nonlinearity** – The maximum deviation in the actual step size (one transition level to another) from the ideal step size. The ideal step size is defined as the Full Scale Range divided by  $2^n$  ( $n$  = number of bits). This error must be within  $\pm 1$  LSB for proper operation.

**ECL** – Emitter coupled logic.

**Full Scale Range (Actual)** – The difference between the actual minimum and maximum end points of the analog input (of an A/D).

**Full Scale Range (Ideal)** – The difference between the actual minimum and maximum end points of the analog input (of an A/D), plus one LSB.

**Gain Error** – The difference between the actual and expected gain (end point to end point), with respect to the reference, of a data converter. The gain error is usually expressed in LSBs.

**Grey Code** – Also known as *reflected binary code*, it is a digital code such that each code differs from adjacent codes by only one bit. Since more than one bit is never changed at each transition, race condition errors are eliminated.

**Integral Nonlinearity** – The maximum error of an A/D, or DAC, transfer function from the ideal straight line connecting the analog end points. This parameter is sensitive to dynamics, and test conditions must be specified in order to be meaningful. This parameter is the best overall indicator of the device's performance.

**Line Regulation** – The ability of a voltage regulator to maintain a certain output voltage as the input to the regulator is varied. The error is typically expressed as a percent of the nominal output voltage.

**Load Regulation** – The ability of a voltage regulator to maintain a certain output voltage as the load current is varied. The error is typically expressed as a percent of the nominal output voltage.

**LSB** – Least Significant Bit. It is the lowest order bit of a binary code.

**Monotonicity** – The characteristic of the transfer function whereby increasing the input code (of a DAC), or the input signal (of an A/D), results in the output never decreasing.

**MSB** – Most Significant Bit. It is the highest order bit of a binary code.

**Natural Binary Code** – A binary code defined by:

$$N = A_n 2^n + \dots + A_3 2^3 + A_2 2^2 + A_1 2^1 + A_0 2^0$$

where each "A" coefficient has a value of 1 or 0. Typically, all zeroes correspond to a zero input voltage of an A/D, and all ones correspond to the most positive input voltage.

**Nyquist Theorem** – See Sampling Theorem.

**Offset Binary Code** – Applicable only to bipolar input (or output) data converters, it is the same as Natural Binary, except that all zeros correspond to the most negative input voltage (of an A/D), while all ones correspond to the most positive input.

**Power Supply Sensitivity** – The change in a data converter's performance with changes in the power supply voltage(s). This parameter is usually expressed in percent of full scale versus  $\Delta V$ .

**Quantization Error** – Also known as *digitization error* or *uncertainty*. It is the inherent error involved in digitizing an analog signal due to the finite number of steps at the digital output versus the infinite number of values at the analog input. This error is a minimum of  $\pm 1/2$  LSB.

**Resolution** – The smallest change which can be discerned by an A/D converter, or produced by a DAC. It is usually expressed as the number of bits ( $n$ ), where the converter has  $2^n$  possible states.

**Sampling Theorem** – Also known as the *Nyquist Theorem*. It states that the sampling frequency of an A/D must be no less than 2x the highest frequency (of interest) of the analog signal to be digitized in order to preserve the information of that analog signal.

**Unipolar Input** – A mode of operation whereby the analog input range (of an A/D), or output range (of a DAC), includes values of a signal polarity. Examples are 0 to  $+2.0$  V, 0 to  $-5.0$  V,  $2.0$  to  $8.0$  V, etc.

**Unipolar Offset Error** – The difference between the actual and ideal locations of the 00<sub>H</sub> to 01<sub>H</sub> transition, where the ideal location is 1/2 LSB above the most negative input voltage.

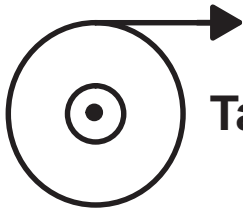
# Tape and Reel Options

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## In Brief . . .

Motorola offers the convenience of Tape and Reel packaging for our growing family of standard integrated circuit products. Reels are available to support the requirements of both first and second generation pick-and-place equipment. The packaging fully conforms to the latest EIA-481A specification. The antistatic embossed tape provides a secure cavity, sealed with a peel-back cover tape.

	<b>Page</b>
Tape and Reel Configurations . . . . .	12-2
Tape and Reel Information Table . . . . .	12-4
Analog MPQ Table . . . . .	12-5

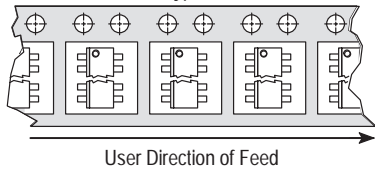


# Tape and Reel Configurations

## Mechanical Polarization

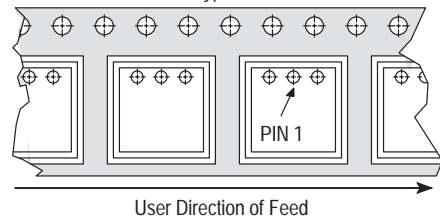
### SOIC and Micro-8 DEVICES

Typical



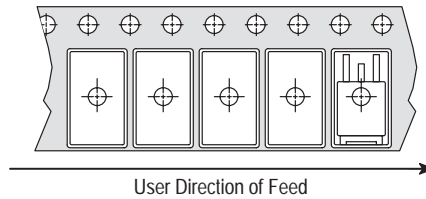
### PLCC DEVICES

Typical



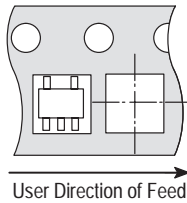
### DPAK and D<sup>2</sup>PAK DEVICES

Typical



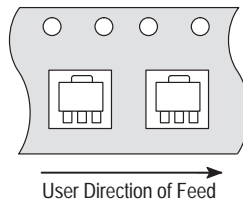
### SOT-23 (5 Pin) DEVICES

Typical



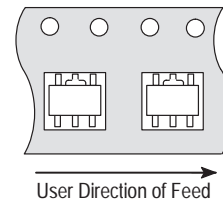
### SOT-89 (3 Pin) DEVICES

Typical



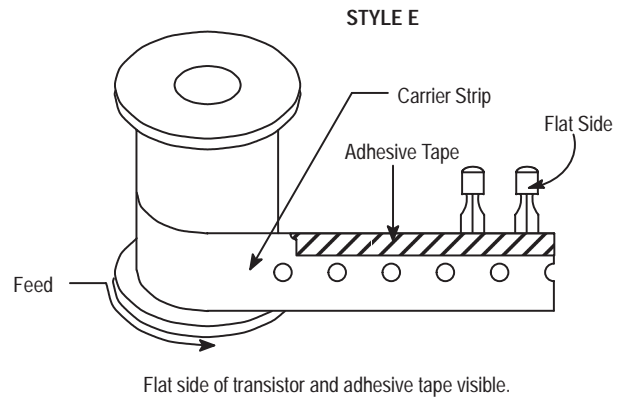
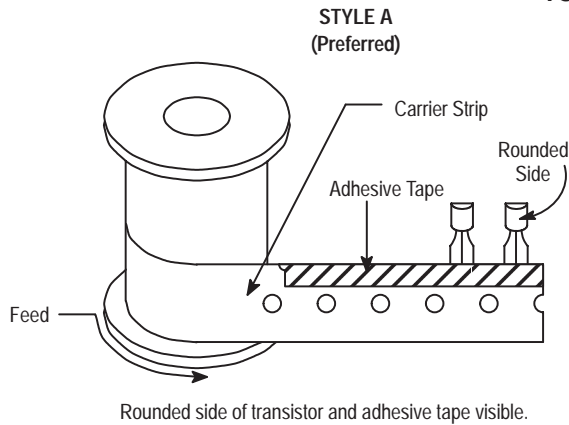
### SOT-89 (5 Pin) DEVICES

Typical

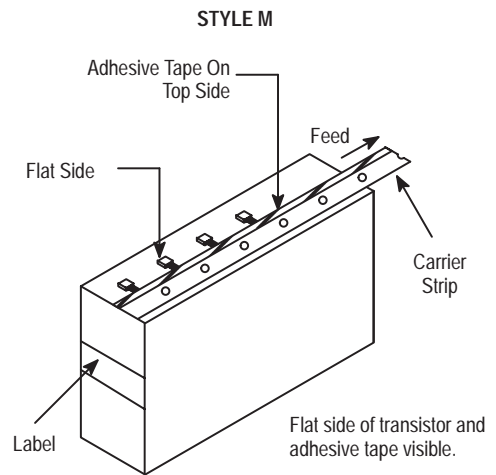
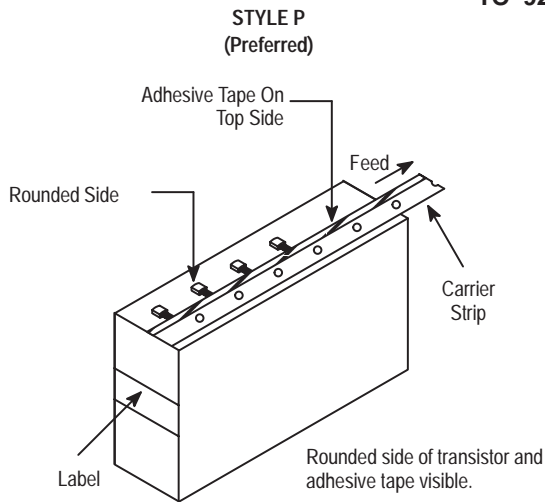


# Tape and Reel Configurations (continued)

## TO-92 Reel Styles



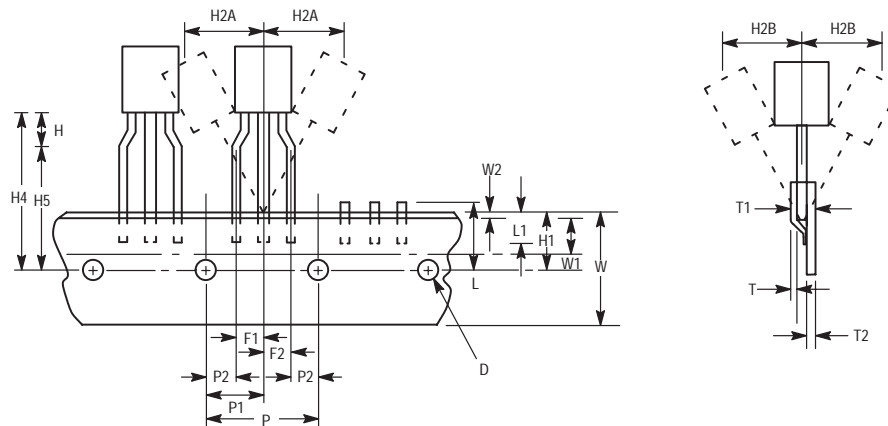
## TO-92 Ammo Pack Styles



Style P ammo pack is equivalent to Styles A and B of reel pack dependent on feed orientation from box.

Style M ammo pack is equivalent to Style E of reel pack dependent on feed orientation from box.

## TO-92 EIA Radial Tape in Fan Fold Box or On Reel



# Tape and Reel Information Table

Package	Tape Width (mm)	Devices <sup>(1)</sup> per Reel	Reel Size (inch)	Device Suffix
SO-8, SOP-8	12	2,500	13	R2
SO-14	16	2,500	13	R2
SO-16	16	2,500	13	R2
SO-16L, SO-8+8L WIDE	16	1,000	13	R2
SO-20L WIDE	24	1,000	13	R2
SO-24L WIDE	24	1,000	13	R2
SO-28L WIDE	24	1,000	13	R2
SO-28L WIDE	32	1,000	13	R3
Micro-8	12	2,500	13	R2
PLCC-20	16	1,000	13	R2
PLCC-28	24	500	13	R2
PLCC-44	32	500	13	R2
PLCC-52	32	500	13	R2
PLCC-68	44	250	13	R2
PLCC-84	44	250	13	R2
TO-226AA (TO-92) <sup>(2)</sup>	18	2,000	13	RA, RE, RP, or RM (Ammo Pack) only
DPAK	16	2,500	13	RK
D <sup>2</sup> PAK	24	800	13	R4
SOT-23 (5 Pin)	8	3,000	7	TR
SOT-89 (3/5 Pin)	12	1,000	7	T1

<sup>(1)</sup> Minimum order quantity is 1 reel. Distributors/OEM customers may break lots or reels at their option, however broken reels may not be returned.

<sup>(2)</sup> Integrated circuits in TO-226AA packages are available in Styes A and E only, with optional "Ammo Pack" (Suffix RP or RM). The RA and RP configurations are preferred. For ordering information please contact your local Motorola Semiconductor Sales Office.

# Analog MPQ Table

## Tape/Reel and Ammo Pack

Package Type	Package Code	MPQ
<b>PLCC</b>		
Case 775	0802	1000/reel
Case 776	0804	500/reel
Case 777	0801	500/reel
<b>SOIC</b>		
Case 751	0095	2500/reel
Case 751A	0096	2500/reel
Case 751B	0097	2500/reel
Case 751G	2003	1000/reel
Case 751D	2005	1000/reel
Case 751E	2008	1000/reel
Case 751F	2009	1000/reel
<b>Micro-8</b>		
Case 846A	-	2500/reel
<b>TO-92</b>		
Case 29	0031	2000/reel
Case 29	0031	2000/Ammo Pack
<b>DPAK</b>		
Case 369A	-	2500/reel
<b>D2PAK</b>		
Case 936	-	800/reel
<b>SOT-23 (5 Pin)</b>		
Case 1212	-	3000/reel
<b>SOT-89 (3 Pin)</b>		
Case 1213	-	1000/reel
<b>SOT-89 (5 Pin)</b>		
Case 1214	-	1000/reel



# Packaging Information

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## In Brief . . .

*The packaging availability for each device type is indicated on the individual data sheets and the Selector Guide. All of the outline dimensions for the packages are given in this section.*

*The maximum power consumption an integrated circuit can tolerate at a given operating ambient temperature can be found from the equation:*

$$P_{D(TA)} = \frac{T_{J(max)} - T_A}{R_{\theta JA(Typ)}}$$

*where:*

$P_{D(TA)}$  = *Power Dissipation allowable at a given operating ambient temperature. This must be greater than the sum of the products of the supply voltages and supply currents at the worst case operating condition.*

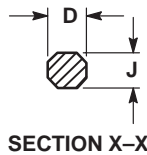
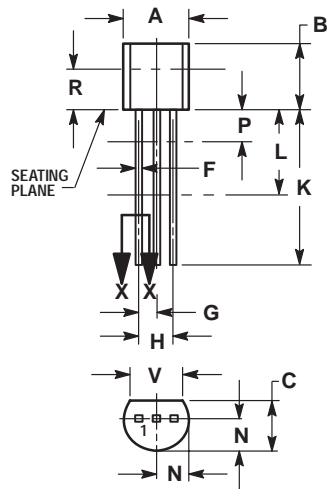
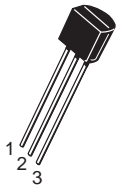
$T_{J(max)}$  = *Maximum operating Junction Temperature as listed in the Maximum Ratings Section. See individual data sheets for  $T_{J(max)}$  information.*

$T_A$  = *Maximum desired operating Ambient Temperature*

$R_{\theta JA(Typ)}$  = *Typical Thermal Resistance Junction-to-Ambient*

# Case Outline Dimensions

**LP, P, Z SUFFIX**  
**CASE 29-04**  
 Plastic Package  
 (TO-226AA/TO-92)  
 ISSUE AD

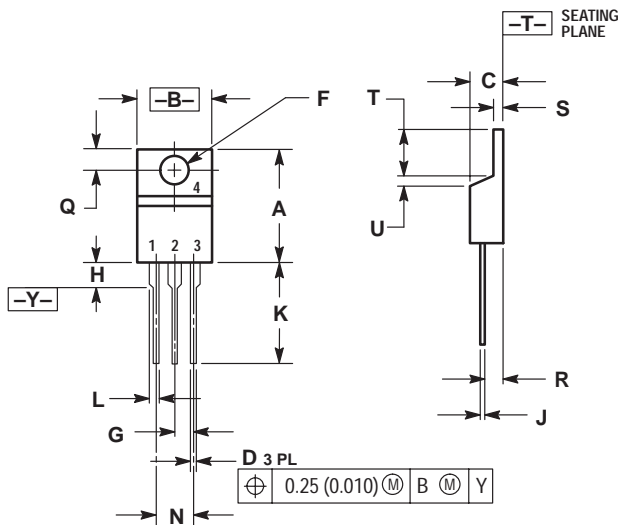
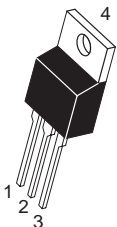


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. DIMENSION F APPLIES BETWEEN P AND L. DIMENSION D AND J APPLY BETWEEN L AND K MINIMUM. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.022	0.41	0.55
F	0.016	0.019	0.41	0.48
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	---	12.70	---
L	0.250	---	6.35	---
N	0.080	0.105	2.04	2.66
P	---	0.100	---	2.54
R	0.115	---	2.93	---
V	0.135	---	3.43	---

**KC, T SUFFIX**  
**CASE 221A-06**  
 Plastic Package  
 ISSUE Y

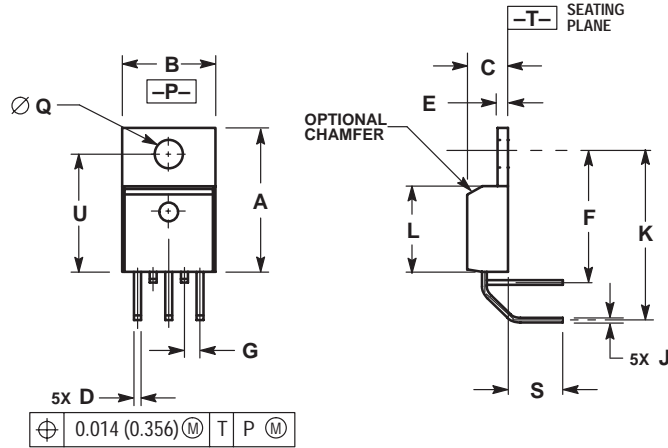
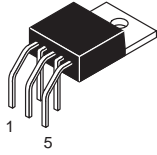


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.560	0.625	14.23	15.87
B	0.380	0.420	9.66	10.66
C	0.140	0.190	3.56	4.82
D	0.020	0.045	0.51	1.14
F	0.139	0.155	3.53	3.93
G	0.100 BSC	---	2.54 BSC	---
H	---	0.280	---	7.11
J	0.012	0.045	0.31	1.14
K	0.500	0.580	12.70	14.73
L	0.045	0.070	1.15	1.77
N	0.200 BSC	---	5.08 BSC	---
Q	0.100	0.135	2.54	3.42
R	0.080	0.115	2.04	2.92
S	0.020	0.055	0.51	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27

**TH SUFFIX**  
**CASE 314A-03**  
 Plastic Package  
 ISSUE D

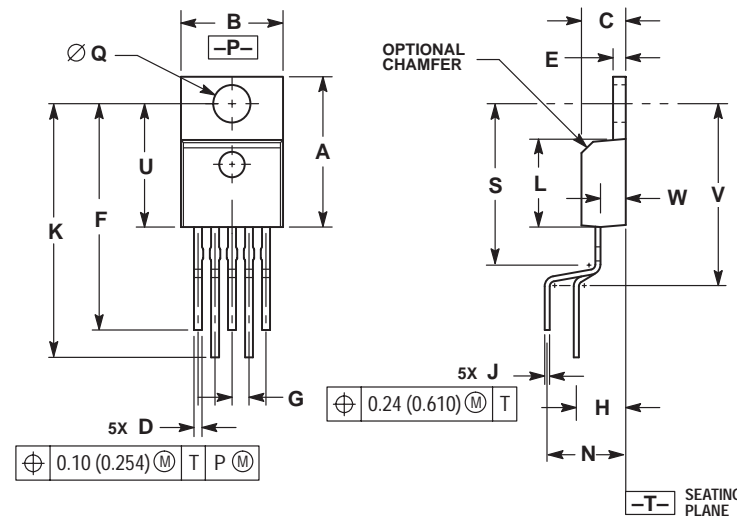
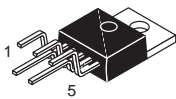


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 0.043 (1.092) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.572	0.613	14.529	15.570
B	0.390	0.415	9.906	10.541
C	0.170	0.180	4.318	4.572
D	0.025	0.038	0.635	0.965
E	0.048	0.055	1.219	1.397
F	0.570	0.585	14.478	14.859
G	0.067 BSC		1.702 BSC	
J	0.015	0.025	0.381	0.635
K	0.730	0.745	18.542	18.923
L	0.320	0.365	8.128	9.271
Q	0.140	0.153	3.556	3.886
S	0.210	0.260	5.334	6.604
U	0.468	0.505	11.888	12.827

**T, TV SUFFIX**  
**CASE 314B-05**  
 Plastic Package  
 ISSUE J

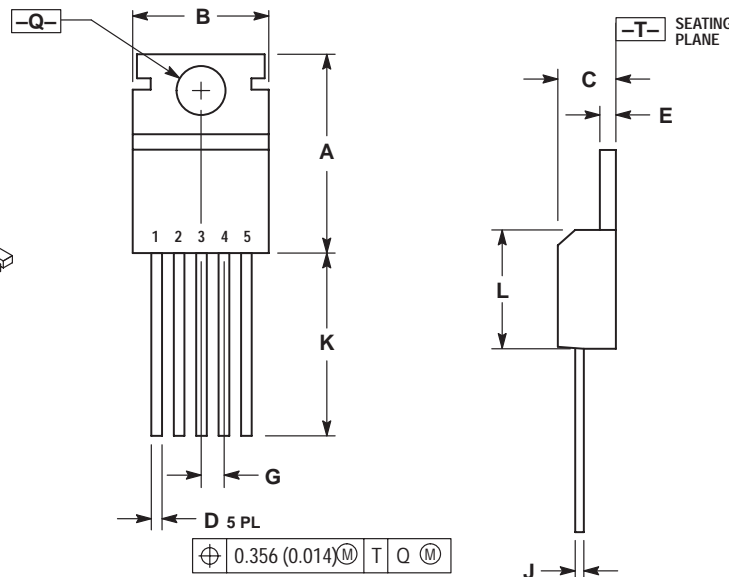
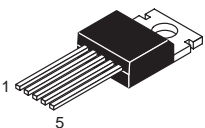


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 0.043 (1.092) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.572	0.613	14.529	15.570
B	0.390	0.415	9.906	10.541
C	0.170	0.180	4.318	4.572
D	0.025	0.038	0.635	0.965
E	0.048	0.055	1.219	1.397
F	0.850	0.935	21.590	23.749
G	0.067 BSC		1.702 BSC	
H	0.166 BSC		4.216 BSC	
J	0.015	0.025	0.381	0.635
K	0.900	1.100	22.860	27.940
L	0.320	0.365	8.128	9.271
N	0.320 BSC		8.128 BSC	
Q	0.140	0.153	3.556	3.886
S	---	0.620	---	15.748
U	0.468	0.505	11.888	12.827
V	---	0.735	---	18.669
W	0.090	0.110	2.286	2.794

**T SUFFIX**  
**CASE 314C-01**  
 Plastic Package  
 ISSUE A

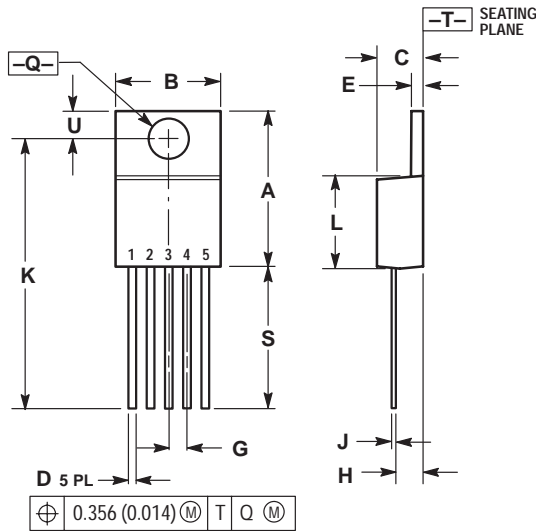
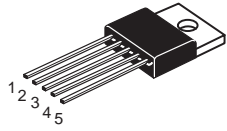


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 10.92 (0.043) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.610	0.625	15.59	15.88
B	0.380	0.420	9.65	10.67
C	0.160	0.190	4.06	4.83
D	0.020	0.040	0.51	1.02
E	0.035	0.055	0.89	1.40
G	0.067 BSC		1.702 BSC	
J	0.015	0.025	0.38	0.64
K	0.500	---	12.70	---
L	0.355	0.370	9.02	9.40
Q	0.139	0.147	3.53	3.73

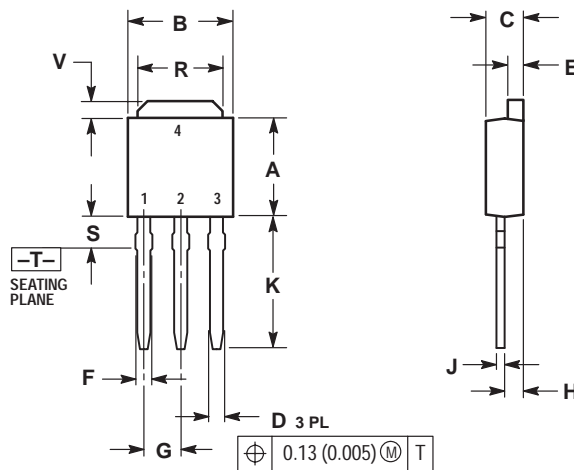
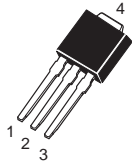
**T, T1 SUFFIX**  
**CASE 314D-03**  
 Plastic Package  
 ISSUE D



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 10.92 (0.043) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.572	0.613	14.529	15.570
B	0.390	0.415	9.906	10.541
C	0.170	0.180	4.318	4.572
D	0.025	0.038	0.635	0.965
E	0.048	0.055	1.219	1.397
G	0.067 BSC		1.702 BSC	
H	0.087	0.112	2.210	2.845
J	0.015	0.025	0.381	0.635
K	1.020	1.065	25.908	27.051
L	0.320	0.365	8.128	9.271
Q	0.140	0.153	3.556	3.886
U	0.105	0.117	2.667	2.972
S	0.543	0.582	13.792	14.783

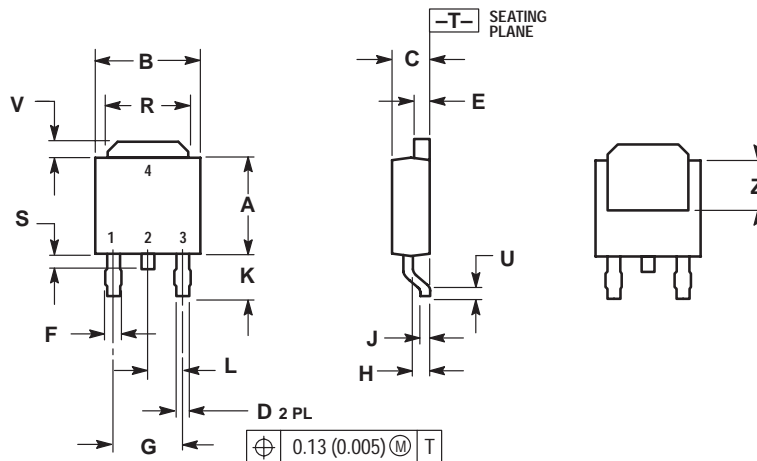
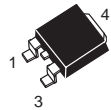
**DT-1 SUFFIX**  
**CASE 369-07**  
 Plastic Package (DPAK)  
 ISSUE K



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.250	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.033	0.040	0.84	1.01
F	0.037	0.047	0.94	1.19
G	0.090 BSC		2.29 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.350	0.380	8.89	9.65
R	0.175	0.215	4.45	5.46
S	0.050	0.090	1.27	2.28
V	0.030	0.050	0.77	1.27

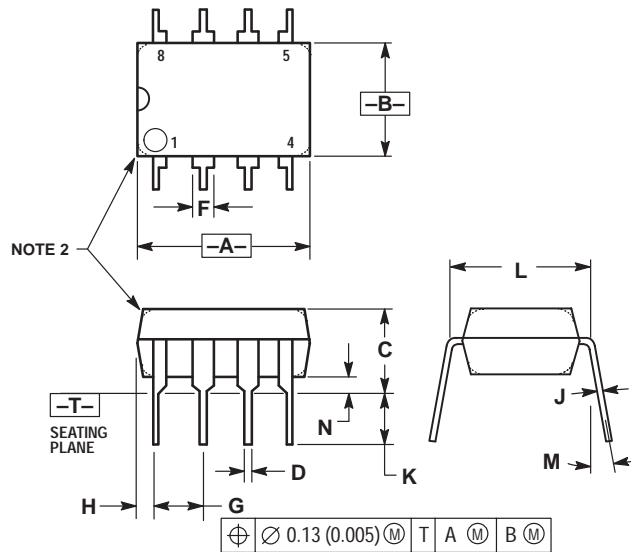
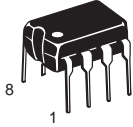
**DT SUFFIX**  
**CASE 369A-13**  
 Plastic Package (DPAK)  
 ISSUE Y



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.250	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.033	0.040	0.84	1.01
F	0.037	0.047	0.94	1.19
G	0.180 BSC		4.58 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.102	0.114	2.60	2.89
L	0.090 BSC		2.29 BSC	
R	0.175	0.215	4.45	5.46
S	0.020	0.050	0.51	1.27
U	0.020	---	0.51	---
V	0.030	0.050	0.77	1.27
Z	0.138	---	3.51	---

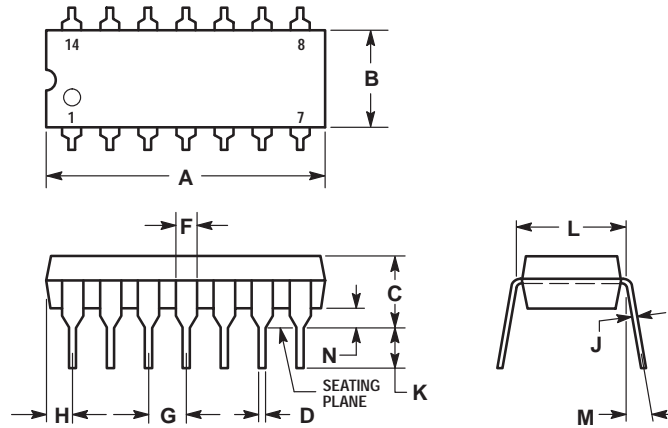
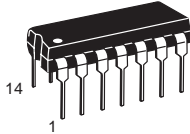
**DP1, N, P, P1 SUFFIX**  
**CASE 626-05**  
 Plastic Package  
 ISSUE K



- NOTES:
1. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
  2. PACKAGE CONTOUR OPTIONAL (ROUND OR SQUARE CORNERS).
  3. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.40	10.16	0.370	0.400
B	6.10	6.60	0.240	0.260
C	3.94	4.45	0.155	0.175
D	0.38	0.51	0.015	0.020
F	1.02	1.78	0.040	0.070
G	2.54 BSC		0.100 BSC	
H	0.76	1.27	0.030	0.050
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	— 10°		— 10°	
N	0.76	1.01	0.030	0.040

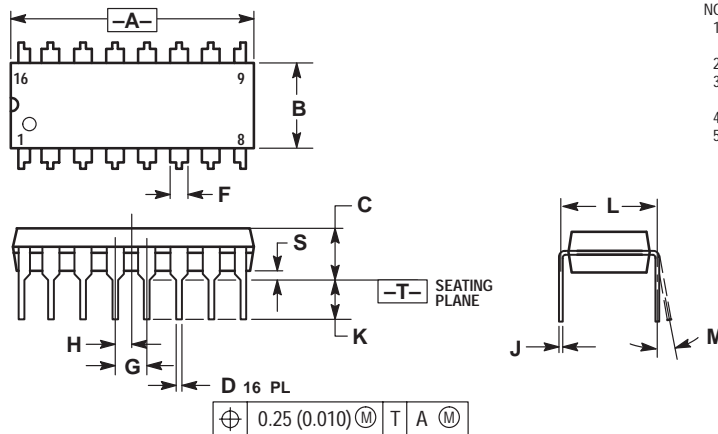
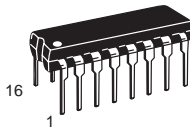
**N, P, N-14, P2 SUFFIX**  
**CASE 646-06**  
 Plastic Package  
 ISSUE L



- NOTES:
1. LEADS WITHIN 0.13 (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
  2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  4. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.715	0.770	18.16	19.56
B	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100 BSC		2.54 BSC	
H	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.300 BSC		7.62 BSC	
M	0° 10°		0° 10°	
N	0.015	0.039	0.39	1.01

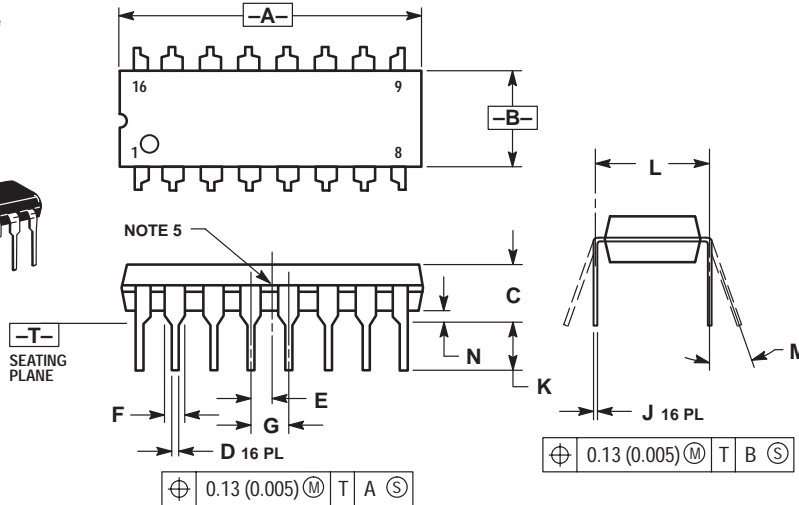
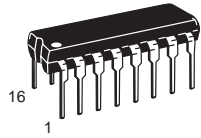
**DP2, N, P, PC SUFFIX**  
**CASE 648-08**  
 Plastic Package  
 ISSUE R



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0° 10°		0° 10°	
S	0.020	0.040	0.51	1.01

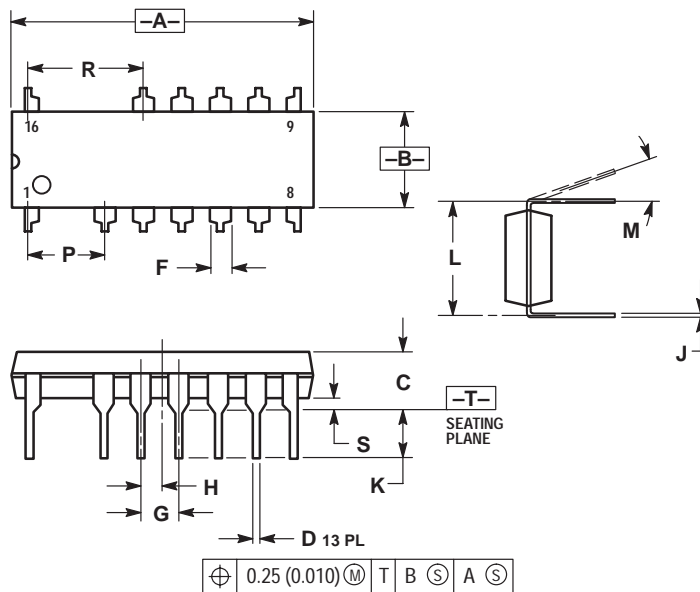
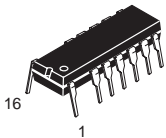
**B, P, P2, V SUFFIX**  
**CASE 648C-03**  
 Plastic Package  
 (DIP-16)  
 ISSUE C



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. INTERNAL LEAD CONNECTION BETWEEN 4 AND 5, 12 AND 13.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.840	18.80	21.34
B	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
E	0.050 BSC			
F	0.040	0.70	1.02	1.78
G	0.100 BSC			
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.300 BSC			
M	0°	10°	0°	10°
N	0.015	0.040	0.39	1.01

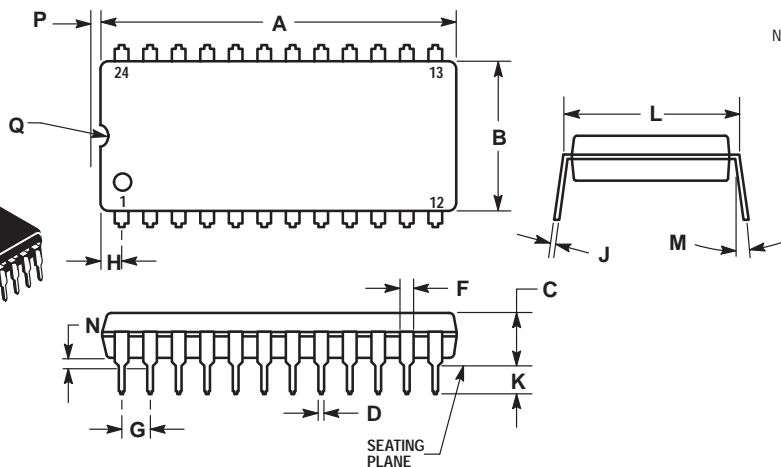
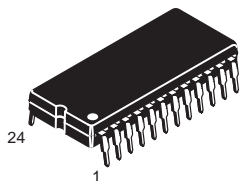
**P SUFFIX**  
**CASE 648E-01**  
 Plastic Package  
 (DIP-16)  
 ISSUE O



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION A AND B DOES NOT INCLUDE MOLD PROTRUSION.
  5. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.25 (0.010).
  6. ROUNDED CORNER OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.760	18.80	19.30
B	0.245	0.260	6.23	6.60
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.050	0.070	1.27	1.77
G	0.100 BSC			
H	0.050 BSC			
J	0.008	0.015	0.21	0.38
K	0.120	0.140	3.05	3.55
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
P	0.200 BSC			
R	0.300 BSC			
S	0.015	0.035	0.39	0.88

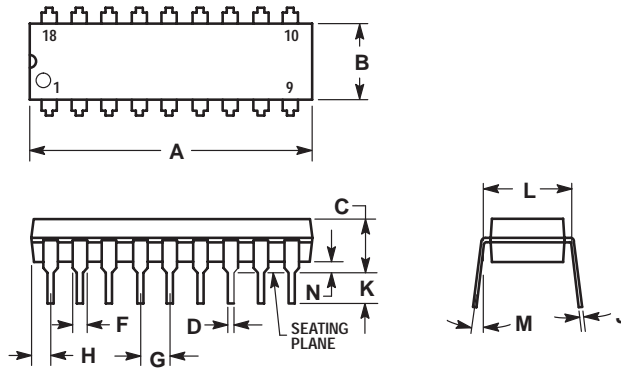
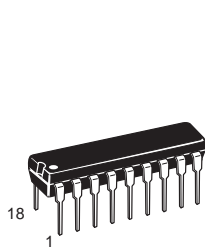
**P SUFFIX**  
**CASE 649-03**  
 Plastic Package  
 ISSUE D



- NOTES:
1. LEADS WITHIN 0.13 (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
  2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	31.50	32.13	1.240	1.265
B	13.21	13.72	0.520	0.540
C	4.70	5.21	0.185	0.205
D	0.38	0.51	0.015	0.020
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
H	1.65	2.16	0.065	0.085
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	14.99	15.49	0.590	0.610
M	---	10	---	10°
N	0.51	1.02	0.020	0.040
P	0.13	0.38	0.005	0.015
Q	0.51	0.76	0.020	0.030

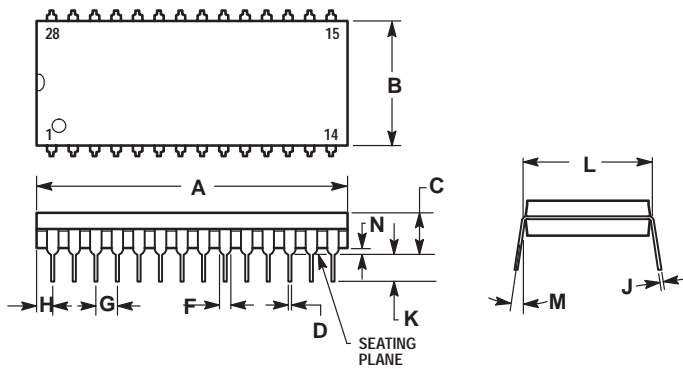
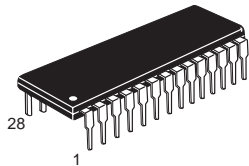
**A, B, N, P SUFFIX**  
**CASE 707-02**  
 Plastic Package  
 ISSUE C



- NOTES:
1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25 (0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
  2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	22.22	23.24	0.875	0.915
B	6.10	6.60	0.240	0.260
C	3.56	4.57	0.140	0.180
D	0.36	0.56	0.014	0.022
F	1.27	1.78	0.050	0.070
G	2.54 BSC		0.100 BSC	
H	1.02	1.52	0.040	0.060
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

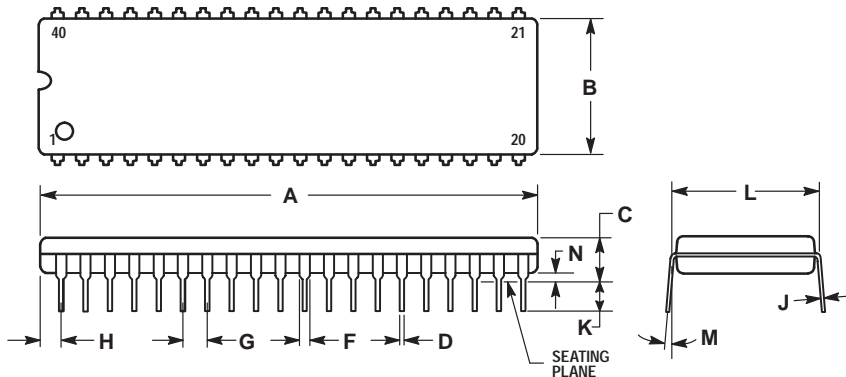
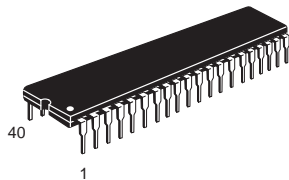
**P SUFFIX**  
**CASE 710-02**  
 Plastic Package  
 ISSUE B



- NOTES:
1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25 (0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
  2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	36.45	37.21	1.435	1.465
B	13.72	14.22	0.540	0.560
C	3.94	5.08	0.155	0.200
D	0.36	0.56	0.014	0.022
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
H	1.65	2.16	0.065	0.085
J	0.20	0.38	0.008	0.015
K	2.92	3.43	0.115	0.135
L	15.24 BSC		0.600 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

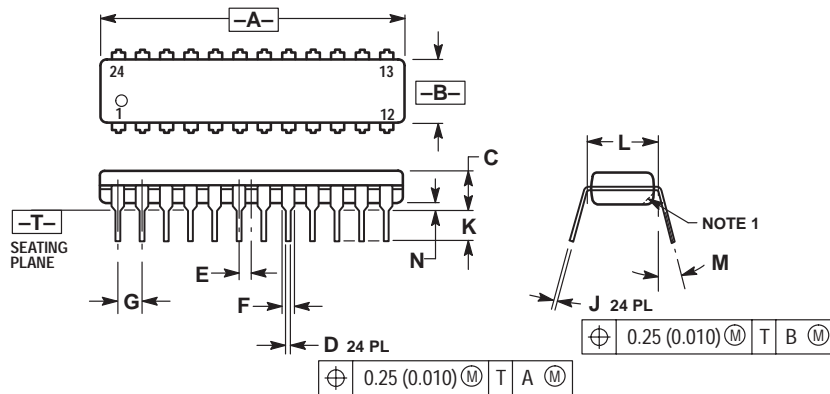
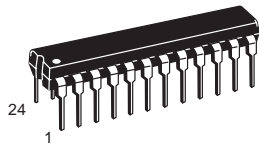
**P SUFFIX**  
**CASE 711-03**  
 Plastic Package  
 ISSUE C



- NOTES:
1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25 (0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
  2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	51.69	52.45	2.035	2.065
B	13.72	14.22	0.540	0.560
C	3.94	5.08	0.155	0.200
D	0.36	0.56	0.014	0.022
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
H	1.65	2.16	0.065	0.085
J	0.20	0.38	0.008	0.015
K	2.92	3.43	0.115	0.135
L	15.24 BSC		0.600 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

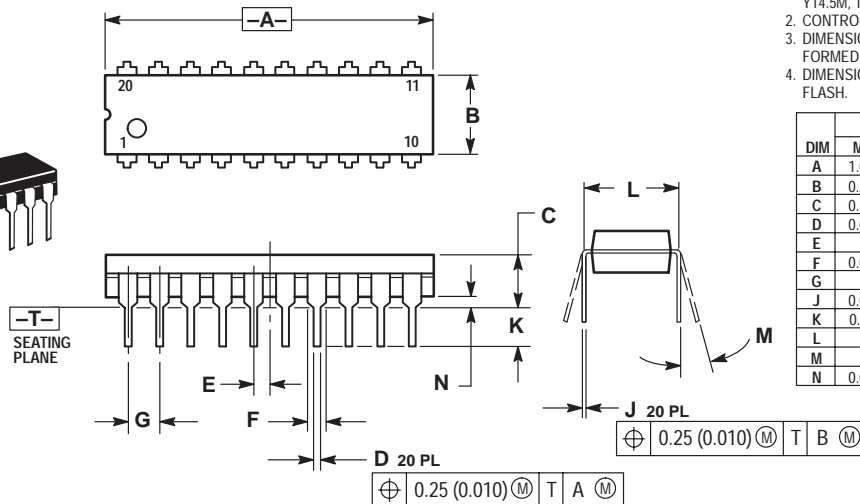
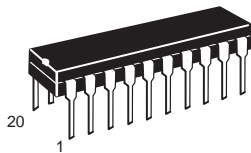
**F, P, P-3 SUFFIX**  
**CASE 724-03**  
 Plastic Package  
 (NDIP-24)  
 ISSUE D



- NOTES:
1. CHAMFERED CONTOUR OPTIONAL.
  2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  3. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  4. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.230	1.265	31.25	32.13
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.020	0.38	0.51
E	0.050 BSC		1.27 BSC	
F	0.040	0.060	1.02	1.52
G	0.100 BSC		2.54 BSC	
J	0.007	0.012	0.18	0.30
K	0.110	0.140	2.80	3.55
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

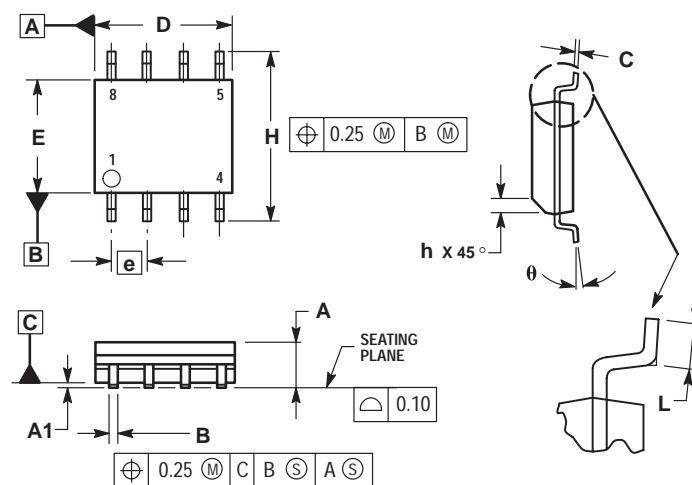
**H, P, DP SUFFIX**  
**CASE 738-03**  
 Plastic Package  
 ISSUE E



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.010	1.070	25.66	27.17
B	0.240	0.260	6.10	6.60
C	0.150	0.180	3.81	4.57
D	0.015	0.022	0.39	0.55
E	0.050 BSC		1.27 BSC	
F	0.050	0.070	1.27	1.77
G	0.100 BSC		2.54 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.140	2.80	3.55
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

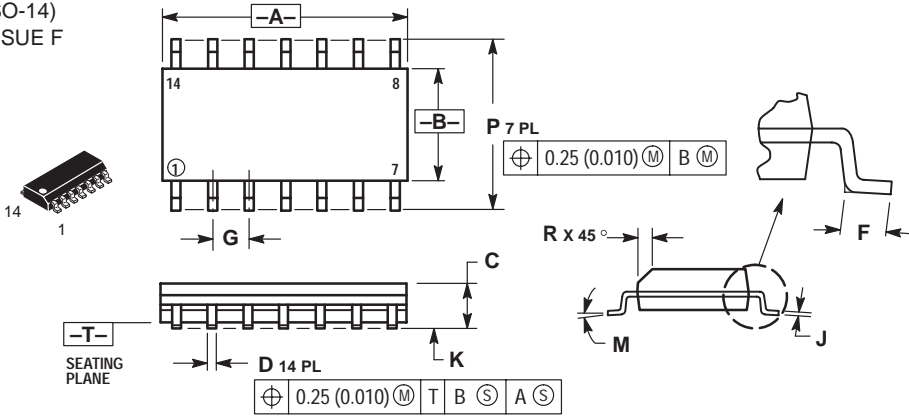
**D, D1, D2 SUFFIX**  
**CASE 751-05**  
 Plastic Package  
 (SO-8, SOP-8)  
 ISSUE R



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. DIMENSIONS ARE IN MILLIMETERS.
  3. DIMENSION D AND E DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
  5. DIMENSION B DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS	
	MIN	MAX
A	1.35	1.75
A1	0.10	0.25
B	0.35	0.49
C	0.18	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27 BSC	
H	5.80	6.20
h	0.25	0.50
L	0.40	1.25
θ	0°	7°

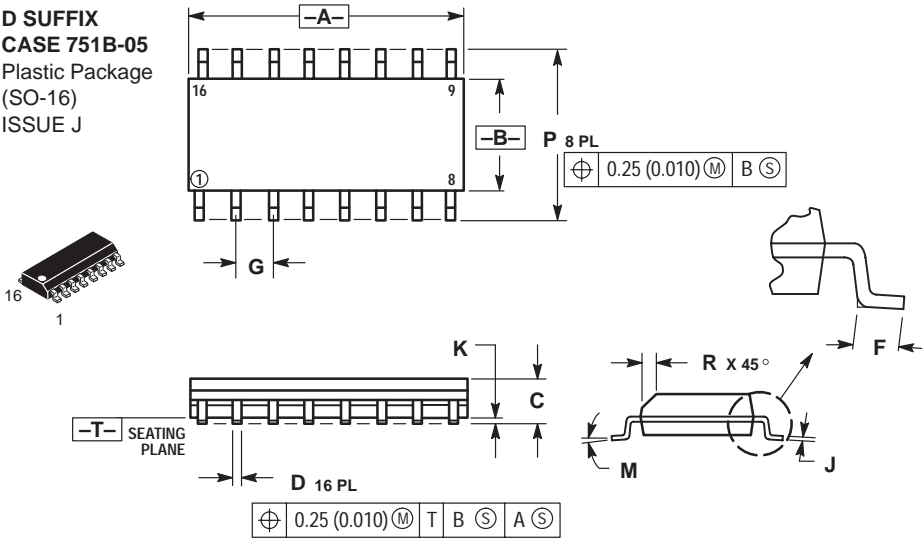
**D SUFFIX**  
**CASE 751A-03**  
 Plastic Package  
 (SO-14)  
 ISSUE F



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
  5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	8.55	8.75	0.337	0.344
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

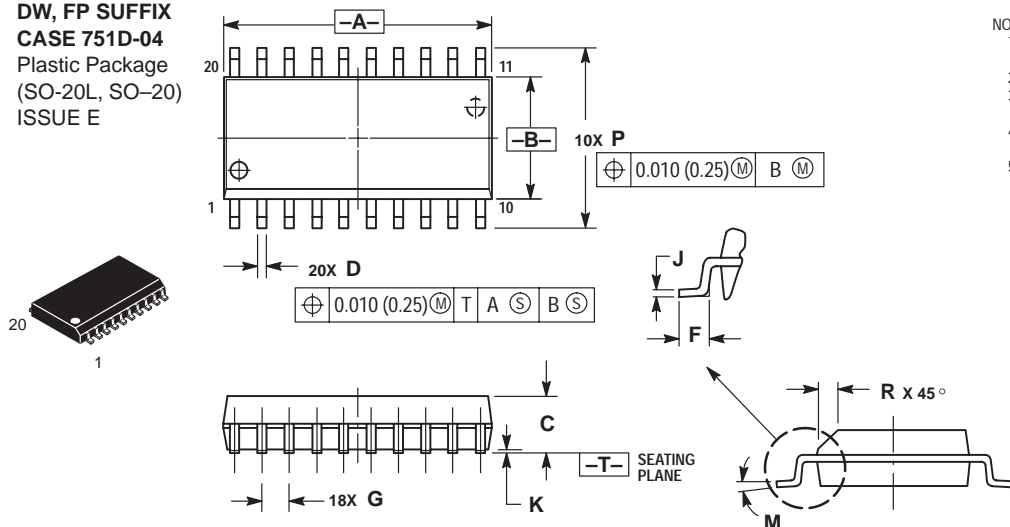
**D SUFFIX**  
**CASE 751B-05**  
 Plastic Package  
 (SO-16)  
 ISSUE J



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
  5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

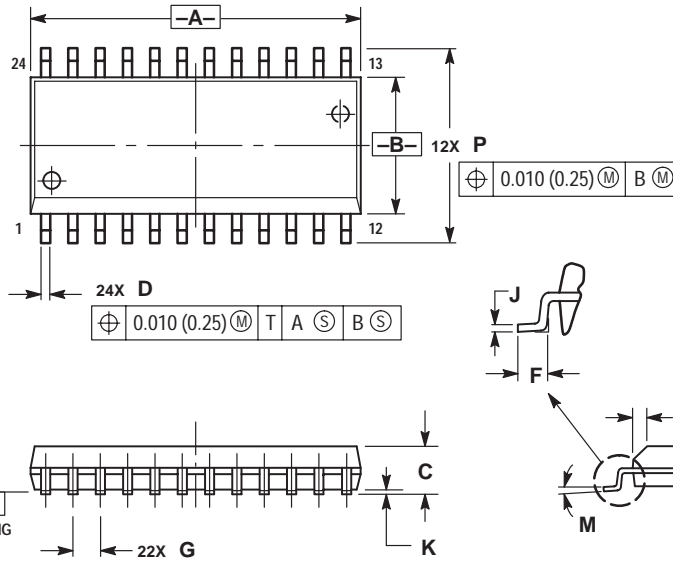
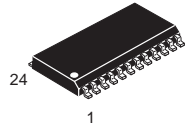
**DW, FP SUFFIX**  
**CASE 751D-04**  
 Plastic Package  
 (SO-20L, SO-20)  
 ISSUE E



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.150 (0.006) PER SIDE.
  5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	12.65	12.95	0.499	0.510
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

**DW SUFFIX**  
**CASE 751E-04**  
 Plastic Package  
 (SO-24L,  
 SOP (16+4+4)L)  
 ISSUE E

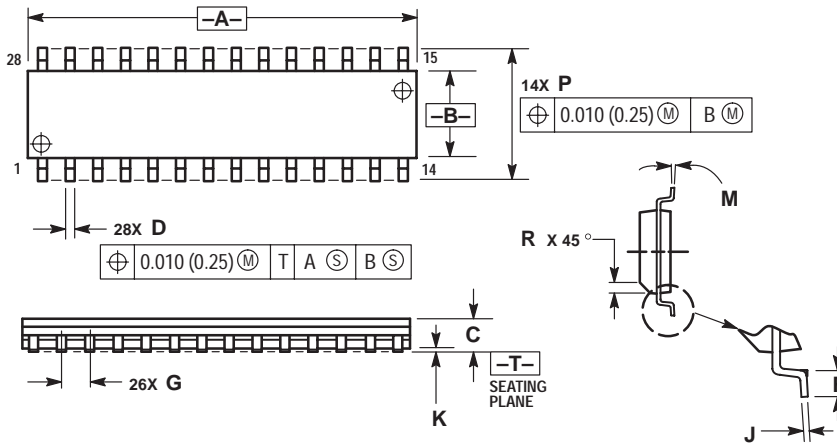
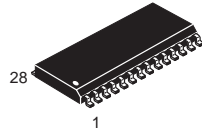


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	15.25	15.54	0.601	0.612
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.41	0.90	0.016	0.035
G	1.27 BSC		0.050 BSC	
J	0.23	0.32	0.009	0.013
K	0.13	0.29	0.005	0.011
M	0°	8°	0°	8°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

**DW SUFFIX**  
**CASE 751F-04**  
 Plastic Package  
 (SO-28L, SOIC-28)  
 ISSUE E

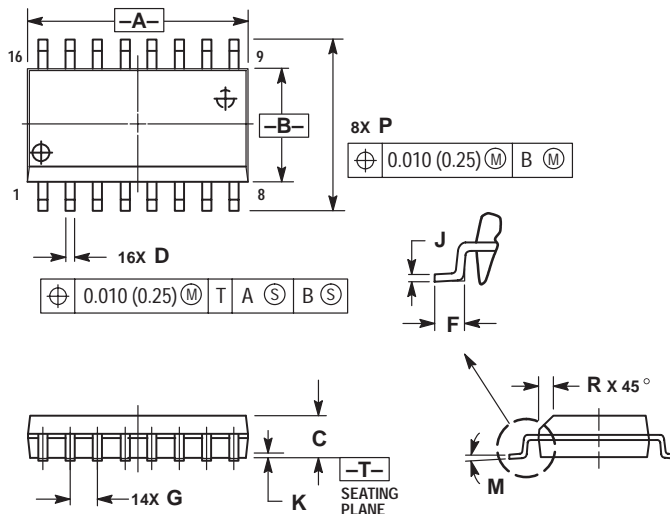
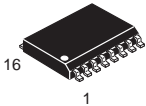


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	17.80	18.05	0.701	0.711
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.41	0.90	0.016	0.035
G	1.27 BSC		0.050 BSC	
J	0.23	0.32	0.009	0.013
K	0.13	0.29	0.005	0.011
M	0°	8°	0°	8°
P	10.01	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

**DW SUFFIX**  
**CASE 751G-02**  
 Plastic Package  
 (SO-16L, SOP-16L,  
 SOP-8+8L)  
 ISSUE A

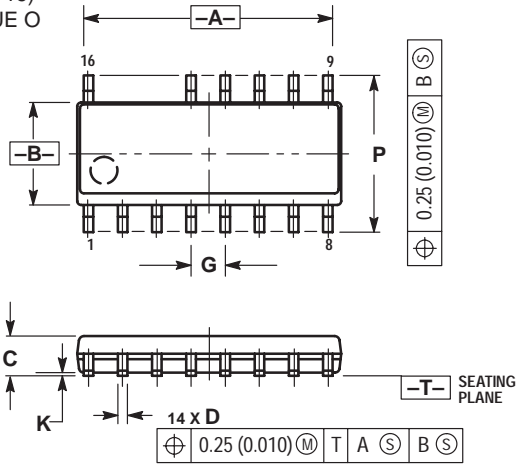
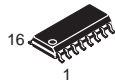


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.15	10.45	0.400	0.411
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

**D SUFFIX**  
**CASE 751K-01**  
 Plastic Package  
 (SO-16)  
 ISSUE O

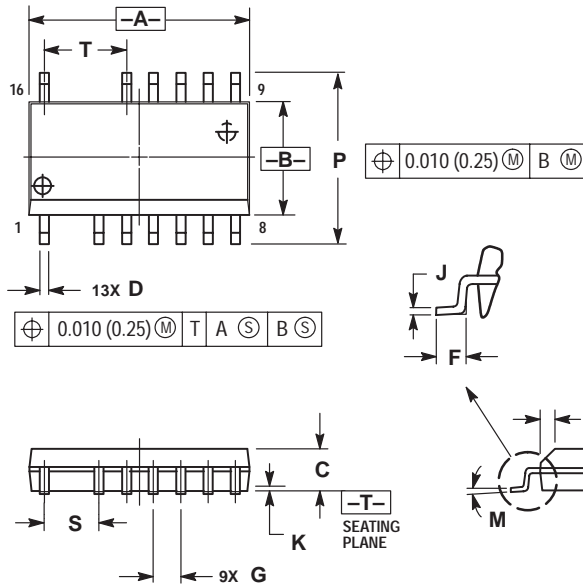
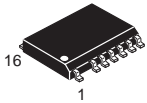


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.368	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

**DW SUFFIX**  
**CASE 751N-01**  
 Plastic Package  
 (SOP-16L)  
 ISSUE O

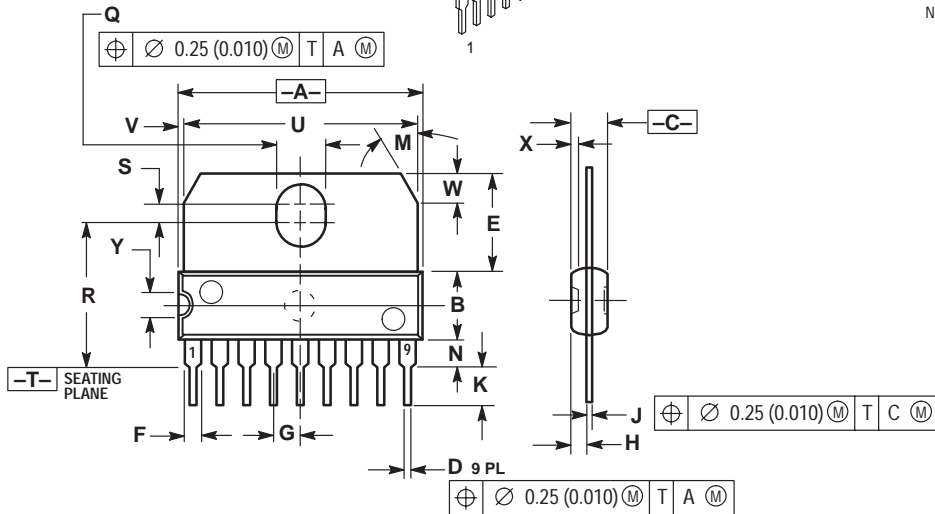
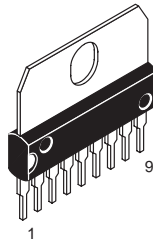


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.15	10.45	0.400	0.411
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029
S	2.54 BSC		0.100 BSC	
T	3.81 BSC		0.150 BSC	

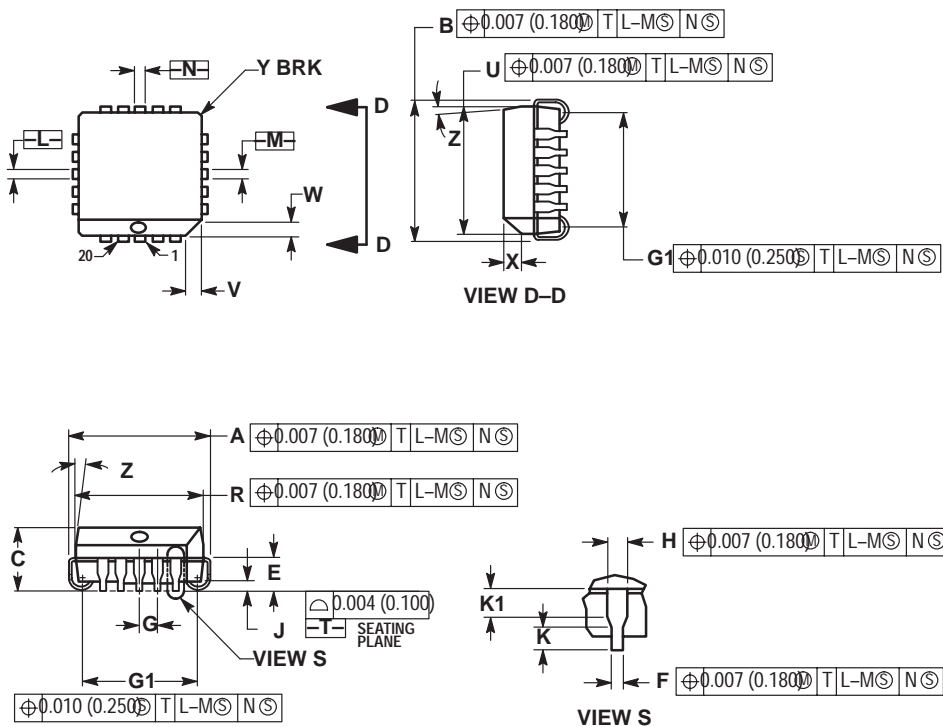
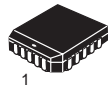
**CASE 762-01**  
 Plastic Medium Power Package  
 (SIP-9)  
 ISSUE C



- NOTES:  
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5, 1982.  
 2. CONTROLLING DIMENSION: MILLIMETER.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	22.40	23.00	0.873	0.897
B	6.40	6.60	0.252	0.260
C	3.45	3.65	0.135	1.143
D	0.40	0.55	0.015	0.021
E	9.35	9.60	0.368	0.377
F	1.40	1.60	0.055	0.062
G	2.54 BSC		0.100 BSC	
H	1.51	1.71	0.059	0.067
J	0.360	0.400	0.014	0.015
K	3.95	4.20	0.155	0.165
M	30° BSC		30° BSC	
N	2.50	2.70	0.099	0.106
Q	3.15	3.45	0.124	0.135
R	13.60	13.90	0.535	0.547
S	1.65	1.95	0.064	0.076
U	22.00	22.20	0.866	0.874
V	0.55	0.75	0.021	0.029
W	2.89 BSC		0.113 BSC	
X	0.65	0.75	0.025	0.029
Y	2.70	2.80	0.106	0.110

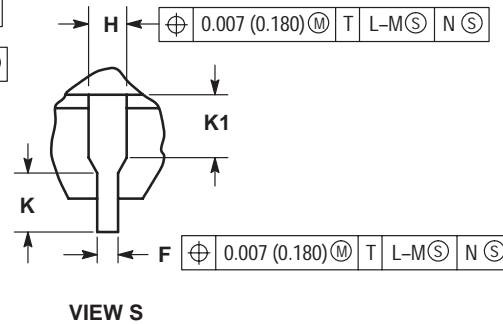
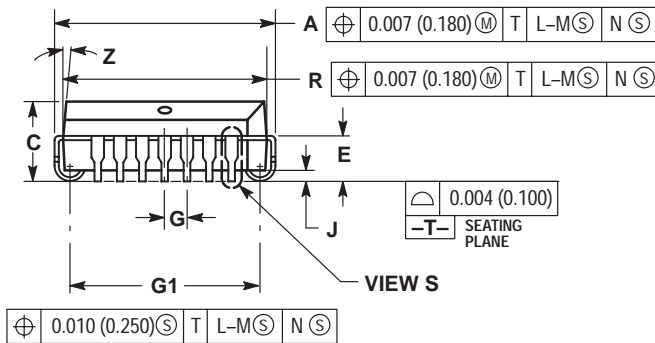
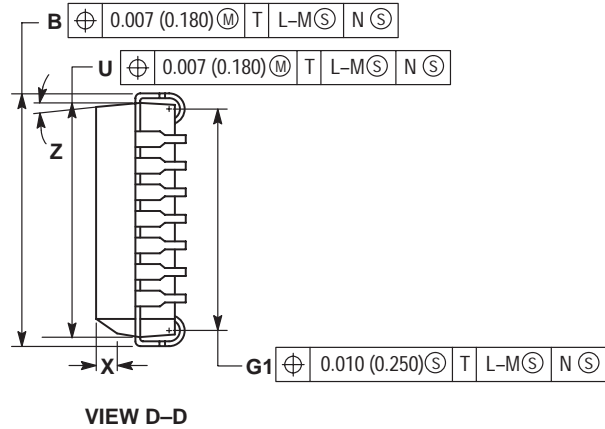
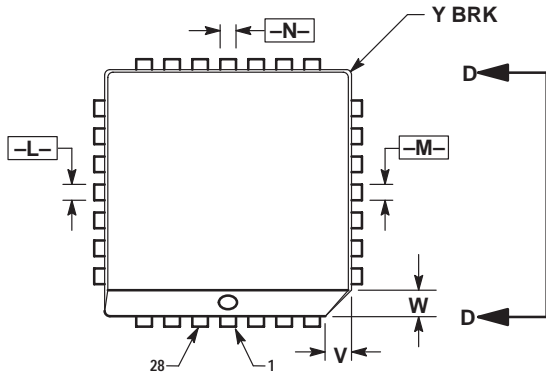
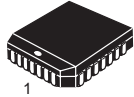
**FN SUFFIX**  
**CASE 775-02**  
 Plastic Package  
 (PLCC-20)  
 ISSUE C



- NOTES:  
 1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.  
 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.  
 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.  
 4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.  
 5. CONTROLLING DIMENSION: INCH.  
 6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.  
 7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.385	0.395	9.78	10.03
B	0.385	0.395	9.78	10.03
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2°	10°	---	10°
G1	0.310	0.330	7.88	8.38
K1	0.040	---	1.02	---

**FN SUFFIX**  
**CASE 776-02**  
 Plastic Package  
 (PLCC-28)  
 ISSUE D

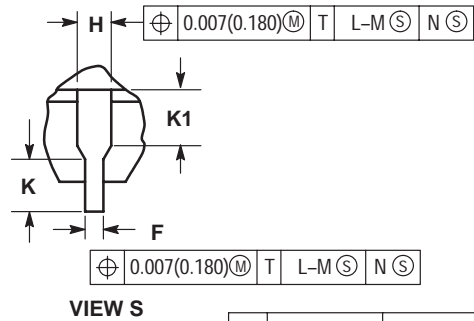
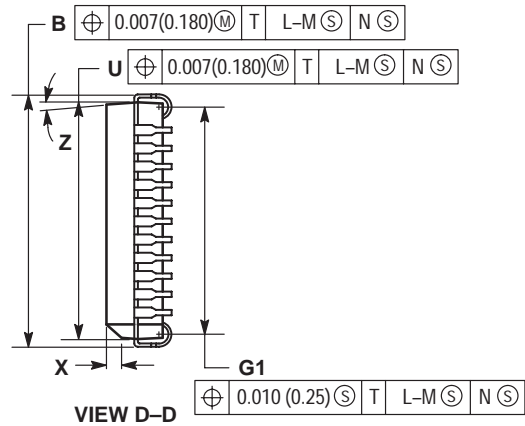
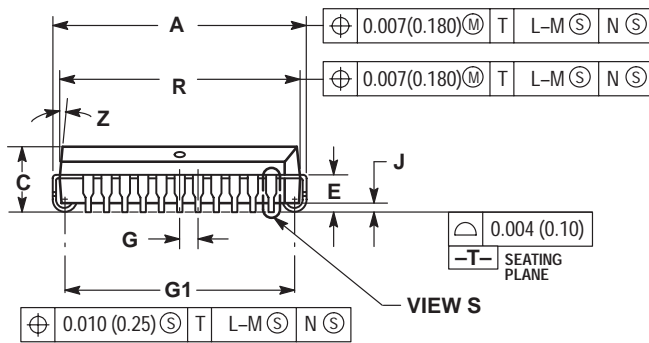
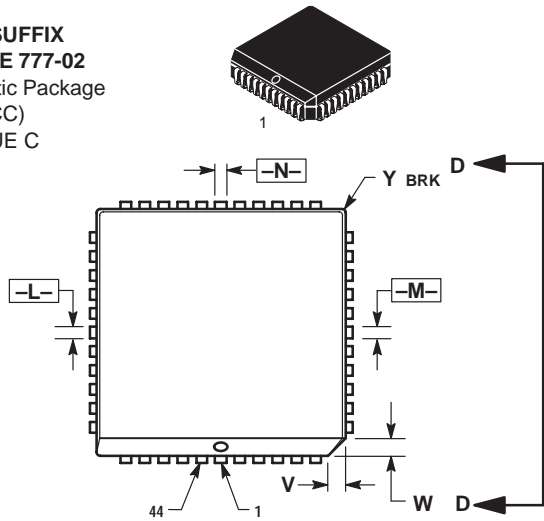


**NOTES:**

- DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
- DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
- DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.485	0.495	12.32	12.57
B	0.485	0.495	12.32	12.57
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.450	0.456	11.43	11.58
U	0.450	0.456	11.43	11.58
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2°	10°	2°	10°
G1	0.410	0.430	10.42	10.92
K1	0.040	---	1.02	---

**FN SUFFIX**  
**CASE 777-02**  
 Plastic Package  
 (PLCC)  
 ISSUE C

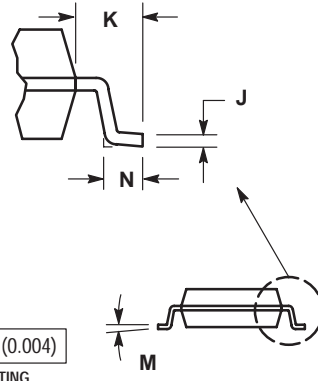
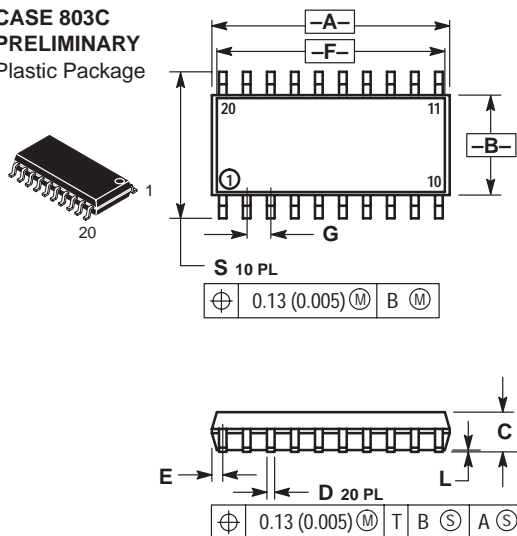


- NOTES:
- DATUMS -L-, -M-, AND -N- ARE DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
  - DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
  - DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.25) PER SIDE.
  - DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  - CONTROLLING DIMENSION: INCH.

- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.685	0.695	17.40	17.65
B	0.685	0.695	17.40	17.65
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.650	0.656	16.51	16.66
U	0.650	0.656	16.51	16.66
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2°	10°	2°	10°
G1	0.610	0.630	15.50	16.00
K1	0.040	---	1.02	---

**M SUFFIX**  
**CASE 803C**  
 PRELIMINARY  
 Plastic Package

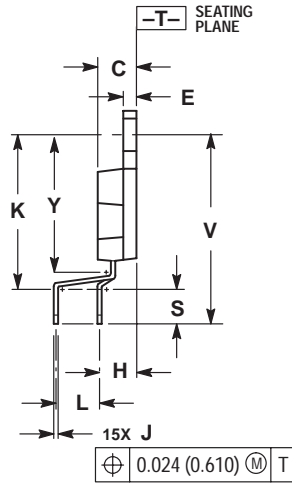
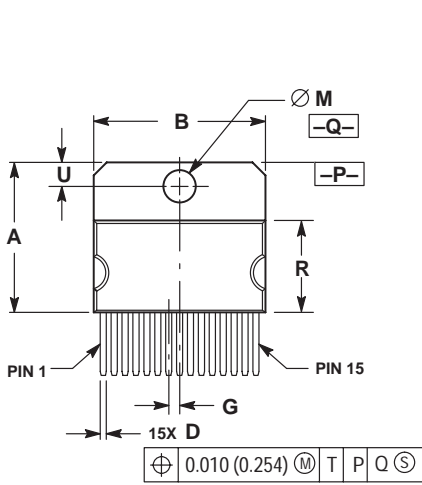
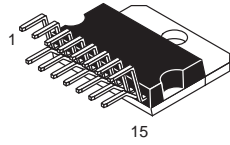


- NOTES:
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  - CONTROLLING DIMENSION: MILLIMETER.
  - DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
  - MAXIMUM MOLD PROTRUSION 0.15 (0.008) PER SIDE.
  - DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.006) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	12.35	12.80	0.486	0.504
B	5.10	5.45	0.201	0.215
C	1.95	2.05	0.077	0.081
D	0.35	0.50	0.014	0.020
E	---	0.81	---	0.032
F	12.40*		0.488*	
G	1.15	1.39	0.045	0.055
H	0.59	0.81	0.023	0.032
J	0.18	0.27	0.007	0.011
K	1.10	1.50	0.043	0.059
L	0.05	0.20	0.001	0.008
M	0°	10°	0°	10°
N	0.50	0.85	0.020	0.033
S	7.40	8.20	0.291	0.323

\*APPROXIMATE

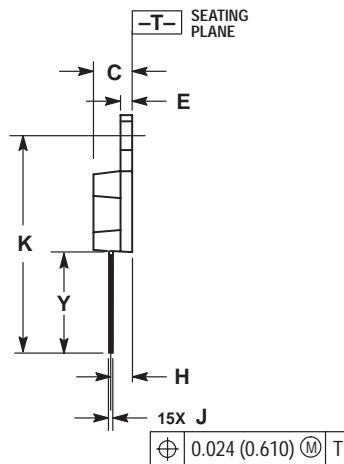
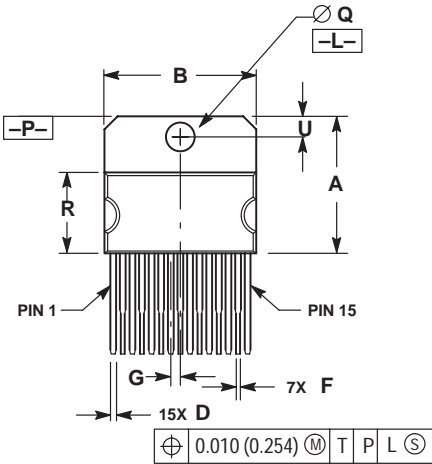
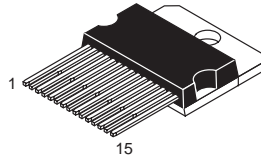
**TV SUFFIX**  
**CASE 821C-04**  
 Plastic Package  
 (15-Pin ZIP)  
 ISSUE D



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION R DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
  5. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.010 (0.250).
  6. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.003 (0.076) TOTAL IN EXCESS OF THE D DIMENSION, AT MAXIMUM MATERIAL CONDITION.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.684	0.694	17.374	17.627
B	0.784	0.792	19.914	20.116
C	0.173	0.181	4.395	4.597
D	0.024	0.031	0.610	0.787
E	0.058	0.062	1.473	1.574
G	0.050 BSC		1.270 BSC	
H	0.169 BSC		4.293 BSC	
J	0.018	0.024	0.458	0.609
K	0.700	0.710	17.780	18.034
L	0.200 BSC		5.080 BSC	
M	0.148	0.151	3.760	3.835
R	0.416	0.426	10.567	10.820
S	0.157	0.167	3.988	4.242
U	0.105	0.115	2.667	2.921
V	0.868 REF		22.047 REF	
Y	0.625	0.639	15.875	16.231

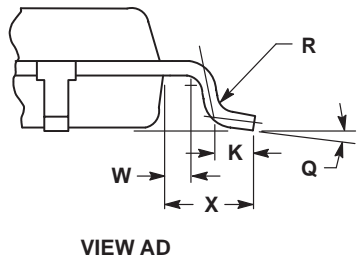
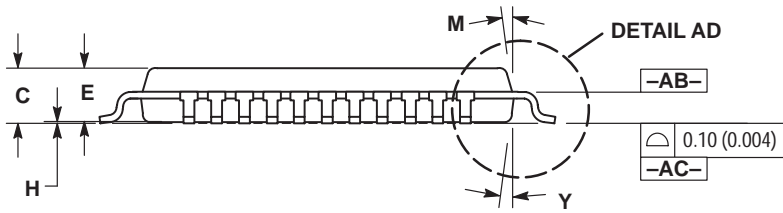
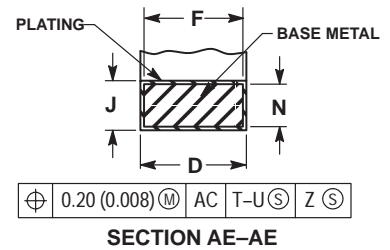
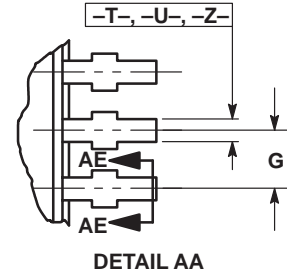
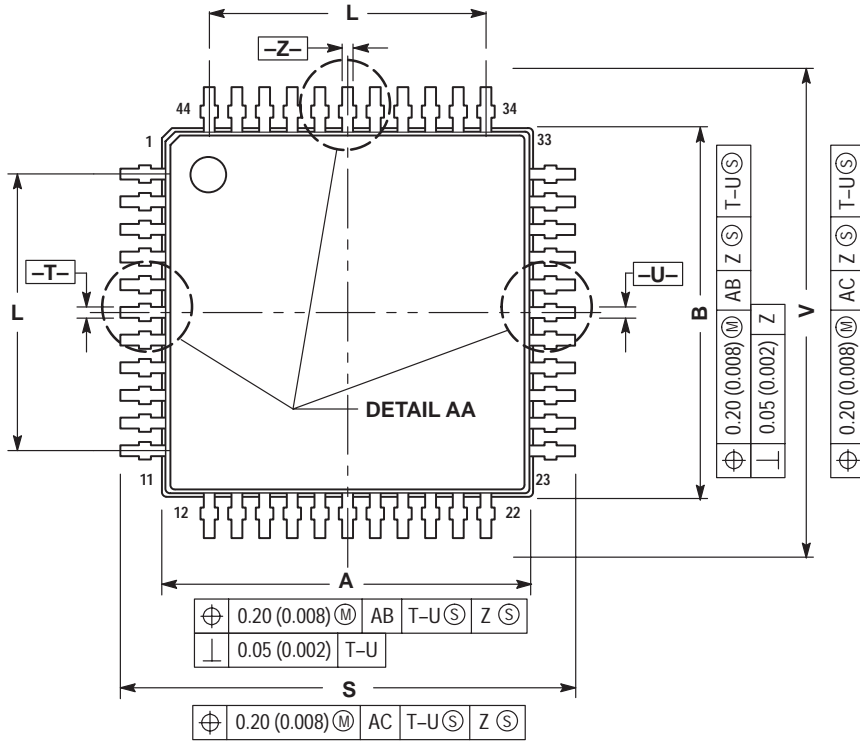
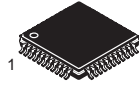
**T SUFFIX**  
**CASE 821D-03**  
 Plastic Package  
 ISSUE C



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION R DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
  5. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.010 (0.250).
  6. DELETED
  7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.003 (0.076) TOTAL IN EXCESS OF THE D DIMENSION, AT MAXIMUM MATERIAL CONDITION.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.681	0.694	17.298	17.627
B	0.784	0.792	19.914	20.116
C	0.173	0.181	4.395	4.597
D	0.024	0.031	0.610	0.787
E	0.058	0.062	1.473	1.574
F	0.016	0.023	0.407	0.584
G	0.050 BSC		1.270 BSC	
H	0.110 BSC		2.794 BSC	
J	0.018	0.024	0.458	0.609
K	1.078	1.086	27.382	27.584
Q	0.148	0.151	3.760	3.835
R	0.416	0.426	10.567	10.820
U	0.110 BSC		2.794 BSC	
Y	0.503 REF		12.776 REF	

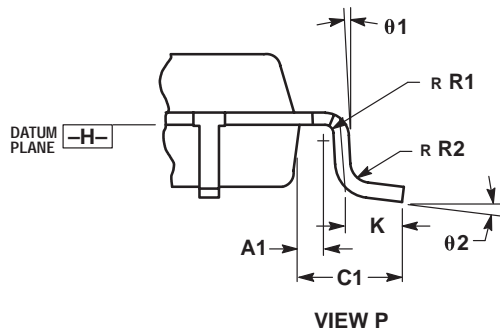
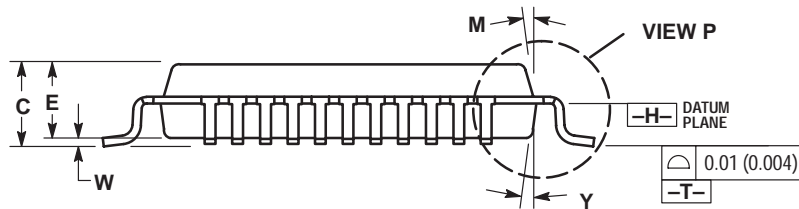
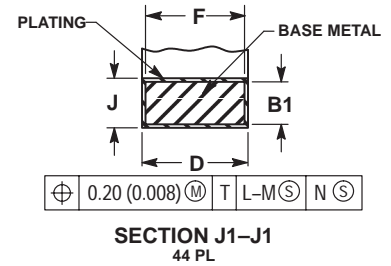
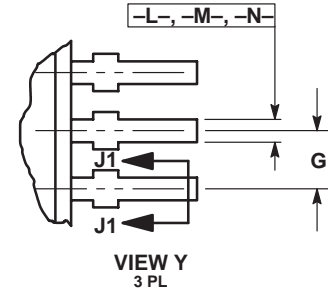
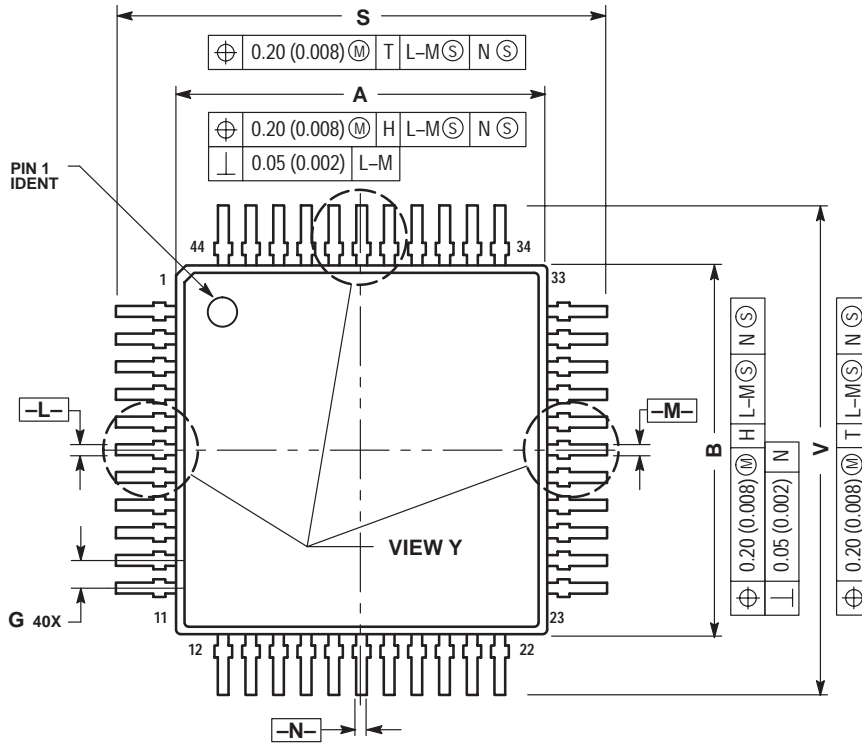
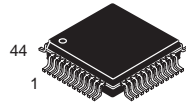
**FTB SUFFIX**  
**CASE 824D-01**  
 Plastic Package  
 (TQFP-44)  
 ISSUE O



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
  4. DATUMS -T-, -U- AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-.
  5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -AC-.
  6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
  7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.530 (0.021).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.950	10.050	0.392	0.396
B	9.950	10.050	0.392	0.396
C	1.400	1.600	0.055	0.063
D	0.300	0.450	0.012	0.018
E	1.350	1.450	0.053	0.057
F	0.300	0.400	0.012	0.016
G	0.800 BSC		0.031 BSC	
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.450	0.550	0.018	0.022
L	8.000 BSC		0.315 BSC	
M	12° REF		12° REF	
N	0.090	0.160	0.004	0.006
Q	1°	5°	1°	5°
R	0.100	0.200	0.004	0.008
S	11.900	12.100	0.469	0.476
V	11.900	12.100	0.469	0.476
W	0.200 REF		0.008 REF	
X	1.000 REF		0.039 REF	
Y	12° REF		12° REF	

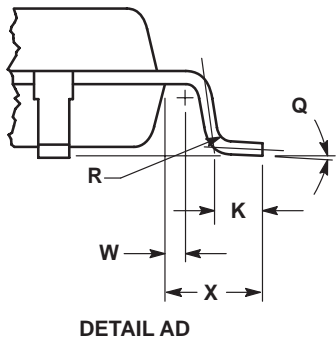
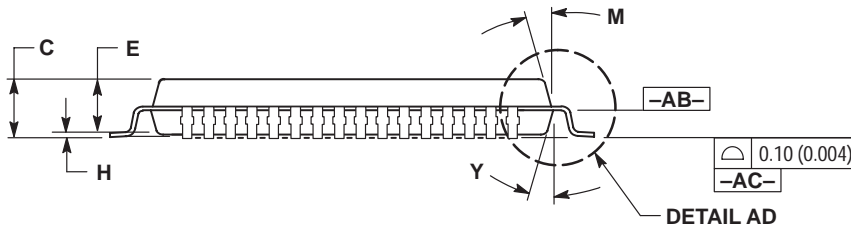
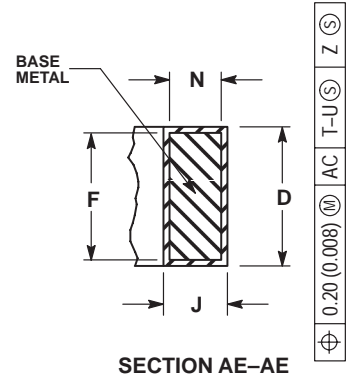
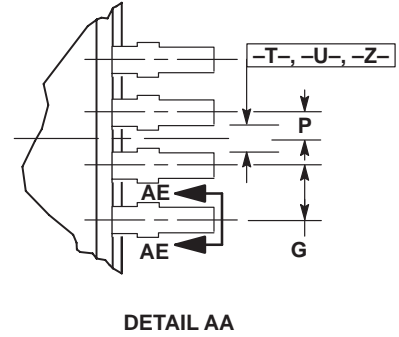
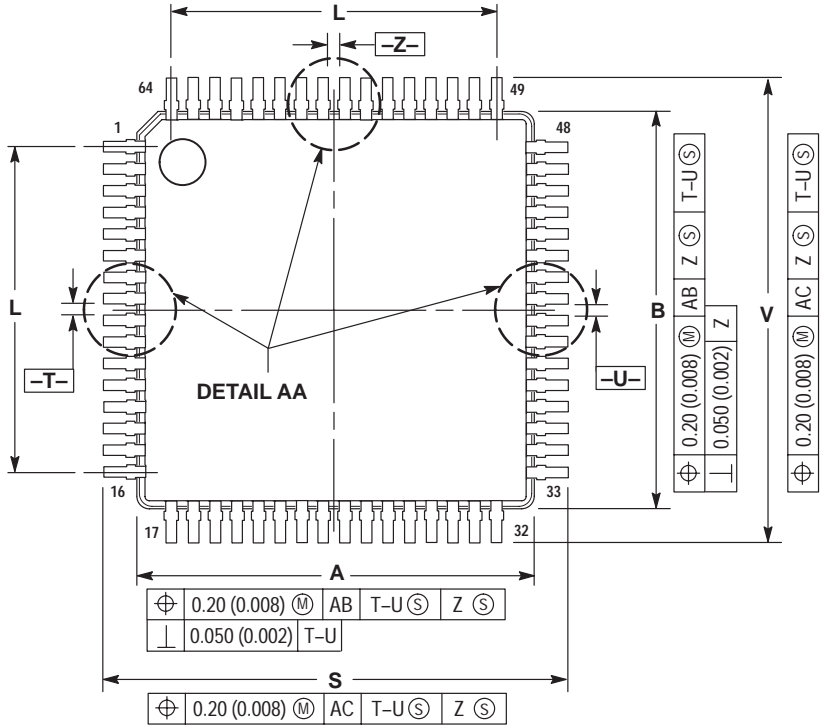
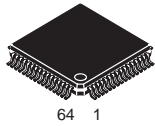
**FB SUFFIX**  
**CASE 824E-02**  
 Plastic Package  
 (QFP)  
 ISSUE A



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
  4. DATUMS -L-, -M- AND -N- TO BE DETERMINED AT DATUM PLANE -H-.
  5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -T-.
  6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
  7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.530 (0.021).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.90	10.10	0.390	0.398
B	9.90	10.10	0.390	0.398
C	2.00	2.21	0.079	0.087
D	0.30	0.45	0.0118	0.0177
E	2.00	2.10	0.079	0.083
F	0.30	0.40	0.012	0.016
G	0.80 BSC		0.031 BSC	
J	0.13	0.23	0.005	0.009
K	0.65	0.95	0.026	0.037
M	5° 10°		5° 10°	
S	12.95	13.45	0.510	0.530
V	12.95	13.45	0.510	0.530
W	0.000	0.210	0.000	0.008
Y	5° 10°		5° 10°	
A1	0.450 REF		0.018 REF	
B1	0.130	0.170	0.005	0.007
C1	1.600 REF		0.063 REF	
R1	0.130	0.300	0.005	0.012
R2	0.130	0.300	0.005	0.012
$\theta 1$	5° 10°		5° 10°	
$\theta 2$	0° 7°		0° 7°	

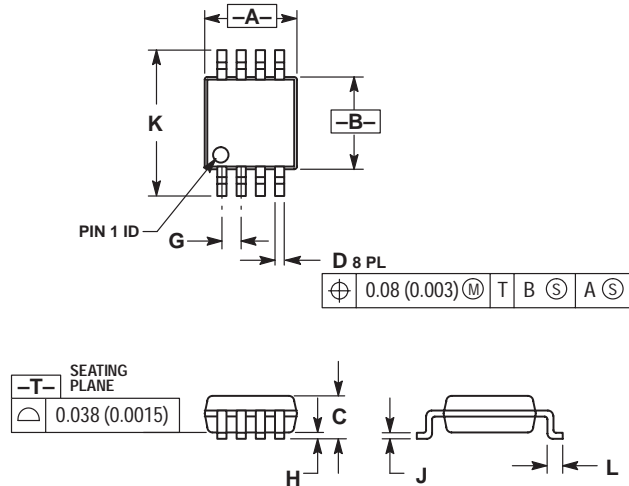
**FB SUFFIX**  
**CASE 840F-01**  
 Plastic Package  
 ISSUE O



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
  4. DATUMS -T-, -U- AND -Z- TO BE DETERMINED AT DATUM PLANE -AC-.
  5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -AC-.
  6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
  7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.350 (0.014).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.950	10.050	0.392	0.396
B	9.950	10.050	0.392	0.396
C	1.400	1.600	0.055	0.063
D	0.170	0.270	0.007	0.011
E	1.350	1.450	0.053	0.057
F	0.170	0.230	0.007	0.009
G	0.500 BSC		0.020 BSC	
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.450	0.550	0.018	0.022
L	7.500 BSC		0.295 BSC	
M	12° REF		12° REF	
N	0.090	0.160	0.004	0.006
P	0.250 BSC		0.010 BSC	
Q	1°	5°	1°	5°
R	0.100	0.200	0.004	0.008
S	11.900	12.100	0.469	0.476
V	11.900	12.100	0.469	0.476
W	0.200 REF		0.008 REF	
X	1.000 REF		0.039 REF	
Y	12° REF		12° REF	

**DM SUFFIX**  
**CASE 846A-02**  
 Plastic Package  
 (Micro-8)  
 ISSUE C

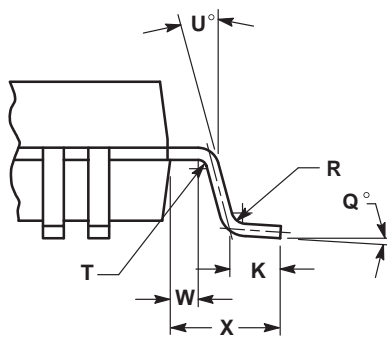
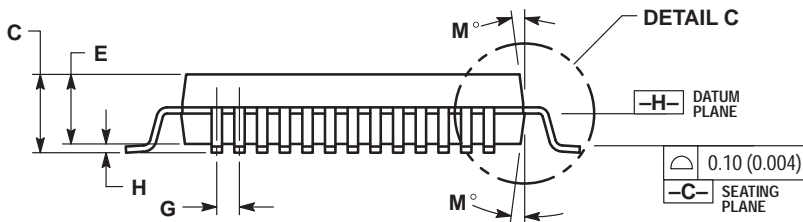
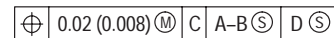
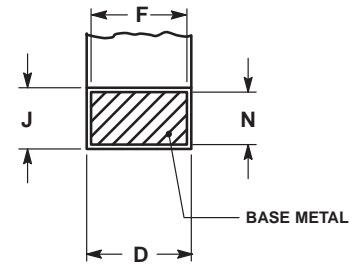
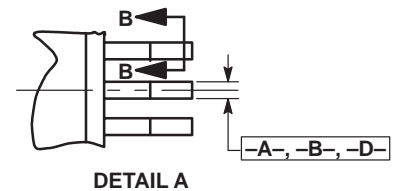
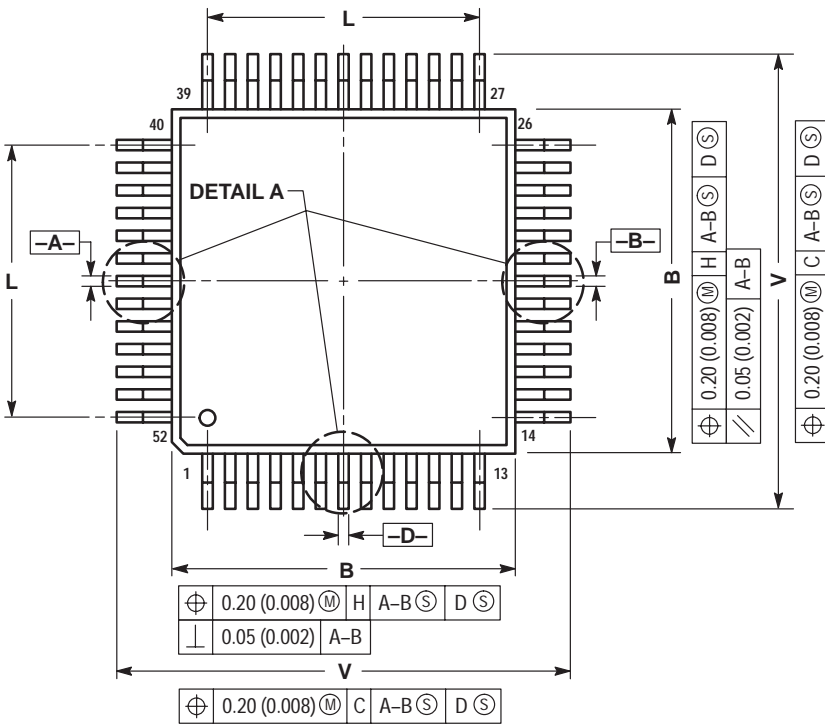
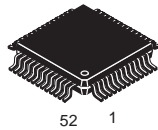


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	---	1.10	---	0.043
D	0.25	0.40	0.010	0.016
G	0.65 BSC		0.026 BSC	
H	0.05	0.15	0.002	0.006
J	0.13	0.23	0.005	0.009
K	4.75	5.05	0.187	0.199
L	0.40	0.70	0.016	0.028

**FB SUFFIX**  
**CASE 848B-04**  
 Plastic Package  
 (TQFP-52)  
 ISSUE C

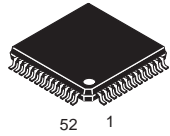


**NOTES:**

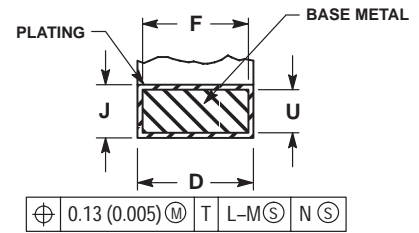
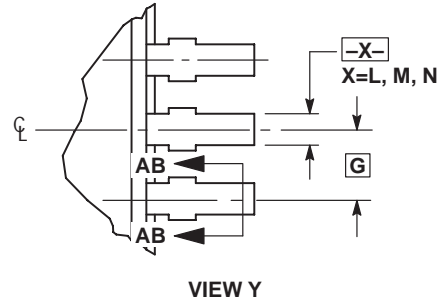
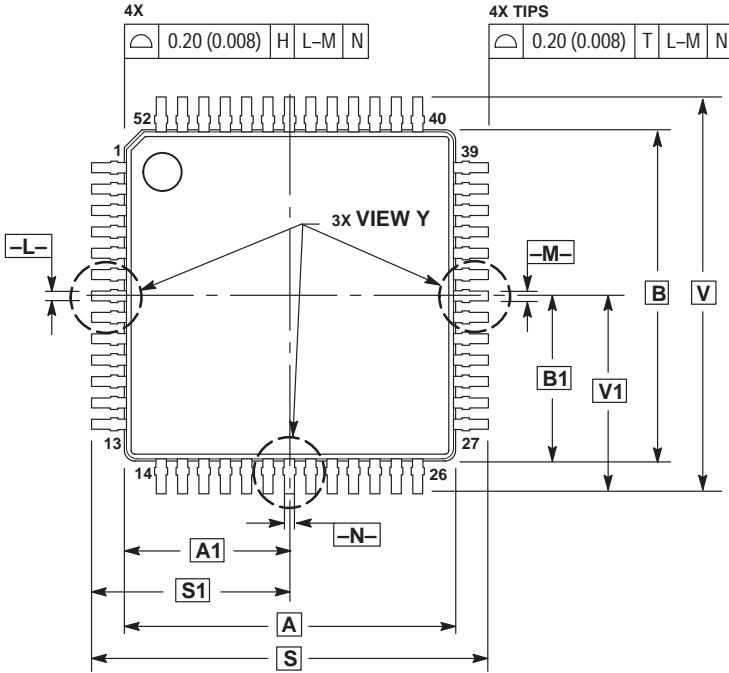
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
- DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
- DATUMS -A-, -B- AND -D- TO BE DETERMINED AT DATUM PLANE -H-.
- DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -C-.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.90	10.10	0.390	0.398
B	9.90	10.10	0.390	0.398
C	2.10	2.45	0.083	0.096
D	0.22	0.38	0.009	0.015
E	2.00	2.10	0.079	0.083
F	0.22	0.33	0.009	0.013
G	0.65 BSC		0.026 BSC	
H	---	0.25	---	0.010
J	0.13	0.23	0.005	0.009
K	0.65	0.95	0.026	0.037
L	7.80 REF		0.307 REF	
M	5°	10°	5°	10°
N	0.13	0.17	0.005	0.007
Q	0°	7°	0°	7°
R	0.13	0.30	0.005	0.012
S	12.95	13.45	0.510	0.530
T	0.13	---	0.005	---
U	0°	---	0°	---
V	12.95	13.45	0.510	0.530
W	0.35	0.45	0.014	0.018
X	1.6 REF		0.063 REF	

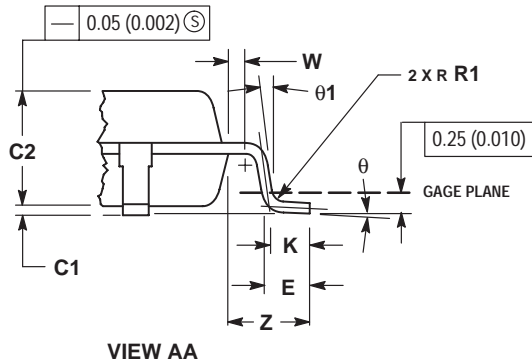
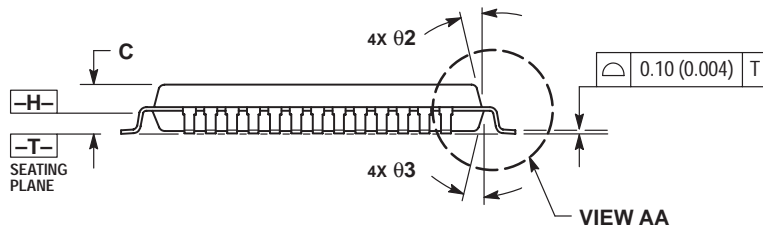
**FB SUFFIX**  
**CASE 848D-03**  
 Plastic Package  
 ISSUE C



52 1



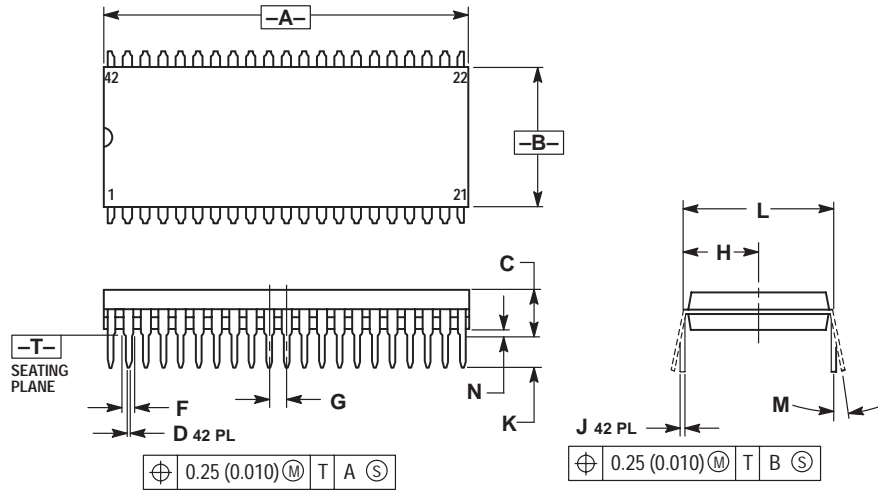
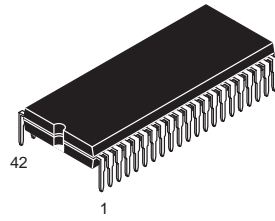
**SECTION AB-AB**  
 ROTATED 90° CLOCKWISE



- NOTES:**
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
  4. DATUMS -L-, -M- AND -N- TO BE DETERMINED AT DATUM PLANE -H-.
  5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -T-.
  6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO NOT INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
  7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.46 (0.018). MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07 (0.003).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.00 BSC	0.394 BSC		
A1	5.00 BSC	0.197 BSC		
B	10.00 BSC	0.394 BSC		
B1	5.00 BSC	0.197 BSC		
C	---	1.70	---	0.067
C1	0.05	0.20	0.002	0.008
C2	1.30	1.50	0.051	0.059
D	0.20	0.40	0.008	0.016
E	0.45	0.75	0.018	0.030
F	0.22	0.35	0.009	0.014
G	0.65 BSC	0.026 BSC		
J	0.07	0.20	0.003	0.008
K	0.50 REF	0.020 REF		
R1	0.08	0.20	0.003	0.008
S	12.00 BSC	0.472 BSC		
S1	6.00 BSC	0.236 BSC		
U	0.09	0.16	0.004	0.006
V	12.00 BSC	0.472 BSC		
V1	6.00 BSC	0.236 BSC		
W	0.20 REF	0.008 REF		
Z	1.00 REF	0.039 REF		
θ	0°	7°	0°	7°
θ1	0°	---	0°	---
θ2	12° REF	12° REF		
θ3	5°	13°	5°	13°

**B SUFFIX**  
**CASE 858-01**  
 Plastic Package  
 ISSUE O

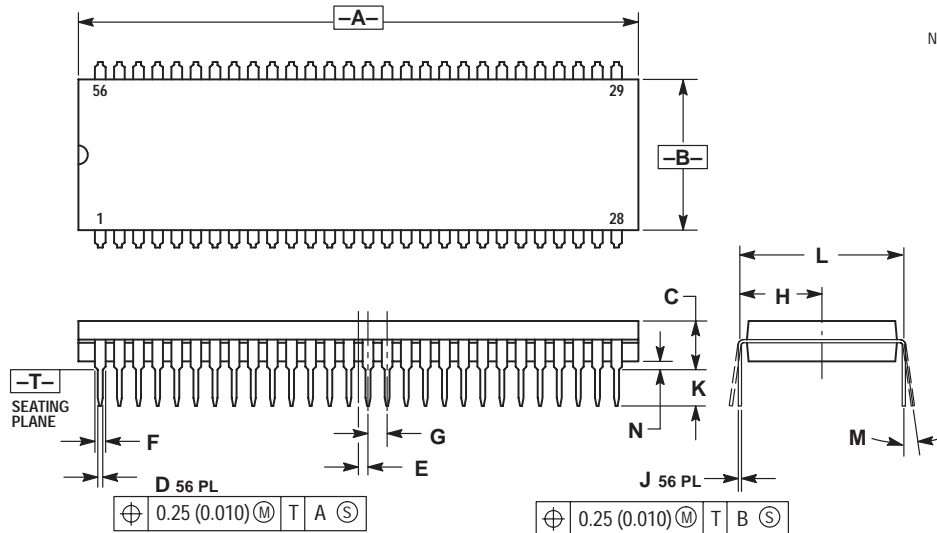
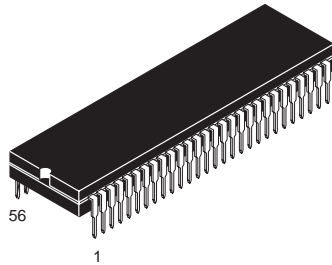


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH. MAXIMUM MOLD FLASH 0.25 (0.010).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.435	1.465	36.45	37.21
B	0.540	0.560	13.72	14.22
C	0.155	0.200	3.94	5.08
D	0.014	0.022	0.36	0.56
F	0.032	0.046	0.81	1.17
G	0.070 BSC		1.778 BSC	
H	0.300 BSC		7.62 BSC	
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.600 BSC		15.24 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.02

**B SUFFIX**  
**CASE 859-01**  
 Plastic Package  
 (SDIP)  
 ISSUE O

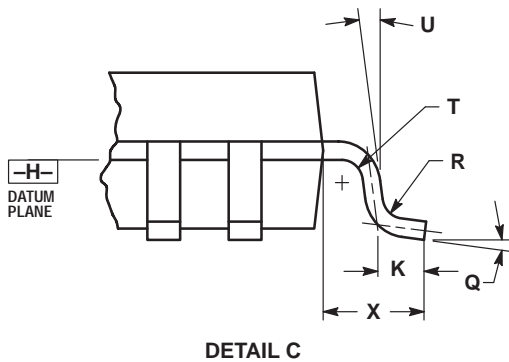
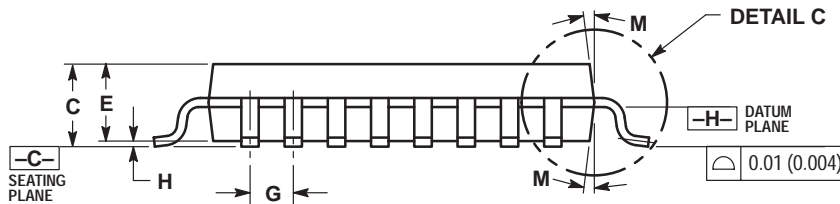
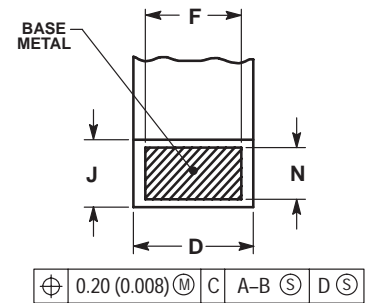
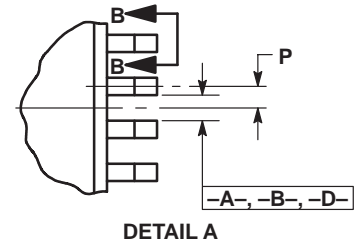
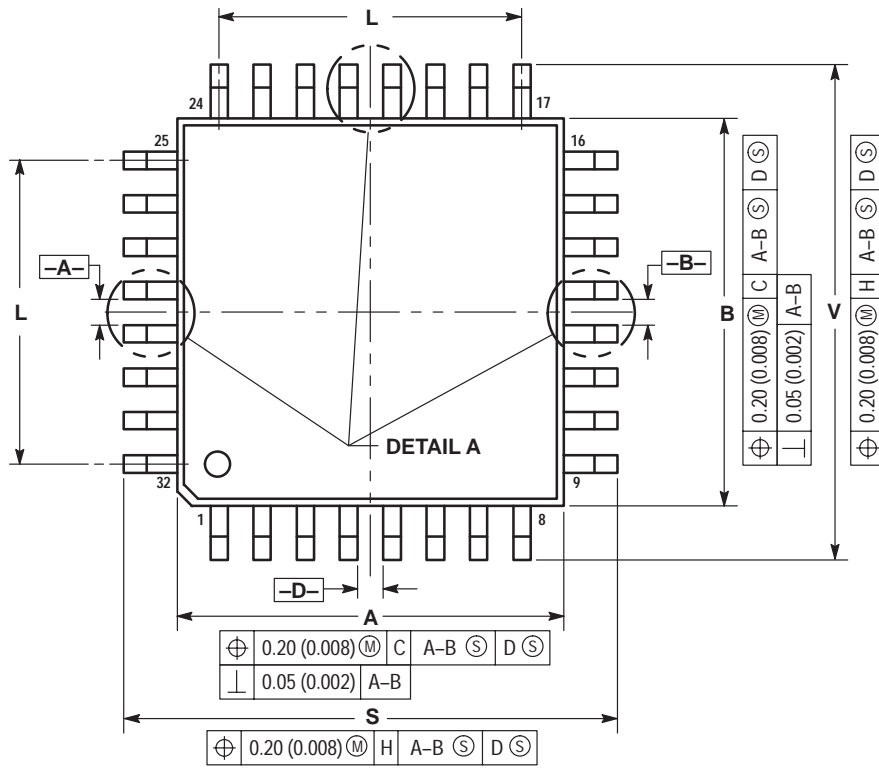
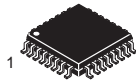


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH. MAXIMUM MOLD FLASH 0.25 (0.010)

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	2.035	2.065	51.69	52.45
B	0.540	0.560	13.72	14.22
C	0.155	0.200	3.94	5.08
D	0.014	0.022	0.36	0.56
E	0.035 BSC		0.89 BSC	
F	0.032	0.046	0.81	1.17
G	0.070 BSC		1.778 BSC	
H	0.300 BSC		7.62 BSC	
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.600 BSC		15.24 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.02

**FB, FTB SUFFIX**  
**CASE 873-01**  
 Plastic Package  
 (TQFP-32)  
 ISSUE A

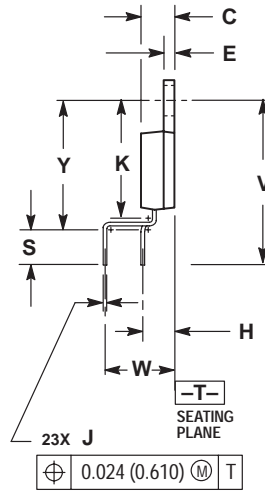
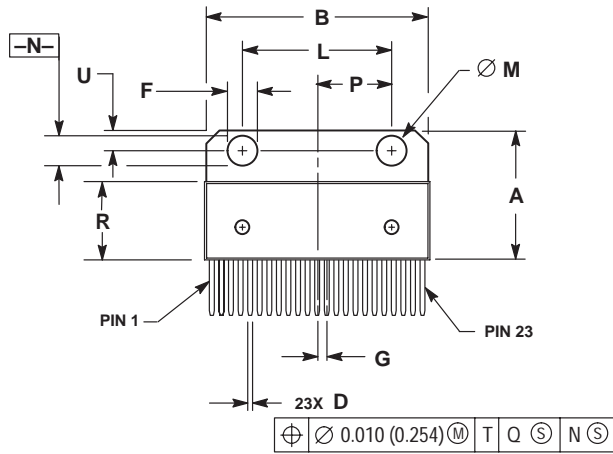
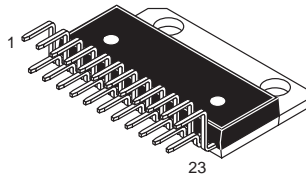


**NOTES:**

- DIMENSION AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
- DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
- DATUMS -A-, -B- AND -D- TO BE DETERMINED AT DATUM PLANE -H-.
- DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -C-.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.95	7.10	0.274	0.280
B	6.95	7.10	0.274	0.280
C	1.40	1.60	0.055	0.063
D	0.273	0.373	0.010	0.015
E	1.30	1.50	0.051	0.059
F	0.273	---	0.010	---
G	0.80 BSC	---	0.031 BSC	---
H	---	0.20	---	0.008
J	0.119	0.197	0.005	0.008
K	0.33	0.57	0.013	0.022
L	5.6 REF	---	0.220 REF	---
M	6°	8°	6°	8°
N	0.119	0.135	0.005	0.005
P	0.40 BSC	---	0.016 BSC	---
Q	5°	10°	5°	10°
R	0.15	0.25	0.006	0.010
S	8.85	9.15	0.348	0.360
T	0.15	0.25	0.006	0.010
U	5°	11°	5°	11°
V	8.85	9.15	0.348	0.360
X	1.00 REF	---	0.039 REF	---

**T SUFFIX**  
**CASE 894-03**  
 Plastic Package  
 (23-Pin SZIP)  
 ISSUE B

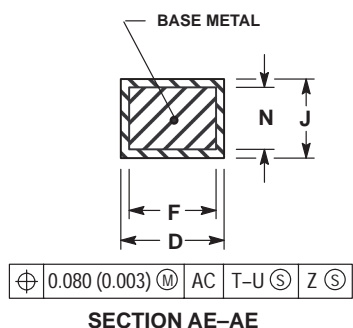
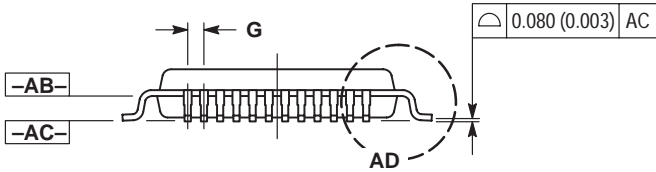
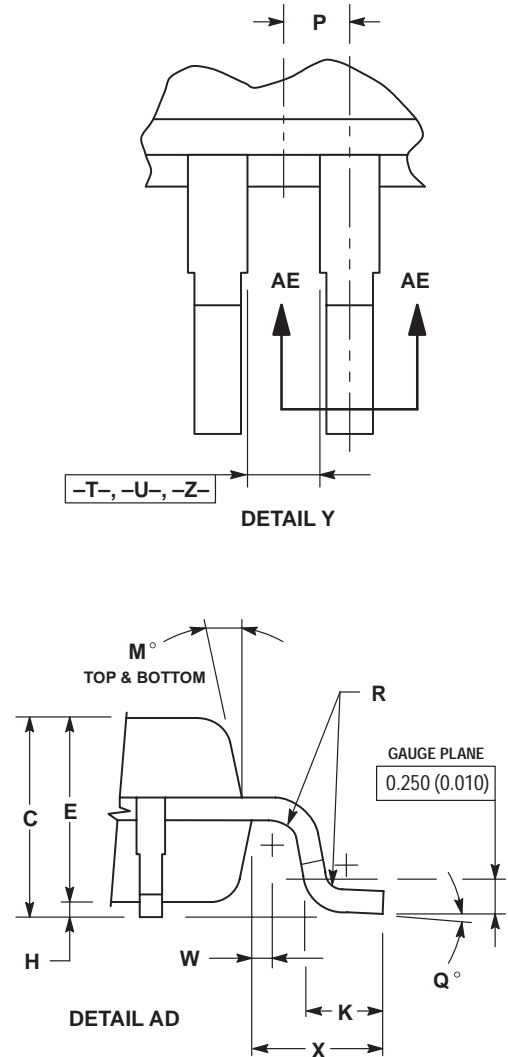
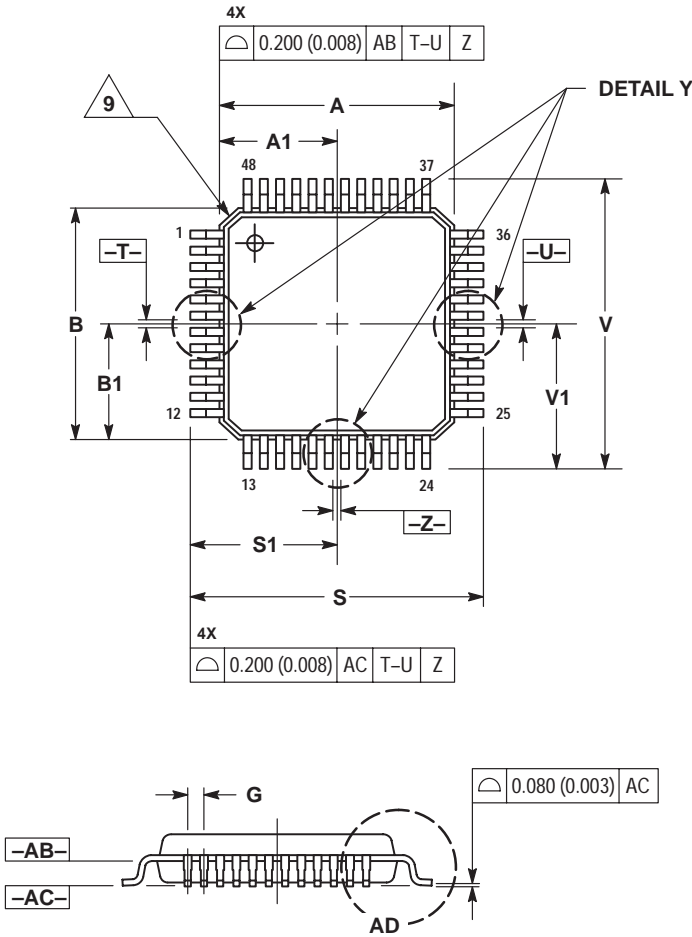
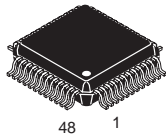


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION R DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
5. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.010 (0.250).
6. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.003 (0.076) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.684	0.694	17.374	17.627
B	1.183	1.193	30.048	30.302
C	0.175	0.179	4.445	4.547
D	0.026	0.031	0.660	0.787
E	0.058	0.062	1.473	1.574
F	0.165	0.175	4.191	4.445
G	0.050 BSC		1.270 BSC	
H	0.169 BSC		4.293 BSC	
J	0.014	0.020	0.356	0.508
K	0.625	0.639	15.875	16.231
L	0.770	0.790	19.558	20.066
M	0.148	0.152	3.760	3.861
N	0.148	0.152	3.760	3.861
P	0.390 BSC		9.906 BSC	
R	0.416	0.424	10.566	10.770
S	0.157	0.167	3.988	4.242
U	0.105	0.115	2.667	2.921
V	0.868 REF		22.047 REF	
W	0.200 BSC		5.080 BSC	
Y	0.700	0.710	17.780	18.034

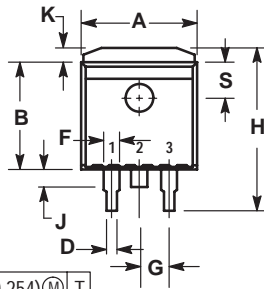
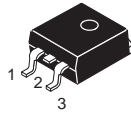
**FTA SUFFIX**  
**CASE 932-02**  
 Plastic Package  
 (TQFP-48)  
 ISSUE D



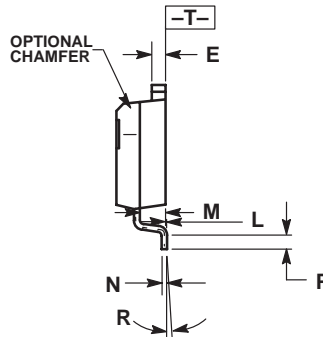
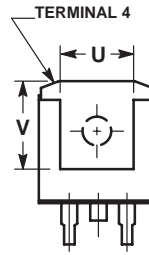
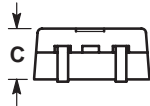
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
  4. DATUMS -T-, -U-, AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-.
  5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -AC-.
  6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B DO NOT INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
  7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.350 (0.014).
  8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076 (0.0003).
  9. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	7.000 BSC		0.276 BSC	
A1	3.500 BSC		0.138 BSC	
B	7.000 BSC		0.276 BSC	
B1	3.500 BSC		0.138 BSC	
C	1.400	1.600	0.055	0.063
D	0.170	0.270	0.007	0.011
E	1.350	1.450	0.053	0.057
F	0.170	0.230	0.007	0.009
G	0.500 BASIC		0.020 BASIC	
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.500	0.700	0.020	0.028
M	12° REF		12° REF	
N	0.090	0.160	0.004	0.006
P	0.250 BASIC		0.010 BASIC	
Q	1°	5°	1°	5°
R	0.150	0.250	0.006	0.010
S	9.000 BSC		0.354 BSC	
S1	4.500 BSC		0.177 BSC	
V	9.000 BSC		0.354 BSC	
V1	4.500 BSC		0.177 BSC	
W	0.200 REF		0.008 REF	
X	1.000 REF		0.039 REF	

**D2T SUFFIX**  
**CASE 936-03**  
 Plastic Package  
 ISSUE B



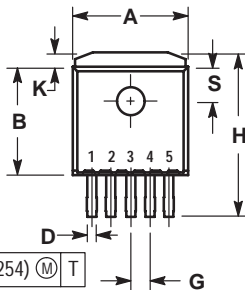
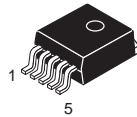
⊕ 0.010 (0.254) Ⓜ T



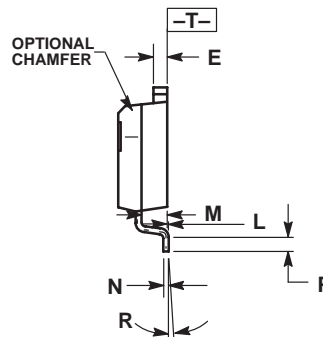
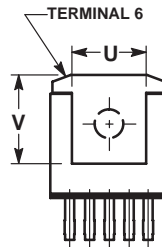
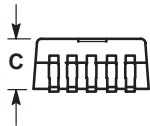
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. TAB CONTOUR OPTIONAL WITHIN DIMENSIONS A AND K.
  4. DIMENSIONS U AND V ESTABLISH A MINIMUM MOUNTING SURFACE FOR TERMINAL 4.
  5. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.025 (0.635) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.386	0.403	9.804	10.236
B	0.356	0.368	9.042	9.347
C	0.170	0.180	4.318	4.572
D	0.026	0.036	0.660	0.914
E	0.045	0.055	1.143	1.397
F	0.051 REF		1.295 REF	
G	0.100 BSC		2.540 BSC	
H	0.539	0.579	13.691	14.707
J	0.125 MAX		3.175 MAX	
K	0.050 REF		1.270 REF	
L	0.000	0.010	0.000	0.254
M	0.088	0.102	2.235	2.591
N	0.018	0.026	0.457	0.660
P	0.058	0.078	1.473	1.981
R	5° REF		5° REF	
S	0.116 REF		2.946 REF	
U	0.200 MIN		5.080 MIN	
V	0.250 MIN		6.350 MIN	

**D2T SUFFIX**  
**CASE 936A-02**  
 Plastic Package  
 (D<sup>2</sup>PAK)  
 ISSUE A



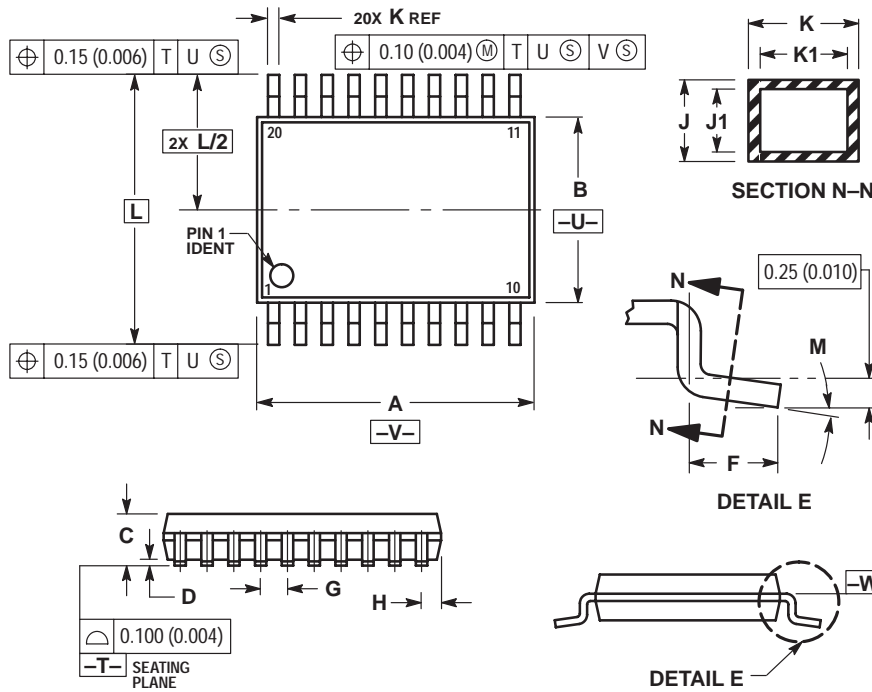
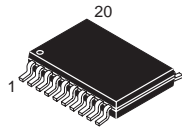
⊕ 0.010 (0.254) Ⓜ T



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. TAB CONTOUR OPTIONAL WITHIN DIMENSIONS A AND K.
  4. DIMENSIONS U AND V ESTABLISH A MINIMUM MOUNTING SURFACE FOR TERMINAL 6.
  5. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.025 (0.635) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.386	0.403	9.804	10.236
B	0.356	0.368	9.042	9.347
C	0.170	0.180	4.318	4.572
D	0.026	0.036	0.660	0.914
E	0.045	0.055	1.143	1.397
G	0.067 BSC		1.702 BSC	
H	0.539	0.579	13.691	14.707
K	0.050 REF		1.270 REF	
L	0.000	0.010	0.000	0.254
M	0.088	0.102	2.235	2.591
N	0.018	0.026	0.457	0.660
P	0.058	0.078	1.473	1.981
R	5° REF		5° REF	
S	0.116 REF		2.946 REF	
U	0.200 MIN		5.080 MIN	
V	0.250 MIN		6.350 MIN	

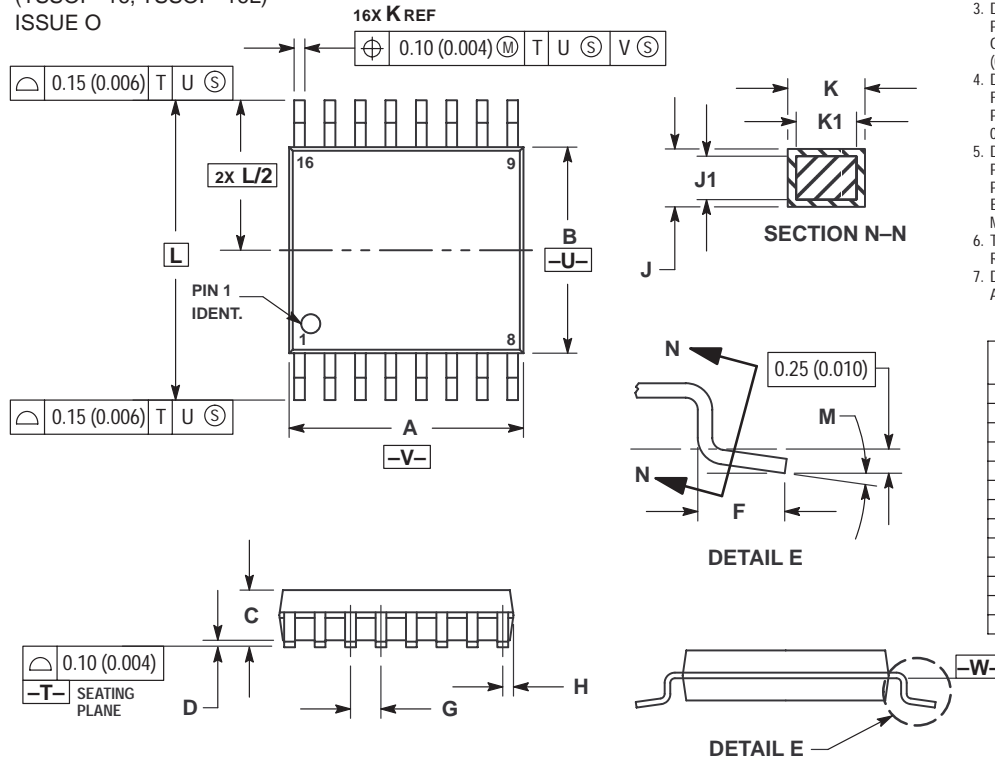
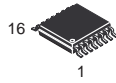
**DT, DTB SUFFIX**  
**CASE 948E-02**  
 Plastic Package  
 (TSSOP-20)  
 ISSUE A



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
  6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.40	6.60	0.252	0.260
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

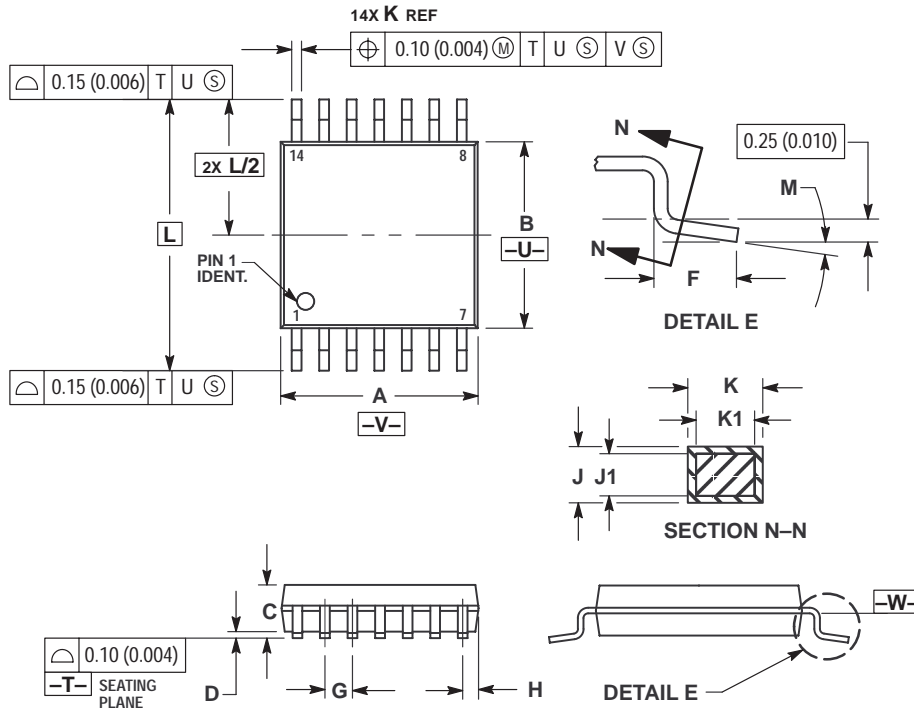
**DTB SUFFIX**  
**CASE 948F-01**  
 Plastic Package  
 (TSSOP-16, TSSOP-16L)  
 ISSUE O



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
  6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

**DTB SUFFIX**  
**CASE 948G-01**  
 Plastic Package  
 (TSSOP-14)  
 ISSUE O

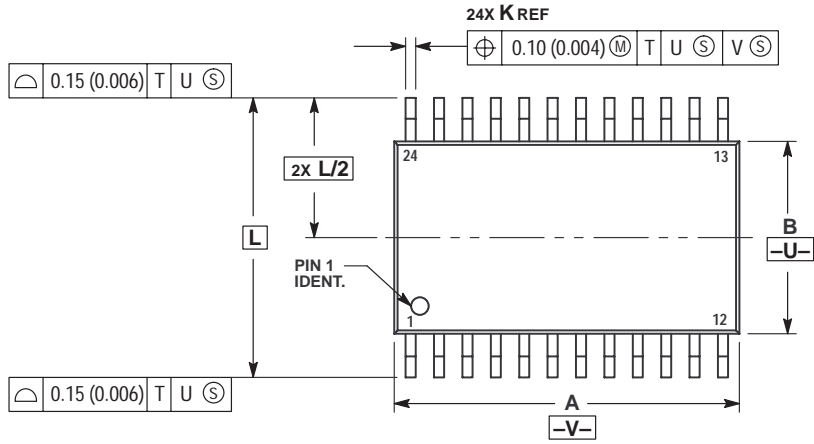
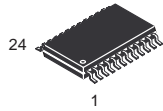


**NOTES:**

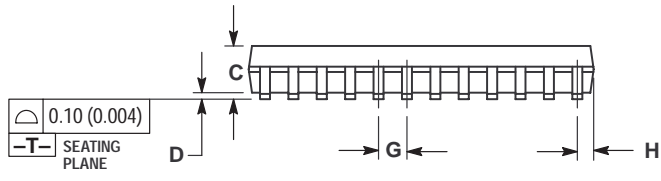
- 1 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2 CONTROLLING DIMENSION: MILLIMETER.
- 3 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- 4 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- 5 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 6 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- 7 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

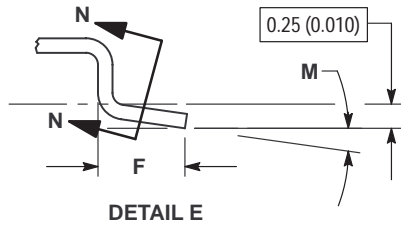
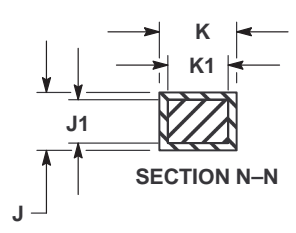
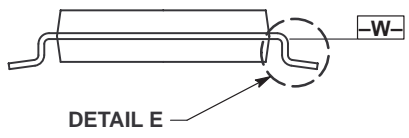
**DTB SUFFIX**  
**CASE 948H-01**  
 Plastic Package  
 ISSUE O



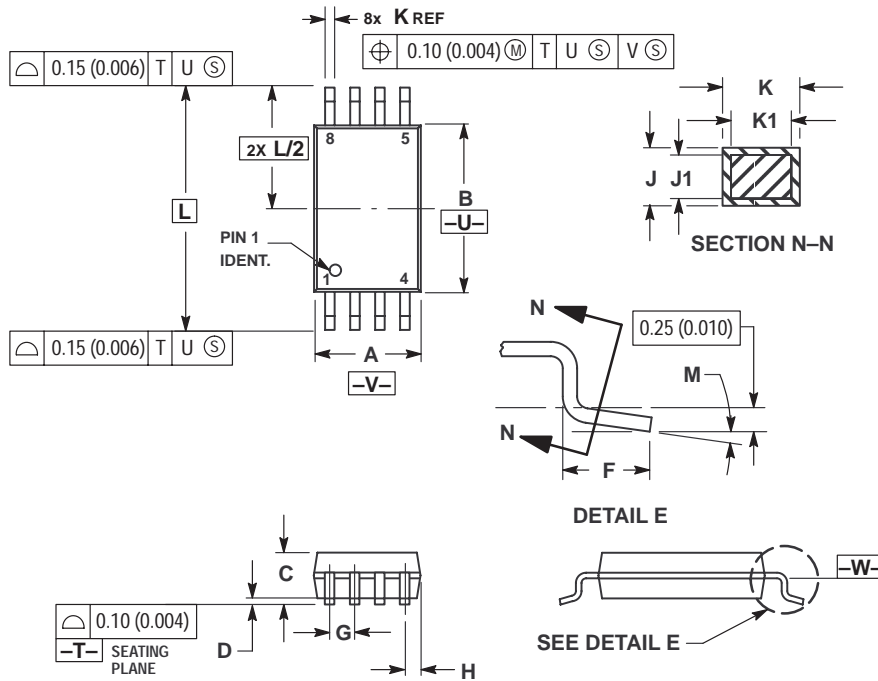
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
  6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	7.70	7.90	0.303	0.311
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°



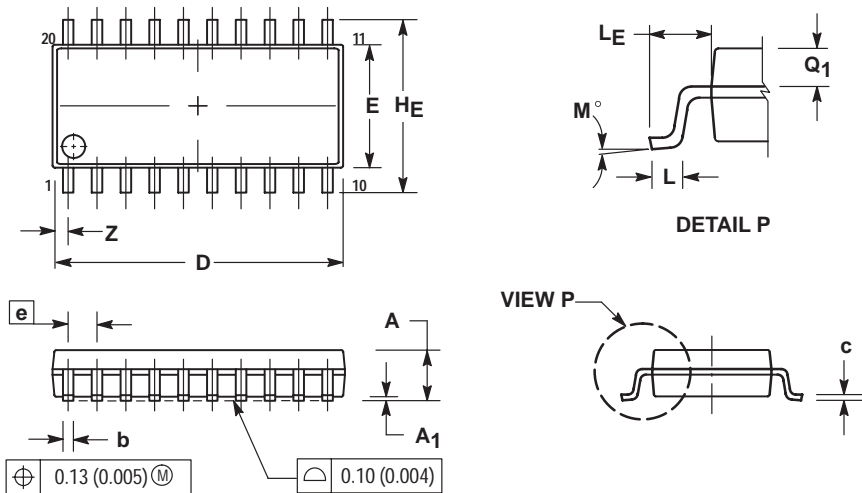
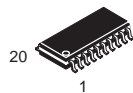
**DTB SUFFIX**  
**CASE 948J-01**  
 Plastic Package  
 (TSSOP-8)  
 ISSUE O



- NOTES:
- 1 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  - 2 CONTROLLING DIMENSION: MILLIMETER.
  - 3 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  - 4 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  - 5 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
  - 6 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  - 7 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

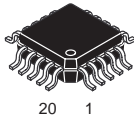
**M SUFFIX**  
**CASE 967-01**  
 Plastic Package  
 (EIAJ-20)  
 ISSUE O



- NOTES:
- 1 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  - 2 CONTROLLING DIMENSION: MILLIMETER.
  - 3 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  - 4 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  - 5 THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	12.35	12.80	0.486	0.504
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q1	0.70	0.90	0.028	0.035
Z	---	0.81	---	0.032

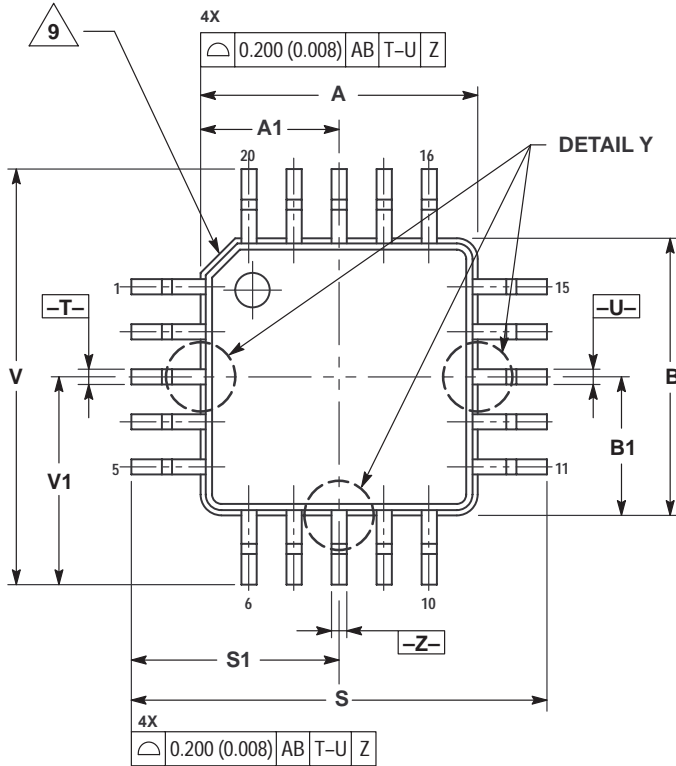
FTB SUFFIX  
CASE 976-01  
Plastic Package  
(TQFP-20)  
ISSUE O



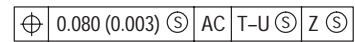
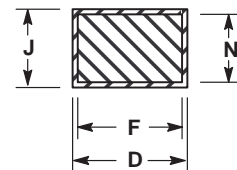
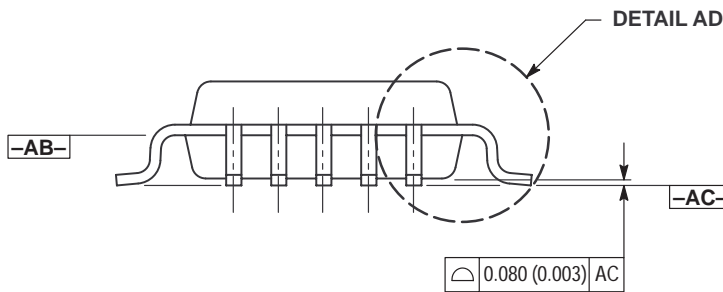
20 1

NOTES:

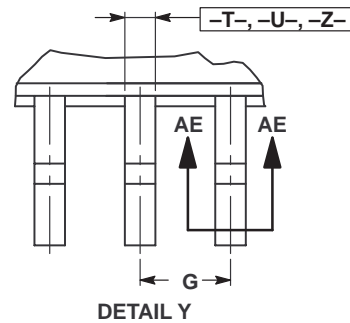
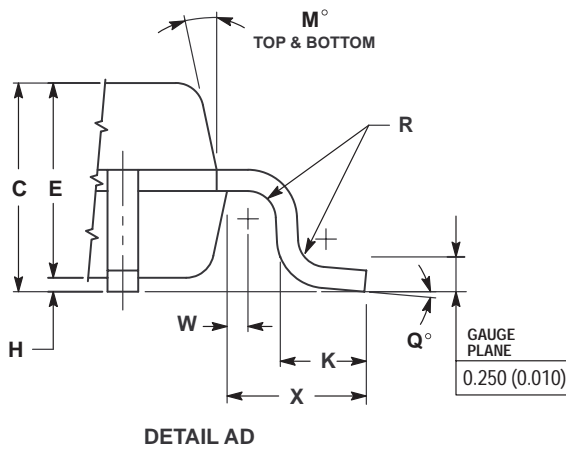
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS -T-, -U-, AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-.
5. DIMENSIONS S AND V TO BE DETERMINED AT DATUM PLANE -AC-.
6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.350 (0.014).
8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076 (0.0003).
9. EXACT SHAPE OF EACH CORNER IS OPTIONAL.



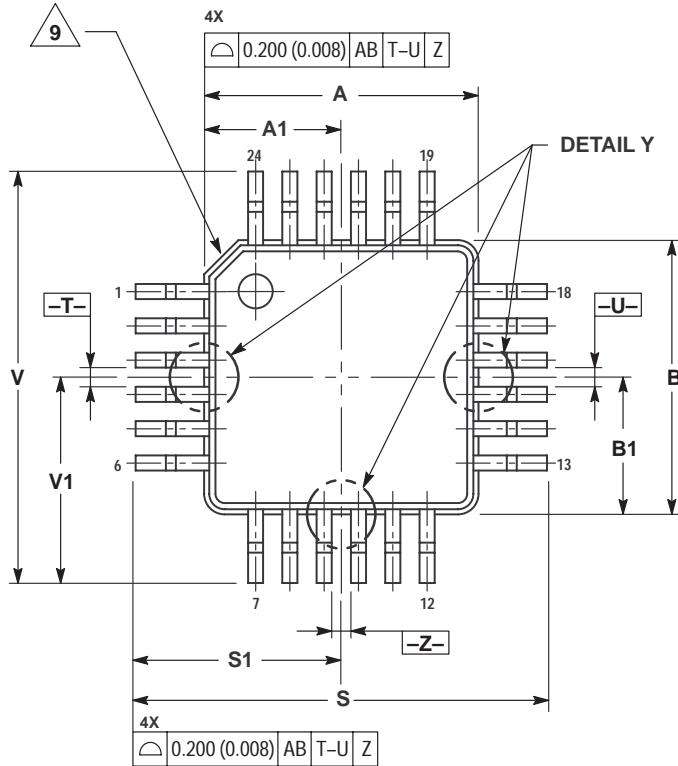
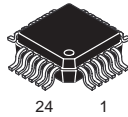
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.000	BSC	0.157	BSC
A1	2.000	BSC	0.079	BSC
B	4.000	BSC	0.157	BSC
B1	2.000	BSC	0.079	BSC
C	1.400	1.600	0.055	0.063
D	0.170	0.270	0.007	0.011
E	1.350	1.450	0.053	0.057
F	0.170	0.230	0.007	0.009
G	0.650	BSC	0.026	BSC
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.500	0.700	0.020	0.028
M	12°	REF	12°	REF
N	0.090	0.160	0.004	0.006
P	0.250	BSC	0.010	BSC
Q	1°	5°	1°	5°
R	0.150	0.250	0.006	0.010
S	6.000	BSC	0.236	BSC
S1	3.000	BSC	0.118	BSC
V	6.000	BSC	0.236	BSC
V1	3.000	BSC	0.118	BSC
W	0.200	REF	0.008	REF
X	1.000	REF	0.039	REF



SECTION AE-AE

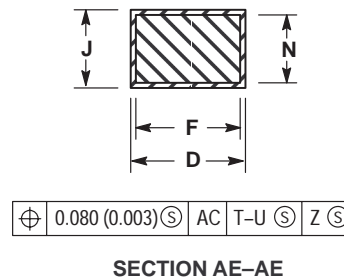
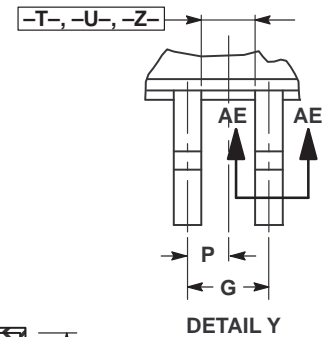
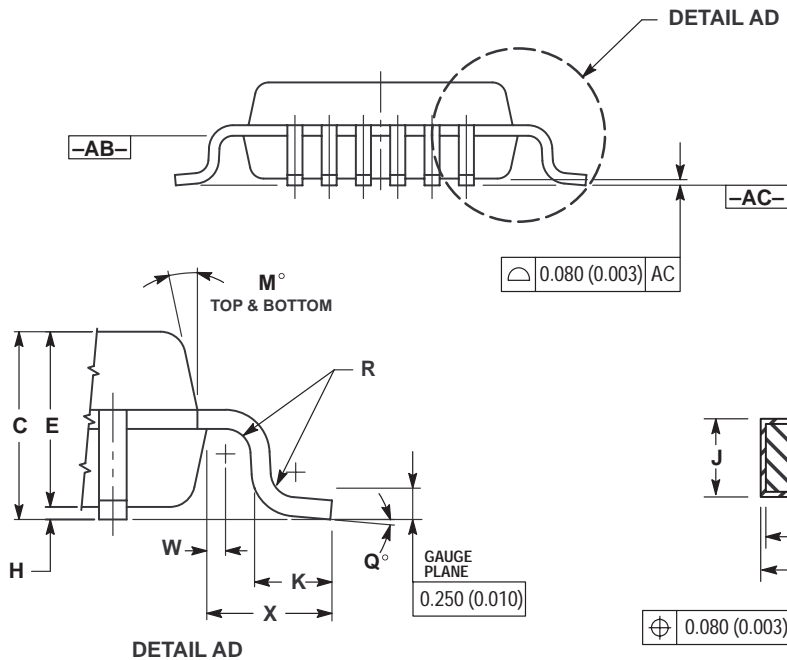


FTA SUFFIX  
CASE 977-01  
Plastic Package  
ISSUE O

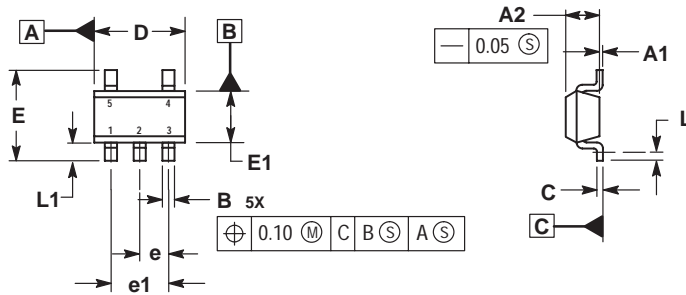


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
  4. DATUMS -T-, -U-, AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-.
  5. DIMENSIONS S AND V TO BE DETERMINED AT DATUM PLANE -AC-.
  6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
  7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.350 (0.014).
  8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076 (0.0003).
  9. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.000 BSC		0.157 BSC	
A1	2.000 BSC		0.079 BSC	
B	4.000 BSC		0.157 BSC	
B1	2.000 BSC		0.079 BSC	
C	1.400	1.600	0.055	0.063
D	0.170	0.270	0.007	0.011
E	1.350	1.450	0.053	0.057
F	0.170	0.230	0.007	0.009
G	0.500 BSC		0.020 BSC	
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.500	0.700	0.020	0.028
M	12° REF		12° REF	
N	0.090	0.160	0.004	0.006
P	0.250 BSC		0.010 BSC	
Q	1°	5°	1°	5°
R	0.150	0.250	0.006	0.010
S	6.000 BSC		0.236 BSC	
S1	3.000 BSC		0.118 BSC	
V	6.000 BSC		0.236 BSC	
V1	3.000 BSC		0.118 BSC	
W	0.200 REF		0.008 REF	
X	1.000 REF		0.039 REF	



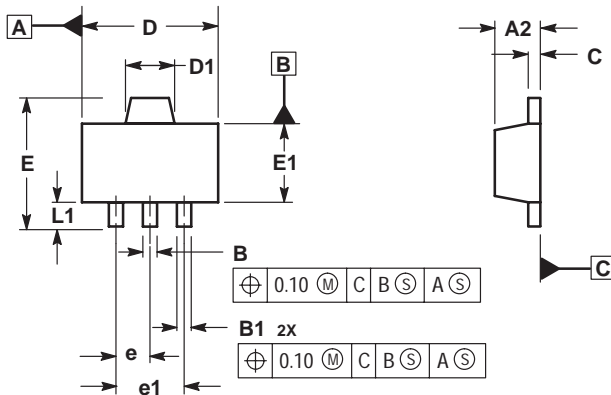
**N SUFFIX**  
**CASE 1212-01**  
 Plastic Package  
 (SOT-23)  
 ISSUE O



- NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
  2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
  3. DATUM C IS A SEATING PLANE.

MILLIMETERS		
DIM	MIN	MAX
A1	0.00	0.10
A2	1.00	1.30
B	0.30	0.50
C	0.10	0.25
D	2.80	3.00
E	2.50	3.10
E1	1.50	1.80
e	0.95 BSC	
e1	1.90 BSC	
L	0.20	----
L1	0.45	0.75

**H SUFFIX**  
**CASE 1213-01**  
 Plastic Package  
 (SOT-89)  
 ISSUE O



- NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
  2. INTERPRET DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
  3. DATUM C IS A SEATING PLANE.

MILLIMETERS		
DIM	MIN	MAX
A2	1.40	1.60
B	0.37	0.57
B1	0.32	0.52
C	0.30	0.50
D	4.40	4.60
D1	1.50	1.70
E	----	4.25
E1	2.40	2.60
e	1.50 BSC	
e1	3.00 BSC	
L1	0.80	----